



Alaska[®] M

88E2010/88E2040L

Single and Quad
10/100/1000/2.5G/5GBASE-T
Ethernet Transceiver

Preliminary Datasheet - Public




For CUSTOMER Use Only

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Alaska M 88E2010/88E2040L

Single and Quad 10/100/1000/2.5G/5GBASE-T Ethernet Transceiver

Preliminary Datasheet - Public

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PRODUCT OVERVIEW

The Marvell® Alaska® M 88E2010/88E2040L is a family of fully IEEE 802.3bz-compliant 1-port (88E2010) or 4-port (88E2040L) physical layer (PHY) devices. The devices support a wide variety of host-side interfaces including 5GBASE-R, 2500BASE-X, and SGMII to support full backward-compatibility with lower speed legacy Ethernet rates including: 1 Gbps, 100 Mbps, and 10 Mbps.

The flexibility of this device family enables extremely low power across all structured wiring cable lengths, enabling dense 5 Gbps applications. The device supports Category 6- (screened or unshielded), Category 6A- (Augmented), Category 7-type cables, and Category 5e-type cables for distances up to 100 meters.

Features

- 1- or 4-port, five-speed PHY. Operates at 10M, 100M, 1G, 2.5G, or 5G data rates on UTP copper lines.
- Compliant with IEEE 802.3bz specifications for 2.5G and 5G modes
- 5GBASE-R, 2500BASE-X, and SGMII system-side interfaces on all devices
- Allows dense multi-port 2.5G/5G applications
- BER better than 1E-15
- 100m reach on CAT 5e for 2.5G and 5G modes
- Clause 45 MDC/MDIO management interface
- Small 10 mm x 12 mm HFCBGA package for 88E2010 single-port applications;
23 mm x 23 mm HFCBGA package for 88E2040L quad-port applications
- Available in commercial and industrial grades

Figure 1: 88E2010 Top-level Block Diagram

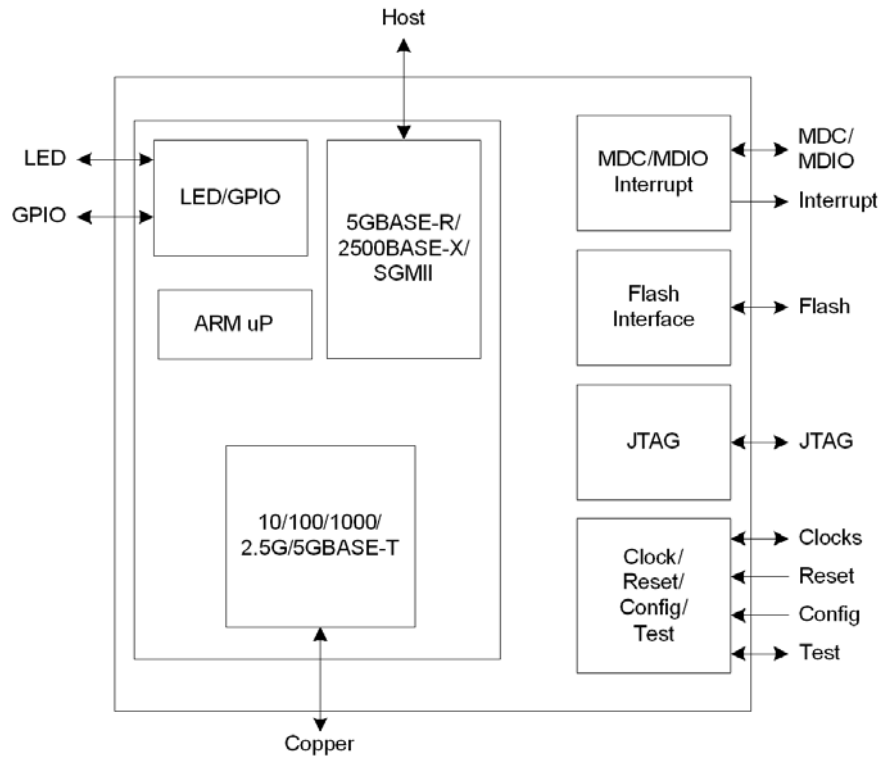


Figure 2: 88E2040L Top-level Block Diagram

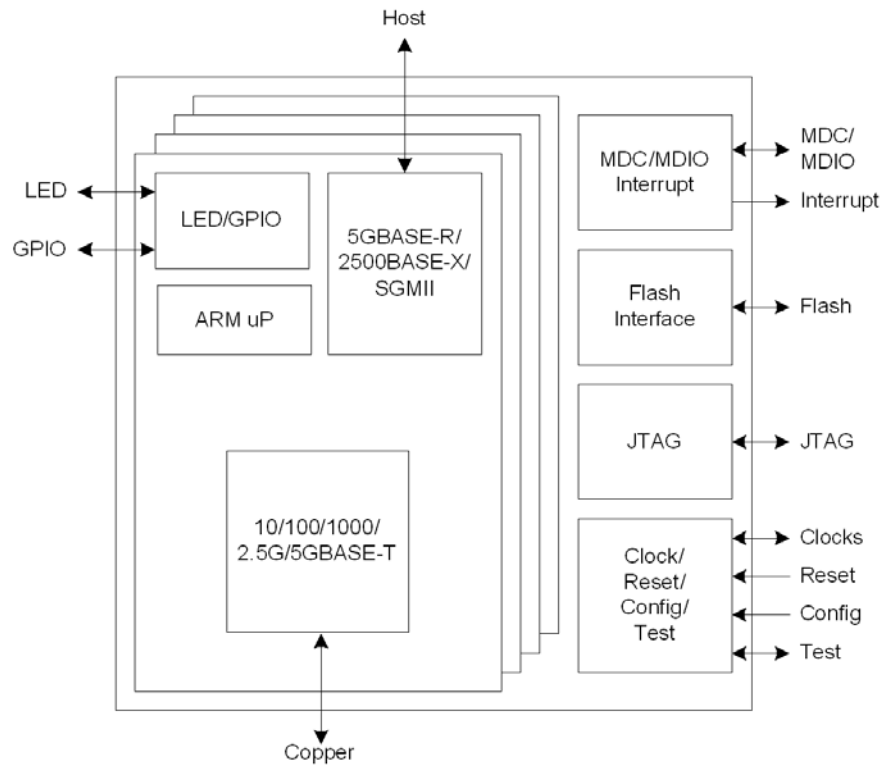




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1

General Chip Description

The 88E2010 and 88E2040L devices are a family of one- and four-port integrated multi-speed copper Ethernet Transceivers.

The host interface to the MAC is via 5GBASE-R, 2500BASE-X, or SGMII interface.

Figure 3: 88E2010 Device Functional Block Diagram

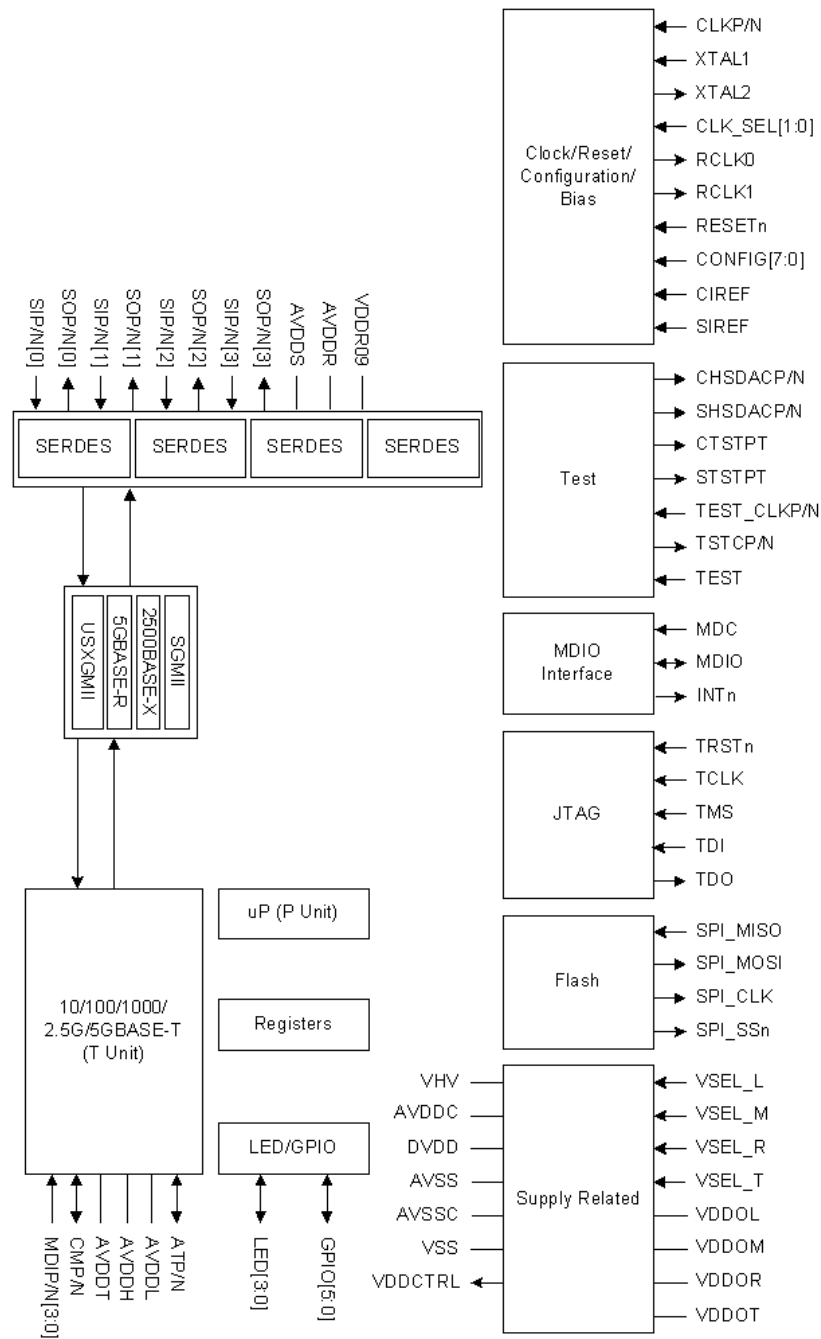
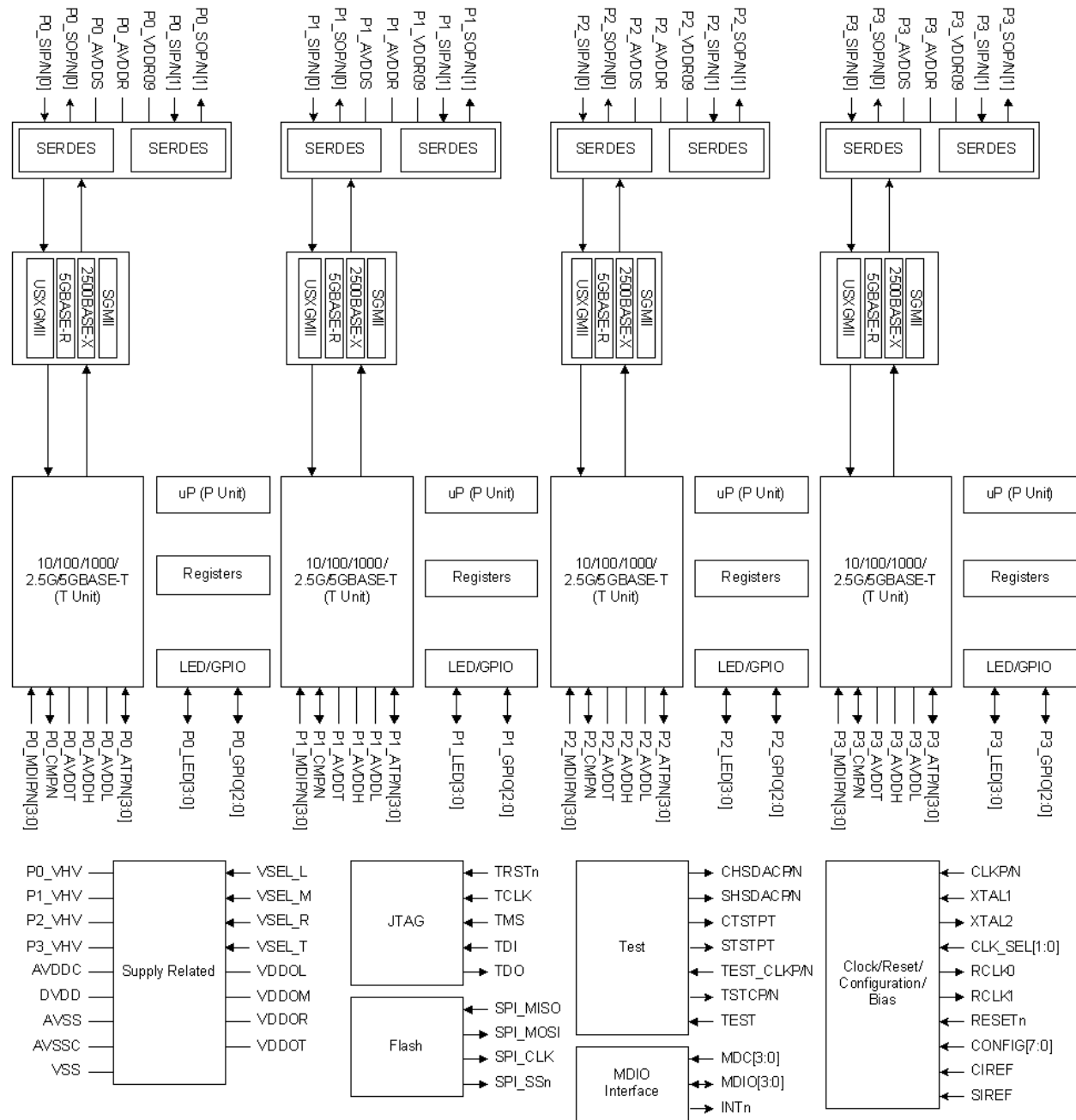


Figure 4: 88E2040L Device Functional Block Diagram



The datasheet is divided as follows:

Section 1 describes the general function of the device.

Section 2 describes the pinout and pin definitions.

Section 3 describes the detailed device functions.

Section 4 describes the copper interface functions (T Unit).

Section 5 describes the MAC interface functions (H Unit).

Section 6 describes the electrical specifications.

Section 7 describes the package mechanical dimensions.

Section 8 describes the order information.

The conventions used in the datasheet are as follows.

All registers are specified per IEEE 802.3 section 45. The format is X.Y, X.Y.Z, or X.Y.Z1:Z2, where X is the device address in decimal from 0 to 31, Y is the register address in hexadecimal from 0000 to FFFF, and Z is the bit in decimal from 0 to 15.

T Unit – 10/100/1000/2.5G/5GBASE-T interface.

H Unit – SGMII/2500BASE-X/5GBASE-R host interface.



Note

Unless otherwise noted, all descriptions apply to the one-, two-, and four-port devices.

2 Signal Description

Table 1: Pin Type Definitions

| Pin Type | Definition |
|----------|-----------------------|
| H | Input with hysteresis |
| I/O | Input and output |
| I | Input only |
| O | Output only |
| PU | Internal pull-up |
| PD | Internal pull-down |
| D | Open drain output |
| Z | Tri-state output |
| mA | DC sink capability |

2.1 Pin Maps

2.1.1 88E2010 Device Pin Map

| | 1 | 2 | 3 | 4 | 5 | 6 | 7 | 8 | 9 | 10 | 11 | 12 | |
|---|-----------|------------|-----------|---------|---------|--------|--------|---------|---------|---------|-----------|----------|---|
| A | VSS | AVSS | SOP[3] | AVSS | SOP[2] | AVSS | SOP[1] | AVSS | SOP[0] | AVSS | SHSDACP | AVSS | A |
| B | MDC | TEST | SON[3] | AVSS | SON[2] | AVSS | SON[1] | AVSS | SON[0] | AVSS | SHSDACN | SIREF | B |
| C | MDIO | INTn | AVSS | SIP[3] | AVSS | SIP[2] | AVSS | SIP[1] | AVSS | SIP[0] | AVSS | STSTPT | C |
| D | CONFIG[1] | CONFIG[2] | CONFIG[6] | SN[3] | AVSS | SIN[2] | AVSS | SN[1] | AVDDS | SIN[0] | SPL_SSn | RESETn | D |
| E | LED[0] | CONFIG[3] | AVDDS | AVDDR | AVSS | VDDR09 | AVSS | AVDDR | AVDDC | VSEL_R | SPL_MOSI | SPL_MISO | E |
| F | LED[1] | LED[3] | VSEL_M | VSS | DVDD | VSS | DVDD | VSS | VHV | GPIO[0] | VSS | SPL_CLK | F |
| G | LED[2] | CONFIG[4] | VDDOM | VSS | DVDD | VSS | DVDD | VSS | VDDOR | GPIO[1] | RCLK1 | GPIO[5] | G |
| H | CONFIG[0] | CONFIG[5] | CONFIG[7] | VSS | DVDD | VSS | DVDD | VSS | VSEL_T | GPIO[2] | GPIO[4] | RCLK0 | H |
| J | CLKN | VDDCTRL | VDDOL | VSS | DVDD | VSS | DVDD | VSS | VDDOT | VSS | TMS | TDO | J |
| K | CLKP | CLK_SEL[0] | VSEL_L | AVDDL | AVSS | AVDDL | AVSS | AVDDL | AVSS | GPIO[3] | TDI | TCK | K |
| L | XTAL2 | CLK_SEL[1] | ATN | AVSS | AVDDH | AVSS | AVDDH | AVSS | AVDDH | AVSS | TEST_CLKP | TRSTn | L |
| M | XTAL1 | AVDDC | ATP | AVDDT | AVSS | AVDDT | AVSS | AVDDT | AVSS | AVDDC | TEST_CLKN | CTSTPT | M |
| N | AVSSC | TSTCN | AVSS | MDIP[3] | MDIN[2] | AVDDT | CMN | MDP[1] | MDIN[0] | AVSS | CHSDACN | CIREF | N |
| P | AVSS | TSTCP | AVSS | MDIN[3] | MDIP[2] | AVSS | CMP | MDIN[1] | MDIP[0] | AVSS | CHSDACP | AVSS | P |
| | 1 | 2 | 3 | 4 | 5 | 6 | 7 | 8 | 9 | 10 | 11 | 12 | |

(Top View)

2.1.2 88E2040L Device Pin Map

Due to the large number of pins, the package is depicted graphically over two pages.

| | 1 | 2 | 3 | 4 | 5 | 6 | 7 | 8 | 9 | 10 | 11 | |
|----|-----------|------------|------------|------------|------------|-----------|------------|------------|------------|------------|---------|----|
| A | AVSS | P0_SOP[0] | AVSS | P0_SOP[1] | AVSS | P1_SOP[1] | AVSS | P1_SOP[0] | AVSS | MDIO[1] | MDC[1] | A |
| B | AVSS | P0_SON[0] | AVSS | P0_SON[1] | AVSS | P1_SON[1] | AVSS | P1_SON[0] | AVSS | VSS | MDC[0] | B |
| C | P0_SIP[0] | AVSS | P0_SIP[1] | AVSS | AVSS | AVSS | P1_SIP[1] | AVSS | P1_SIP[0] | AVSS | MDIO[0] | C |
| D | P0_SIN[0] | P0_AVDDS | P0_SIN[1] | P0_AVDDS | AVSS | P1_AVDDS | P1_SIN[1] | P1_AVDDS | P1_SIN[0] | AVSS | INTn | D |
| E | AVSS | P0_VDDR09 | AVSS | P0_AVDDR | AVSS | P1_AVDDR | AVSS | P1_VDDR09 | AVSS | AVSS | VDDOM | E |
| F | P3_LED[0] | P3_LED[1] | P3_LED[2] | P3_LED[3] | P0_VHV | VSS | DVDD | VSS | DVDD | VSS | P1_VHV | F |
| G | P2_LED[0] | P2_LED[1] | VSS | P2_LED[3] | CONFIG[7] | VSS | DVDD | VSS | DVDD | VSS | DVDD | G |
| H | CONFIG[4] | P2_LED[2] | P1_LED[2] | CONFIG[5] | VDDOL | VSS | DVDD | VSS | DVDD | VSS | DVDD | H |
| J | P1_LED[0] | VSS | P1_LED[1] | P1_LED[3] | CONFIG[6] | VSS | DVDD | VSS | DVDD | VSS | DVDD | J |
| K | P0_LED[0] | P0_LED[1] | P0_LED[2] | P0_LED[3] | VDDOL | VSS | DVDD | VSS | DVDD | VSS | DVDD | K |
| L | CONFIG[0] | CONFIG[1] | VSS | CONFIG[3] | VSEL_L | VSS | DVDD | VSS | DVDD | VSS | DVDD | L |
| M | AVSS | CONFIG[2] | CLK_SEL[0] | CLK_SEL[1] | AVSS | AVSS | AVSS | AVSS | AVSS | AVSS | AVSS | M |
| N | CLKN | P0_AVDDH | P0_AVDDH | P0_AVDDH | P0_AVDDH | AVSS | P1_AVDDH | P1_AVDDH | P1_AVDDH | P1_AVDDH | AVSS | N |
| P | CLKP | AVSS | AVSS | AVSS | AVSS | AVSS | AVSS | AVSS | AVSS | AVSS | AVSS | P |
| R | XTAL2 | P0_AVDDL | P0_AVDDL | P0_AVDDL | P0_AVDDL | AVSS | P1_AVDDL | P1_AVDDL | P1_AVDDL | P1_AVDDL | AVSS | R |
| T | XTAL1 | P0_AVDDT | P0_AVDDT | P0_AVDDT | P0_AVDDT | AVSS | P1_AVDDT | P1_AVDDT | P1_AVDDT | P1_AVDDT | AVSS | T |
| U | AVSSC | AVSS | AVSS | AVSS | AVSS | AVSS | AVSS | AVSS | AVSS | AVSS | AVSS | U |
| V | TSTCN | P0_ATN[0] | P0_ATN[1] | P0_ATN[2] | P0_ATN[3] | AVSS | P1_ATN[3] | P1_ATN[2] | P1_ATN[1] | P1_ATN[0] | AVSS | V |
| W | TSTCP | P0_ATP[0] | P0_ATP[1] | P0_ATP[2] | P0_ATP[3] | AVSS | P1_ATP[3] | P1_ATP[2] | P1_ATP[1] | P1_ATP[0] | AVSS | W |
| Y | AVDDC | AVSS | P0_CMN | P0_CMP | AVSS | AVSS | AVSS | P1_CMP | P1_CMN | AVSS | AVSS | Y |
| AA | AVSS | P0_MDIN[0] | P0_MDIN[1] | P0_MDIN[2] | P0_MDIN[3] | AVSS | P1_MDIN[3] | P1_MDIN[2] | P1_MDIN[1] | P1_MDIN[0] | AVSS | AA |
| AB | AVSS | P0_MDI[0] | P0_MDI[1] | P0_MDI[2] | P0_MDI[3] | AVSS | P1_MDI[3] | P1_MDI[2] | P1_MDI[1] | P1_MDI[0] | AVSS | AB |
| | 1 | 2 | 3 | 4 | 5 | 6 | 7 | 8 | 9 | 10 | 11 | |

(Top View)

| | 12 | 13 | 14 | 15 | 16 | 17 | 18 | 19 | 20 | 21 | 22 | |
|----|------------|------------|------------|------------|-----------|------------|------------|------------|------------|------------|------------|----|
| A | MDC[2] | MDIO[2] | AVSS | P2_SOP[0] | AVSS | P2_SOP[1] | AVSS | P3_SOP[1] | AVSS | P3_SOP[0] | AVSS | A |
| B | MDC[3] | VSS | AVSS | P2_SON[0] | AVSS | P2_SON[1] | AVSS | P3_SON[1] | AVSS | P3_SON[0] | AVSS | B |
| C | MDIO[3] | AVSS | P2_SIP[0] | AVSS | P2_SIP[1] | AVSS | AVSS | AVSS | P3_SIP[1] | AVSS | P3_SIP[0] | C |
| D | TEST | AVSS | P2_SIN[0] | P2_AVDDS | P2_SIN[1] | P2_AVDDS | AVSS | P3_AVDDS | P3_SIN[1] | P3_AVDDS | P3_SIN[0] | D |
| E | VSEL_M | P2_VDDR09 | AVSS | P2_AVDDR | AVSS | P3_AVDDR | AVSS | P3_VDDR09 | AVSS | SIREF | AVSS | E |
| F | P2_VHV | DVDD | VSS | DVDD | VSS | DVDD | P3_VHV | SHSDACP | SHSDACN | AVDDC | STSTPT | F |
| G | VSS | DVDD | VSS | DVDD | VSS | DVDD | VSS | VDDOR | SPL_MOSI | SPL_Sn | RESETn | G |
| H | VSS | DVDD | VSS | DVDD | VSS | DVDD | VSS | VSEL_R | P1_GPIO[2] | VSS | P0_GPIO[2] | H |
| J | VSS | DVDD | VSS | DVDD | VSS | DVDD | VSS | VDDOR | SPL_MISO | P2_GPIO[2] | RCLK1 | J |
| K | VSS | DVDD | VSS | DVDD | VSS | DVDD | VSS | VDDOT | SPL_CLK | P3_GPIO[2] | RCLK0 | K |
| L | VSS | DVDD | VSS | DVDD | VSS | DVDD | VSS | VSEL_T | P0_GPIO[1] | VSS | P0_GPIO[0] | L |
| M | AVSS | AVSS | AVSS | AVSS | AVSS | AVSS | AVSS | AVSS | P1_GPIO[1] | P2_GPIO[1] | P1_GPIO[0] | M |
| N | P2_AVDDH | P2_AVDDH | P2_AVDDH | P2_AVDDH | AVSS | P3_AVDDH | P3_AVDDH | P3_AVDDH | P3_AVDDH | P3_GPIO[1] | P2_GPIO[0] | N |
| P | AVSS | AVSS | AVSS | AVSS | AVSS | AVSS | AVSS | AVSS | AVSS | VSS | P3_GPIO[0] | P |
| R | P2_AVDDL | P2_AVDDL | P2_AVDDL | P2_AVDDL | AVSS | P3_AVDDL | P3_AVDDL | P3_AVDDL | P3_AVDDL | TCK | TRSTn | R |
| T | P2_AVDDT | P2_AVDDT | P2_AVDDT | P2_AVDDT | AVSS | P3_AVDDT | P3_AVDDT | P3_AVDDT | P3_AVDDT | TDI | TEST_CLKN | T |
| U | AVSS | AVSS | AVSS | AVSS | AVSS | AVSS | AVSS | AVSS | AVSS | TDO | TEST_CLKP | U |
| V | P2_ATN[0] | P2_ATN[1] | P2_ATN[2] | P2_ATN[3] | AVSS | P3_ATN[3] | P3_ATN[2] | P3_ATN[1] | P3_ATN[0] | TMS | AVSS | V |
| W | P2_ATP[0] | P2_ATP[1] | P2_ATP[2] | P2_ATP[3] | AVSS | P3_ATP[3] | P3_ATP[2] | P3_ATP[1] | P3_ATP[0] | AVDDC | CTSTPT | W |
| Y | AVSS | P2_CMN | P2_CMP | AVSS | AVSS | AVSS | P3_CMP | P3_CMN | AVSS | AVDDC | CIREF | Y |
| AA | P2_MDIN[0] | P2_MDIN[1] | P2_MDIN[2] | P2_MDIN[3] | AVSS | P3_MDIN[3] | P3_MDIN[2] | P3_MDIN[1] | P3_MDIN[0] | CHSDACN | AVSS | AA |
| AB | P2_MDIP[0] | P2_MDIP[1] | P2_MDIP[2] | P2_MDIP[3] | AVSS | P3_MDIP[3] | P3_MDIP[2] | P3_MDIP[1] | P3_MDIP[0] | CHSDACP | AVSS | AB |
| | 12 | 13 | 14 | 15 | 16 | 17 | 18 | 19 | 20 | 21 | 22 | |

(Top View)

2.2 Pin Description



Note

88E2010 device pin names are not prefixed with P0_.

Table 2: Media Dependent Interface

| 88E2010 Pin # | 88E2040L Pin # | Pin Name | Pin Type | Description |
|---------------|----------------|--------------------------|----------|---|
| P9 N9 | AB2 AA2 | P0_MDIP[0] P0_MDIN[0] | I/O | Media Dependent Interface[0], Port 0. In 2.5G/5GBASE-T and 1000BASE-T modes in MDI configuration, MDIP/N[0] correspond to BI_DA±. In MDIX configuration, MDIP/N[0] correspond to BI_DB±. In 100BASE-TX and 10BASE-T modes in MDI configuration, MDIP/N[0] are used for the transmit pair. In MDIX configuration, MDIP/N[0] are used for the receive pair. MDIP/N[0] should be tied to ground if not used. The device contains an internal 100Ω resistor between the MDIP/N[0] pins. |
| N8 P8 | AB3 AA3 | P0_MDIP[1] P0_MDIN[1] | I/O | Media Dependent Interface[1], Port 0. In 2.5G/5GBASE-T and 1000BASE-T modes in MDIX configuration, MDIP/N[1] correspond to BI_DA±. In MDI configuration, MDIP/N[1] correspond to BI_DB±. In 100BASE-TX and 10BASE-T modes in MDIX configuration, MDIP/N[1] are used for the transmit pair. In MDI configuration, MDIP/N[1] are used for the receive pair. MDIP/N[1] should be tied to ground if not used. The device contains an internal 100Ω resistor between the MDIP/N[1] pins. |
| P5 N5 | AB4 AA4 | P0_MDIP[2] P0_MDIN[2] | I/O | Media Dependent Interface[2], Port 0. In 2.5G/5GBASE-T and 1000BASE-T modes in MDI configuration, MDIP/N[2] correspond to BI_DC±. In MDIX configuration, MDIP/N[2] correspond to BI_DD±. In 100BASE-TX and 10BASE-T modes, these pins are floating. MDIP/N[2] should be tied to ground if not used. The device contains an internal 100Ω resistor between the MDIP/N[2] pins. |

Table 2: Media Dependent Interface (Continued)

| 88E2010 Pin # | 88E2040L Pin # | Pin Name | Pin Type | Description |
|---------------|----------------|--------------------------|----------|---|
| N4 P4 | AB5 AA5 | P0_MDIP[3] P0_MDIN[3] | I/O | Media Dependent Interface[3], Port 0. In 2.5G/5GBASE-T and 1000BASE-T modes in MDIX configuration, MDIP/N[3] correspond to BI_DC±. In MDI configuration, MDIP/N[3] correspond to BI_DD±. In 100BASE-TX and 10BASE-T modes these pins are floating. MDIP/N[3] should be tied to ground if not used. The device contains an internal 100Ω resistor between the MDIP/N[3] pins. |
| -- -- | AB10 AA10 | P1_MDIP[0] P1_MDIN[0] | I/O | Media Dependent Interface[0], Port 1. |
| -- -- | AB9 AA9 | P1_MDIP[1] P1_MDIN[1] | I/O | Media Dependent Interface[1], Port 1. |
| -- -- | AB8 AA8 | P1_MDIP[2] P1_MDIN[2] | I/O | Media Dependent Interface[2], Port 1. |
| -- -- | AB7 AA7 | P1_MDIP[3] P1_MDIN[3] | I/O | Media Dependent Interface[3], Port 1. |
| -- -- | AB12 AA12 | P2_MDIP[0] P2_MDIN[0] | I/O | Media Dependent Interface[0], Port 2. |
| -- -- | AB13 AA13 | P2_MDIP[1] P2_MDIN[1] | I/O | Media Dependent Interface[1], Port 2. |
| -- -- | AB14 AA14 | P2_MDIP[2] P2_MDIN[2] | I/O | Media Dependent Interface[2], Port 2. |
| -- -- | AB15 AA15 | P2_MDIP[3] P2_MDIN[3] | I/O | Media Dependent Interface[3], Port 2. |
| -- -- | AB20 AA20 | P3_MDIP[0] P3_MDIN[0] | I/O | Media Dependent Interface[0], Port 3. |
| -- -- | AB19 AA19 | P3_MDIP[1] P3_MDIN[1] | I/O | Media Dependent Interface[1], Port 3. |
| -- -- | AB18 AA18 | P3_MDIP[2] P3_MDIN[2] | I/O | Media Dependent Interface[2], Port 3. |
| -- -- | AB17 AA17 | P3_MDIP[3] P3_MDIN[3] | I/O | Media Dependent Interface[3], Port 3. |
| P7 N7 | Y4 Y3 | P0_CMP P0_CMN | I | Media Dependent Interface, optional common mode sense, Port 0 |
| -- -- | Y8 Y9 | P1_CMP P1_CMN | I | Media Dependent Interface, optional common mode sense, Port 1 |
| -- -- | Y14 Y13 | P2_CMP P2_CMN | I | Media Dependent Interface, optional common mode sense, Port 2 |
| -- -- | Y18 Y19 | P3_CMP P3_CMN | I | Media Dependent Interface, optional common mode sense, Port 3 |



Table 3: SERDES Interface

| 88E2010 Pin # | 88E2040L Pin # | Pin Name | Pin Type | Description |
|----------------------|----------------------|--------------------------------------|----------|---|
| C10 D10 | C1 D1 | P0_SIP[0] P0_SIN[0] | I | Host Interface Input Lane 0, Port 0 5GBASE-R, 2500BASE-X, SGMII |
| C8 D8 | C3 D3 | P0_SIP[1] P0_SIN[1] | I | Host Interface Input Lane 1 Port 0 |
| C6 D6 C4 D4 | -- -- -- -- | SIP[2] SIN[2] SIP[3] SIN[3] | I | Host Interface Input Lane 2 and 3. |
| -- -- | C9 D9 | P1_SIP[0] P1_SIN[0] | I | Host Interface Input Lane 0, Port 1 5GBASE-R, 2500BASE-X, SGMII |
| -- -- | C7 D7 | P1_SIP[1] P1_SIN[1] | I | Host Interface Input Lane 1, Port 1 |
| -- -- | C14 D14 | P2_SIP[0] P2_SIN[0] | I | Host Interface Input Lane 0, Port 2 5GBASE-R, 2500BASE-X, SGMII, |
| -- -- | C16 D16 | P2_SIP[1] P2_SIN[1] | I | Host Interface Input Lane 1, Port 2 |
| -- -- | C22 D22 | P3_SIP[0] P3_SIN[0] | I | Host Interface Input Lane 0, Port 3 5GBASE-R, 2500BASE-X, SGMII |
| -- -- | C20 D20 | P3_SIP[1] P3_SIN[1] | I | Host Interface Input Lane 1, Port 3 |
| A9 B9 | A2 B2 | P0_SOP[0] P0_SON[0] | O | Host Interface Output Lane 0, Port 0 5GBASE-R, 2500BASE-X, SGMII |
| A7 B7 | A4 B4 | P0_SOP[1] P0_SON[1] | O | Host Interface Output Lane 1 Port 0 |
| A5 B5 A3 B3 | -- -- -- -- | SOP[2] SON[2] SOP[3] SON[3] | O | Host Interface Output Lane 2 and 3. |
| -- -- | A8 B8 | P1_SOP[0] P1_SON[0] | O | Host Interface Output Lane 0, Port 1 5GBASE-R, 2500BASE-X, SGMII |
| -- -- | A6 B6 | P1_SOP[1] P1_SON[1] | O | Host Interface Output Lane 1, Port 1 |
| -- -- | A15 B15 | P2_SOP[0] P2_SON[0] | O | Host Interface Output Lane 0, Port 2 5GBASE-R, 2500BASE-X, SGMII, lane 0 |
| -- -- | A17 B17 | P2_SOP[1] P2_SON[1] | O | Host Interface Output Lane 1, Port 2 These signals can be configured as lane 1 host interface. |
| -- -- | A21 B21 | P3_SOP[0] P3_SON[0] | O | Host Interface Output Lane 0, Port 3 5GBASE-R, 2500BASE-X, SGMII, lane 0 |

Table 3: SERDES Interface (Continued)

| 88E2010 Pin # | 88E2040L Pin # | Pin Name | Pin Type | Description |
|------------------|-------------------|------------------------|-------------|--|
| -- -- | A19 B19 | P3_SOP[1] P3_SON[1] | O | Host Interface Output Lane 1, Port 3 These signals can be configured as lane 1 host interface. |

Table 4: Clock/Reset/Reference

| 88E2010 Pin # | 88E2040L Pin # | Pin Name | Pin Type | Description |
|---------------|----------------|--------------|----------|--|
| N12 | Y22 | CIREF | I | Analog Reference, Copper. This pin should be connected via a 4.99 kΩ 1% resistor to VSS. |
| B12 | E21 | SIREF | I | Analog Reference, SERDES. This pin should be connected via a 4.99 kΩ 1% resistor to VSS |
| K1 J1 | P1 N1 | CLKP CLKN | I | 156.25 MHz or 50 MHz Differential Reference Clock Input. ±50 ppm tolerance. |
| M1 | T1 | XTAL1 | I | 50 MHz crystal input NOTE: 50 MHz crystal operation is only supported for commercial-grade devices. |
| L1 | R1 | XTAL2 | O | 50 MHz crystal output NOTE: 50 MHz crystal operation is only supported for commercial-grade devices. |
| H12 | K22 | RCLK0 | O | Recovered Clock Output 0 to 25 MHz |
| G11 | J22 | RCLK1 | O | Recovered Clock Output 1 to 25 MHz |
| D12 | G22 | RESETn | I | Reset 0 = Reset 1 = Normal |

Table 5: Management Interface

| 88E2010 Pin # | 88E2040L Pin # | Pin Name | Pin Type | Description |
|----------------------|--------------------------|--|----------|--|
| B1 -- -- -- | B11 A11 A12 B12 | MDC[0] MDC[1] MDC[2] MDC[3] | I | <p>Management Clock pin.</p> <p>MDC is the management data clock reference for the serial management interface. A continuous clock stream is not expected. The maximum continuous frequency supported is 12.5 MHz. A 30 MHz non-continuous mode is also supported.</p> <p>88E2040L: If the device is configured to shared MDC/MDIO mode, then MDC[2]/MDIO[2] is used to access all four ports. If the device is configured to dual MDC/MDIO mode, then MDC[1]/MDIO[1] is used to access Ports 0 and 1 while MDC[2]/MDIO[2] is used to access Ports 2 and 3. If MDC[x] is unused, then it should be tied low.</p> |
| C1 -- -- -- | C11 A10 A13 C12 | MDIO[0] MDIO[1] MDIO[2] MDIO[3] | I/O | <p>Management Data pin.</p> <p>MDIO is the management data. MDIO transfers management data in and out of the device synchronously to MDC.</p> <p>This pin requires a pull-up resistor in a range from 1.5 kΩ to 10 kΩ.</p> <p>If MDIO[x] is unused, then it should be left floating.</p> |
| C2 | D11 | INTn | OD | Interrupt pin. (Polarity programmable) |

Table 6: SPI Interface

| 88E2010 Pin # | 88E2040L Pin # | Pin Name | Pin Type | Description |
|------------------|-------------------|---------------------|-------------|-------------------|
| D11 | G21 | SPI_SS _n | O | SPI device enable |
| F12 | K20 | SPI_CLK | O | SPI clock |
| E11 | G20 | SPI_MOSI | O | SPI serial out |
| E12 | J20 | SPI_MISO | I | SPI serial in |

Table 7: LED

| 88E2010 Pin # | 88E2040L Pin # | Pin Name | Pin Type | Description |
|----------------------|----------------------|--|-------------|---------------------|
| E1 F1 G1 F2 | K1 K2 K3 K4 | P0_LED[0] P0_LED[1] P0_LED[2] P0_LED[3] | I/O | LED Outputs, Port 0 |
| -- -- -- -- | J1 J3 H3 J4 | P1_LED[0] P1_LED[1] P1_LED[2] P1_LED[3] | I/O | LED Outputs, Port 1 |
| -- -- -- -- | G1 G2 H2 G4 | P2_LED[0] P2_LED[1] P2_LED[2] P2_LED[3] | I/O | LED Outputs, Port 2 |
| -- -- -- -- | F1 F2 F3 F4 | P3_LED[0] P3_LED[1] P3_LED[2] P3_LED[3] | I/O | LED Outputs, Port 3 |
| F10 G10 H10 | L22 L20 H22 | Reserved Reserved Reserved | -- | Reserved |
| K10 H11 G12 | -- -- -- | Reserved Reserved Reserved | -- | Reserved |
| -- -- -- | M22 M20 H20 | Reserved Reserved Reserved | -- | Reserved |
| -- -- -- | N22 M21 J21 | Reserved Reserved Reserved | -- | Reserved |
| -- -- -- | P22 N21 K21 | Reserved Reserved Reserved | -- | Reserved |

Table 8: Configuration

| 88E2010 Pin # | 88E2040L Pin # | Pin Name | Pin Type | Description |
|--|--|--|----------|--|
| K2 L2 | M3 M4 | CLK_SEL[0] CLK_SEL[1] | I, PD | Reference clock selection 00 = 50 MHz XTAL1/2 01 = 50 MHz CLKP/N 10 = 156.25 MHz CLKP/N 11 = Reserved NOTE: 50 MHz crystal operation is only supported for commercial-grade devices. |
| H1 D1 D2 E2 G2 H2 D3 H3 | L1 L2 M2 L4 H1 H4 J5 G5 | CONFIG[0] CONFIG[1] CONFIG[2] CONFIG[3] CONFIG[4] CONFIG[5] CONFIG[6] CONFIG[7] | I | Hardware Configuration |
| K3 | L5 | VSEL_L | I | VDDOL Voltage Level Select VSS = 2.5V/3.3V, VDDOL = 1.5V/1.8V |
| F3 | E12 | VSEL_M | I | VDDOM Voltage Level Select VSS = 2.5V/3.3V, VDDOM = 1.2V/1.5V/1.8V |
| E10 | H19 | VSEL_R | I | VDDOR Voltage Level Select VSS = 2.5V/3.3V, VDDOR = 1.5V/1.8V |
| H9 | L19 | VSEL_T | I | VDDOT Voltage Level Select VSS = 2.5V/3.3V, VDDOT = 1.5V/1.8V |

Table 9: JTAG Interface

| 88E2010 Pin # | 88E2040L Pin # | Pin Name | Pin Type | Description |
|---------------|----------------|----------|----------|--|
| K11 | T21 | TDI | I, PU | JTAG Data Input |
| J12 | U21 | TDO | O | JTAG Data Output |
| J11 | V21 | TMS | I, PU | JTAG Mode Select |
| K12 | R21 | TCK | I, PU | JTAG Clock |
| L12 | R22 | TRSTn | I, PU | JTAG Reset. TRSTn pin requires a 4.7 kΩ pull-down externally for normal operation. |

Table 10: Test Pins

| 88E2010 Pin # | 88E2040L Pin # | Pin Name | Pin Type | Description |
|--|--|--|-------------|--------------------|
| M3 L3 -- -- -- -- -- -- | W2 V2 W3 V3 W4 V4 W5 V5 | P0_ATP[0] P0_ATN[0] P0_ATP[1] P0_ATN[1] P0_ATP[2] P0_ATN[2] P0_ATP[3] P0_ATN[3] | O | Analog Test Port 0 |
| -- -- -- -- -- -- -- -- | W10 V10 W9 V9 W8 V8 W7 V7 | P1_ATP[0] P1_ATN[0] P1_ATP[1] P1_ATN[1] P1_ATP[2] P1_ATN[2] P1_ATP[3] P1_ATN[3] | O | Analog Test Port 1 |
| -- -- -- -- -- -- -- -- | W12 V12 W13 V13 W14 V14 W15 V15 | P2_ATP[0] P2_ATN[0] P2_ATP[1] P2_ATN[1] P2_ATP[2] P2_ATN[2] P2_ATP[3] P2_ATN[3] | O | Analog Test Port 2 |
| -- -- -- -- -- -- -- -- | W20 V20 W19 V19 W18 V18 W17 V17 | P3_ATP[0] P3_ATN[0] P3_ATP[1] P3_ATN[1] P3_ATP[2] P3_ATN[2] P3_ATP[3] P3_ATN[3] | O | Analog Test Port 3 |
| P11 N11 | AB21 AA21 | CHSDACP CHSDACN | O | Copper AC Test |
| A11 B11 | F19 F20 | SHSDACP SHSDACN | O | SERDES AC Test |
| M12 | W22 | CTSTPT | O | Copper DC Test |
| C12 | F22 | STSTPT | O | SERDES DC Test |
| L11 M11 | U22 T22 | TEST_CLKP TEST_CLKN | I | Test clock input |

Table 10: Test Pins (Continued)

| 88E2010 Pin # | 88E2040L Pin # | Pin Name | Pin Type | Description |
|------------------|-------------------|----------------|-------------|--|
| P2 N2 | W1 V1 | TSTCP TSTCN | O | Test clock output When using the 50 MHz XTAL option, the (CLK_SEL[1:0] = 00), TSTCP/N output pins must be AC coupled with a 0.1 μ F capacitor and connected to CLK_P/N input pins on the board (88E2040L devices only). |
| B2 | D12 | TEST | I, PD | Test Enable. This pin should be left floating if not used. |

Table 11: Power and Ground

| 88E2010 Pin # | 88E2040L Pin # | Pin Name | Pin Type | Description |
|----------------------|--------------------------|--------------------------------------|----------|--|
| F9 -- -- -- | F5 F11 F12 F18 | P0_VHV P1_VHV P2_VHV P3_VHV | Power | High Voltage Fuse Programming These pins must be left floating. |
| L5 L7 L9 -- | N2 N3 N4 N5 | P0_AVDDH | Power | 1.8V or 2.0V analog power |
| -- -- -- -- | N7 N8 N9 N10 | P1_AVDDH | Power | |
| -- -- -- -- | N12 N13 N14 N15 | P2_AVDDH | Power | |
| -- -- -- -- | N17 N18 N19 N20 | P3_AVDDH | Power | |
| M4 M6 M8 N6 | T2 T3 T4 T5 | P0_AVDDT | Power | |
| -- -- -- -- | T7 T8 T9 T10 | P1_AVDDT | Power | |
| -- -- -- -- | T12 T13 T14 T15 | P2_AVDDT | Power | |
| -- -- -- -- | T17 T18 T19 T20 | P3_AVDDT | Power | |

Table 12: Power and Ground (Continued)

| 88E2010 Pin # | 88E2040L Pin # | Pin Name | Pin Type | Description |
|----------------------------|--------------------------|--|----------|---|
| E9 M2 M10 -- | F21 W21 Y1 Y21 | AVDDC | Power | 1.5V analog power |
| K4 K6 K8 -- -- | R2 R3 R4 R5 | P0_AVDDL | Power | 1.5V analog power |
| -- -- -- -- -- | R7 R8 R9 R10 | P1_AVDDL | Power | |
| -- -- -- -- | R12 R13 R14 R15 | P2_AVDDL | Power | |
| -- -- -- -- | R17 R18 R19 R20 | P3_AVDDL | Power | |
| D9 E3 | D2 D4 | P0_AVDDS | Power | |
| -- -- | D6 D8 | P1_AVDDS | Power | |
| -- -- | D15 D17 | P2_AVDDS | Power | |
| -- -- | D19 D21 | P3_AVDDS | Power | |
| E4 E8 -- -- | E4 E6 E15 E17 | P0_AVDDR P1_AVDDR P2_AVDDR P3_AVDDR | Power | 1.5V analog power |
| E6 -- -- -- | E2 E8 E13 E19 | P0_VDDR09 P1_VDDR09 P2_VDDR09 P3_VDDR09 | Power | 0.9V internally regulated power. This pin must be tied to a capacitor. Do not connect this pin to external power. |

Table 12: Power and Ground (Continued)

| 88E2010 Pin # | 88E2040L Pin # | Pin Name | Pin Type | Description |
|--|---|----------|----------|--|
| F5 F7 G5 G7 H5 H7 J5 J7 | F7 F9 F13 F15 F17 G7 G9 G11 G13 G15 G17 H7 H9 H11 H13 H15 H17 J7 J9 J11 J13 J15 J17 K7 K9 K11 K13 K15 K17 L7 L9 L11 L13 L15 L17 | DVDD | Power | Digital power 0.8V for C-grade 0.88V for I-grade |
| J3 | H5 K5 | VDDOL | Power | I/O power - LED, CONFIG, CLK_SEL |
| G3 | E11 | VDDOM | Power | I/O power - MDC, MDIO, INTn, TEST |
| G9 | G19 J19 | VDDOR | Power | I/O power - RESETn, SPI, RCLK0, RCLK1 |
| J9 | K19 | VDDOT | Power | I/O power - JTAG |



Table 12: Power and Ground (Continued)

| 88E2010 Pin # | 88E2040L Pin # | Pin Name | Pin Type | Description |
|------------------|-------------------|----------|----------|---------------|
| A2 | A1 | AVSS | Power | Analog Ground |
| A4 | A3 | | | |
| A6 | A5 | | | |
| A8 | A7 | | | |
| A10 | A9 | | | |
| A12 | A14 | | | |
| B4 | A16 | | | |
| B6 | A18 | | | |
| B8 | A20 | | | |
| B10 | A22 | | | |
| C3 | B1 | | | |
| C5 | B3 | | | |
| C7 | B5 | | | |
| C9 | B7 | | | |
| C11 | B9 | | | |
| D5 | B14 | | | |
| D7 | B16 | | | |
| E5 | B18 | | | |
| E7 | B20 | | | |
| K5 | B22 | | | |
| K7 | C2 | | | |
| K9 | C4 | | | |
| L4 | C5 | | | |
| L6 | C6 | | | |
| L8 | C8 | | | |
| L10 | C10 | | | |
| M5 | C13 | | | |
| M7 | C15 | | | |
| M9 | C17 | | | |
| N3 | C18 | | | |
| N10 | C19 | | | |
| P1 | C21 | | | |
| P3 | D5 | | | |
| P6 | D10 | | | |
| P10 | D13 | | | |
| P12 | D18 | | | |
| | E1 | | | |
| | E3 | | | |
| | E5 | | | |
| | E7 | | | |
| | E9 | | | |
| | E10 | | | |
| | E14 | | | |
| | E16 | | | |
| | E18 | | | |
| | E20 | | | |
| | E22 | | | |
| | M1 | | | |
| | M5 | | | |
| | M6 | | | |
| | M7 | | | |
| | M8 | | | |

Table 12: Power and Ground (Continued)

| 88E2010 Pin # | 88E2040L Pin # | Pin Name | Pin Type | Description |
|------------------|--|--------------|----------|---------------|
| -- | M9 M10 M11 M12 M13 M14 M15 M16 M17 M18 M19 N6 N11 N16 P2 P3 P4 P5 P6 P7 P8 P9 P10 P11 P12 P13 P14 P15 P16 P17 P18 P19 P20 R6 R11 R16 T6 T11 T16 U2 U3 U4 U5 U6 U7 U8 U9 U10 U11 U12 U13 U14 | AVSS (cont.) | Power | Analog Ground |



Table 12: Power and Ground (Continued)

| 88E2010 Pin # | 88E2040L Pin # | Pin Name | Pin Type | Description |
|------------------|--|--------------|----------|---------------|
| -- | U15 U16 U17 U18 U19 U20 V6 V11 V16 V22 W6 W11 W16 Y2 Y5 Y6 Y7 Y10 Y11 Y12 Y15 Y16 Y17 Y20 AA1 AA6 AA11 AA16 AA22 AB1 AB6 AB11 AB16 AB22 | AVSS (cont.) | Power | Analog Ground |

Table 12: Power and Ground (Continued)

| 88E2010 Pin # | 88E2040L Pin # | Pin Name | Pin Type | Description |
|--|---|----------|----------|---|
| N1 | U1 | AVSSC | Power | Analog Ground This must be isolated from AVSS. |
| A1 F4 F6 F8 F11 G4 G6 G8 H4 H6 H8 J4 J6 J8 J10 | B10 B13 F6 F8 F10 F14 F16 G3 G6 G8 G10 G12 G14 G16 G18 H6 H8 H10 H12 H14 H16 H18 H21 J2 J6 J8 J10 J12 J14 J16 J18 K6 K8 K10 K12 K14 K16 K18 L3 L6 L8 L10 L12 L14 L16 L18 L21 P21 | VSS | Power | Ground |

2.3 Pin Assignment Lists

2.3.1 88E2010 Device Pin Assignment List

Table 13: 88E2010 Pin List — Alphabetical by Signal Name

| Pin Number | Pin Name | Pin Number | Pin Name |
|------------|----------|------------|----------|
| L3 | ATN | B4 | AVSS |
| M3 | ATP | B6 | AVSS |
| K4 | AVDDL | B8 | AVSS |
| K6 | AVDDL | B10 | AVSS |
| K8 | AVDDL | C3 | AVSS |
| L5 | AVDDH | C5 | AVSS |
| L7 | AVDDH | C7 | AVSS |
| L9 | AVDDH | C9 | AVSS |
| M4 | AVDDT | C11 | AVSS |
| M6 | AVDDT | D5 | AVSS |
| M8 | AVDDT | D7 | AVSS |
| N6 | AVDDT | E5 | AVSS |
| E9 | AVDDC | E7 | AVSS |
| M2 | AVDDC | K5 | AVSS |
| M10 | AVDDC | K7 | AVSS |
| E4 | AVDDR | K9 | AVSS |
| E8 | AVDDR | L4 | AVSS |
| D9 | AVDDS | L6 | AVSS |
| E3 | AVDDS | L8 | AVSS |
| A2 | AVSS | L10 | AVSS |
| A4 | AVSS | M5 | AVSS |
| A6 | AVSS | M7 | AVSS |
| A8 | AVSS | M9 | AVSS |
| A10 | AVSS | N3 | AVSS |
| A12 | AVSS | N10 | AVSS |

| Pin Number | Pin Name |
|------------|------------|
| P1 | AVSS |
| P3 | AVSS |
| P6 | AVSS |
| P10 | AVSS |
| P12 | AVSS |
| N1 | AVSSC |
| N11 | CHSDACN |
| P11 | CHSDACP |
| N12 | CIREF |
| K2 | CLK_SEL[0] |
| L2 | CLK_SEL[1] |
| J1 | CLKN |
| K1 | CLKP |
| N7 | CMN |
| P7 | CMP |
| H1 | CONFIG[0] |
| D1 | CONFIG[1] |
| D2 | CONFIG[2] |
| E2 | CONFIG[3] |
| G2 | CONFIG[4] |
| H2 | CONFIG[5] |
| D3 | CONFIG[6] |
| H3 | CONFIG[7] |
| M12 | CTSTPT |
| F5 | DVDD |
| F7 | DVDD |
| G5 | DVDD |
| G7 | DVDD |

| Pin Number | Pin Name |
|------------|----------|
| H5 | DVDD |
| H7 | DVDD |
| J5 | DVDD |
| J7 | DVDD |
| F10 | – |
| G10 | – |
| H10 | – |
| K10 | – |
| H11 | – |
| G12 | – |
| C2 | INTn |
| E1 | LED[0] |
| F1 | LED[1] |
| G1 | LED[2] |
| F2 | LED[3] |
| B1 | MDC |
| N9 | MDIN[0] |
| P8 | MDIN[1] |
| N5 | MDIN[2] |
| P4 | MDIN[3] |
| C1 | MDIO |
| P9 | MDIP[0] |
| N8 | MDIP[1] |
| P5 | MDIP[2] |
| N4 | MDIP[3] |
| H12 | RCLK0 |
| G11 | RCLK1 |
| D12 | RESETn |



| Pin Number | Pin Name |
|------------|---------------------|
| B11 | SHSDACN |
| A11 | SHSDACP |
| D10 | SIN[0] |
| D8 | SIN[1] |
| D6 | SIN[2] |
| D4 | SIN[3] |
| C10 | SIP[0] |
| C8 | SIP[1] |
| C6 | SIP[2] |
| C4 | SIP[3] |
| B12 | SIREF |
| B9 | SON[0] |
| B7 | SON[1] |
| B5 | SON[2] |
| B3 | SON[3] |
| A9 | SOP[0] |
| A7 | SOP[1] |
| A5 | SOP[2] |
| A3 | SOP[3] |
| F12 | SPI_CLK |
| E12 | SPI_MISO |
| E11 | SPI_MOSI |
| D11 | SPI_SS _n |
| C12 | STSTPT |
| K12 | TCK |
| K11 | TDI |
| J12 | TDO |
| B2 | TEST |

| Pin Number | Pin Name |
|------------|-------------------|
| M11 | TEST_CLKN |
| L11 | TEST_CLKP |
| J11 | TMS |
| L12 | TRST _n |
| N2 | TSTCN |
| P2 | TSTCP |
| J2 | VDDCTRL |
| J3 | VDDOL |
| G3 | VDDOM |
| G9 | VDDOR |
| J9 | VDDOT |
| E6 | VDDR09 |
| F9 | VHV |
| K3 | VSEL_L |
| F3 | VSEL_M |
| E10 | VSEL_R |
| H9 | VSEL_T |
| A1 | VSS |
| F4 | VSS |
| F6 | VSS |
| F8 | VSS |
| F11 | VSS |
| G4 | VSS |
| G6 | VSS |
| G8 | VSS |
| H4 | VSS |
| H6 | VSS |
| H8 | VSS |

| Pin Number | Pin Name |
|-------------------|-----------------|
| J4 | VSS |
| J6 | VSS |
| J8 | VSS |
| J10 | VSS |
| M1 | XTAL1 |
| L1 | XTAL2 |

2.3.2 88E2040L Device Pin Assignment List

Table 14: 88E2040L Pin List — Alphabetical by Signal Name

| Pin Number | Pin Name | Pin Number | Pin Name |
|------------|----------|------------|----------|
| F21 | AVDDC | C5 | AVSS |
| W21 | AVDDC | C6 | AVSS |
| Y1 | AVDDC | C8 | AVSS |
| Y21 | AVDDC | C10 | AVSS |
| A1 | AVSS | C13 | AVSS |
| A3 | AVSS | C15 | AVSS |
| A5 | AVSS | C17 | AVSS |
| A7 | AVSS | C18 | AVSS |
| A9 | AVSS | C19 | AVSS |
| A14 | AVSS | C21 | AVSS |
| A16 | AVSS | D5 | AVSS |
| A18 | AVSS | D10 | AVSS |
| A20 | AVSS | D13 | AVSS |
| A22 | AVSS | D18 | AVSS |
| B1 | AVSS | E1 | AVSS |
| B3 | AVSS | E3 | AVSS |
| B5 | AVSS | E5 | AVSS |
| B7 | AVSS | E7 | AVSS |
| B9 | AVSS | E9 | AVSS |
| B14 | AVSS | E10 | AVSS |
| B16 | AVSS | E14 | AVSS |
| B18 | AVSS | E16 | AVSS |
| B20 | AVSS | E18 | AVSS |
| B22 | AVSS | E20 | AVSS |
| C2 | AVSS | E22 | AVSS |
| C4 | AVSS | M1 | AVSS |

| Pin Number | Pin Name |
|------------|----------|
| M5 | AVSS |
| M6 | AVSS |
| M7 | AVSS |
| M8 | AVSS |
| M9 | AVSS |
| M10 | AVSS |
| M11 | AVSS |
| M12 | AVSS |
| M13 | AVSS |
| M14 | AVSS |
| M15 | AVSS |
| M16 | AVSS |
| M17 | AVSS |
| M18 | AVSS |
| M19 | AVSS |
| N6 | AVSS |
| N11 | AVSS |
| N16 | AVSS |
| P2 | AVSS |
| P3 | AVSS |
| P4 | AVSS |
| P5 | AVSS |
| P6 | AVSS |
| P7 | AVSS |
| P8 | AVSS |
| P9 | AVSS |
| P10 | AVSS |
| P11 | AVSS |

| Pin Number | Pin Name |
|------------|----------|
| P12 | AVSS |
| P13 | AVSS |
| P14 | AVSS |
| P15 | AVSS |
| P16 | AVSS |
| P17 | AVSS |
| P18 | AVSS |
| P19 | AVSS |
| P20 | AVSS |
| R6 | AVSS |
| R11 | AVSS |
| R16 | AVSS |
| T6 | AVSS |
| T11 | AVSS |
| T16 | AVSS |
| U2 | AVSS |
| U3 | AVSS |
| U4 | AVSS |
| U5 | AVSS |
| U6 | AVSS |
| U7 | AVSS |
| U8 | AVSS |
| U9 | AVSS |
| U10 | AVSS |
| U11 | AVSS |
| U12 | AVSS |
| U13 | AVSS |
| U14 | AVSS |



| Pin Number | Pin Name |
|------------|----------|
| U15 | AVSS |
| U16 | AVSS |
| U17 | AVSS |
| U18 | AVSS |
| U19 | AVSS |
| U20 | AVSS |
| V6 | AVSS |
| V11 | AVSS |
| V16 | AVSS |
| V22 | AVSS |
| W6 | AVSS |
| W11 | AVSS |
| W16 | AVSS |
| Y2 | AVSS |
| Y5 | AVSS |
| Y6 | AVSS |
| Y7 | AVSS |
| Y10 | AVSS |
| Y11 | AVSS |
| Y12 | AVSS |
| Y15 | AVSS |
| Y16 | AVSS |
| Y17 | AVSS |
| Y20 | AVSS |
| AA1 | AVSS |
| AA6 | AVSS |
| AA11 | AVSS |
| AA16 | AVSS |

| Pin Number | Pin Name |
|------------|------------|
| AA22 | AVSS |
| AB1 | AVSS |
| AB6 | AVSS |
| AB11 | AVSS |
| AB16 | AVSS |
| AB22 | AVSS |
| U1 | AVSSC |
| AA21 | CHSDACN |
| AB21 | CHSDACP |
| Y22 | CIREF |
| M3 | CLK_SEL[0] |
| M4 | CLK_SEL[1] |
| N1 | CLKN |
| P1 | CLKP |
| L1 | CONFIG[0] |
| L2 | CONFIG[1] |
| M2 | CONFIG[2] |
| L4 | CONFIG[3] |
| H1 | CONFIG[4] |
| H4 | CONFIG[5] |
| J5 | CONFIG[6] |
| G5 | CONFIG[7] |
| W22 | CTSTPT |
| F7 | DVDD |
| F9 | DVDD |
| F13 | DVDD |
| F15 | DVDD |
| F17 | DVDD |

| Pin Number | Pin Name |
|------------|----------|
| G7 | DVDD |
| G9 | DVDD |
| G11 | DVDD |
| G13 | DVDD |
| G15 | DVDD |
| G17 | DVDD |
| H7 | DVDD |
| H9 | DVDD |
| H11 | DVDD |
| H13 | DVDD |
| H15 | DVDD |
| H17 | DVDD |
| J7 | DVDD |
| J9 | DVDD |
| J11 | DVDD |
| J13 | DVDD |
| J15 | DVDD |
| J17 | DVDD |
| K7 | DVDD |
| K9 | DVDD |
| K11 | DVDD |
| K13 | DVDD |
| K15 | DVDD |
| K17 | DVDD |
| L7 | DVDD |
| L9 | DVDD |
| L11 | DVDD |
| L13 | DVDD |

| Pin Number | Pin Name |
|------------|-----------|
| L15 | DVDD |
| L17 | DVDD |
| D11 | INTn |
| B11 | MDC[0] |
| A11 | MDC[1] |
| A12 | MDC[2] |
| B12 | MDC[3] |
| C11 | MDIO[0] |
| A10 | MDIO[1] |
| A13 | MDIO[2] |
| C12 | MDIO[3] |
| V2 | P0_ATN[0] |
| V3 | P0_ATN[1] |
| V4 | P0_ATN[2] |
| V5 | P0_ATN[3] |
| W2 | P0_ATP[0] |
| W3 | P0_ATP[1] |
| W4 | P0_ATP[2] |
| W5 | P0_ATP[3] |
| R2 | P0_AVDDL |
| R3 | P0_AVDDL |
| R4 | P0_AVDDL |
| R5 | P0_AVDDL |
| N2 | P0_AVDDH |
| N3 | P0_AVDDH |
| N4 | P0_AVDDH |
| N5 | P0_AVDDH |
| T2 | P0_AVDDT |



| Pin Number | Pin Name |
|------------|------------|
| T3 | P0_AVDDT |
| T4 | P0_AVDDT |
| T5 | P0_AVDDT |
| E4 | P0_AVDDR |
| D2 | P0_AVDDS |
| D4 | P0_AVDDS |
| Y3 | P0_CMN |
| Y4 | P0_CMP |
| L22 | P0_GPIO[0] |
| L20 | P0_GPIO[1] |
| H22 | P0_GPIO[2] |
| K1 | P0_LED[0] |
| K2 | P0_LED[1] |
| K3 | P0_LED[2] |
| K4 | P0_LED[3] |
| AA2 | P0_MDIN[0] |
| AA3 | P0_MDIN[1] |
| AA4 | P0_MDIN[2] |
| AA5 | P0_MDIN[3] |
| AB2 | P0_MDIP[0] |
| AB3 | P0_MDIP[1] |
| AB4 | P0_MDIP[2] |
| AB5 | P0_MDIP[3] |
| D1 | P0_SIN[0] |
| D3 | P0_SIN[1] |
| C1 | P0_SIP[0] |
| C3 | P0_SIP[1] |
| B2 | P0_SON[0] |

| Pin Number | Pin Name |
|------------|-----------|
| B4 | P0_SON[1] |
| A2 | P0_SOP[0] |
| A4 | P0_SOP[1] |
| E2 | P0_VDDR09 |
| F5 | P0_VHV |
| V10 | P1_ATN[0] |
| V9 | P1_ATN[1] |
| V8 | P1_ATN[2] |
| V7 | P1_ATN[3] |
| W10 | P1_ATP[0] |
| W9 | P1_ATP[1] |
| W8 | P1_ATP[2] |
| W7 | P1_ATP[3] |
| R7 | P1_AVDDL |
| R8 | P1_AVDDL |
| R9 | P1_AVDDL |
| R10 | P1_AVDDL |
| N7 | P1_AVDDH |
| N8 | P1_AVDDH |
| N9 | P1_AVDDH |
| N10 | P1_AVDDH |
| T7 | P1_AVDDT |
| T8 | P1_AVDDT |
| T9 | P1_AVDDT |
| T10 | P1_AVDDT |
| E6 | P1_AVDDR |
| D6 | P1_AVDDS |
| D8 | P1_AVDDS |

| Pin Number | Pin Name |
|------------|------------|
| Y9 | P1_CMN |
| Y8 | P1_CMP |
| M22 | P1_GPIO[0] |
| M20 | P1_GPIO[1] |
| H20 | P1_GPIO[2] |
| J1 | P1_LED[0] |
| J3 | P1_LED[1] |
| H3 | P1_LED[2] |
| J4 | P1_LED[3] |
| AA10 | P1_MDIN[0] |
| AA9 | P1_MDIN[1] |
| AA8 | P1_MDIN[2] |
| AA7 | P1_MDIN[3] |
| AB10 | P1_MDIP[0] |
| AB9 | P1_MDIP[1] |
| AB8 | P1_MDIP[2] |
| AB7 | P1_MDIP[3] |
| D9 | P1_SIN[0] |
| D7 | P1_SIN[1] |
| C9 | P1_SIP[0] |
| C7 | P1_SIP[1] |
| B8 | P1_SON[0] |
| B6 | P1_SON[1] |
| A8 | P1_SOP[0] |
| A6 | P1_SOP[1] |
| E8 | P1_VDDR09 |
| F11 | P1_VHV |
| V12 | P2_ATN[0] |

| Pin Number | Pin Name |
|------------|------------|
| V13 | P2_ATN[1] |
| V14 | P2_ATN[2] |
| V15 | P2_ATN[3] |
| W12 | P2_ATP[0] |
| W13 | P2_ATP[1] |
| W14 | P2_ATP[2] |
| W15 | P2_ATP[3] |
| R12 | P2_AVDDL |
| R13 | P2_AVDDL |
| R14 | P2_AVDDL |
| R15 | P2_AVDDL |
| N12 | P2_AVDDH |
| N13 | P2_AVDDH |
| N14 | P2_AVDDH |
| N15 | P2_AVDDH |
| T12 | P2_AVDDT |
| T13 | P2_AVDDT |
| T14 | P2_AVDDT |
| T15 | P2_AVDDT |
| E15 | P2_AVDDR |
| D15 | P2_AVDDS |
| D17 | P2_AVDDS |
| Y13 | P2_CMN |
| Y14 | P2_CMP |
| N22 | P2_GPIO[0] |
| M21 | P2_GPIO[1] |
| J21 | P2_GPIO[2] |
| G1 | P2_LED[0] |



| Pin Number | Pin Name |
|------------|------------|
| G2 | P2_LED[1] |
| H2 | P2_LED[2] |
| G4 | P2_LED[3] |
| AA12 | P2_MDIN[0] |
| AA13 | P2_MDIN[1] |
| AA14 | P2_MDIN[2] |
| AA15 | P2_MDIN[3] |
| AB12 | P2_MDIP[0] |
| AB13 | P2_MDIP[1] |
| AB14 | P2_MDIP[2] |
| AB15 | P2_MDIP[3] |
| D14 | P2_SIN[0] |
| D16 | P2_SIN[1] |
| C14 | P2_SIP[0] |
| C16 | P2_SIP[1] |
| B15 | P2_SON[0] |
| B17 | P2_SON[1] |
| A15 | P2_SOP[0] |
| A17 | P2_SOP[1] |
| E13 | P2_VDDR09 |
| F12 | P2_VHV |
| V20 | P3_ATN[0] |
| V19 | P3_ATN[1] |
| V18 | P3_ATN[2] |
| V17 | P3_ATN[3] |
| W20 | P3_ATP[0] |
| W19 | P3_ATP[1] |
| W18 | P3_ATP[2] |

| Pin Number | Pin Name |
|------------|------------|
| W17 | P3_ATP[3] |
| R17 | P3_AVDDL |
| R18 | P3_AVDDL |
| R19 | P3_AVDDL |
| R20 | P3_AVDDL |
| N17 | P3_AVDDH |
| N18 | P3_AVDDH |
| N19 | P3_AVDDH |
| N20 | P3_AVDDH |
| T17 | P3_AVDDT |
| T18 | P3_AVDDT |
| T19 | P3_AVDDT |
| T20 | P3_AVDDT |
| E17 | P3_AVDDR |
| D19 | P3_AVDDS |
| D21 | P3_AVDDS |
| Y19 | P3_CMN |
| Y18 | P3_CMP |
| P22 | P3_GPIO[0] |
| N21 | P3_GPIO[1] |
| K21 | P3_GPIO[2] |
| F1 | P3_LED[0] |
| F2 | P3_LED[1] |
| F3 | P3_LED[2] |
| F4 | P3_LED[3] |
| AA20 | P3_MDIN[0] |
| AA19 | P3_MDIN[1] |
| AA18 | P3_MDIN[2] |

| Pin Number | Pin Name |
|------------|---------------------|
| AA17 | P3_MDIN[3] |
| AB20 | P3_MDIP[0] |
| AB19 | P3_MDIP[1] |
| AB18 | P3_MDIP[2] |
| AB17 | P3_MDIP[3] |
| D22 | P3_SIN[0] |
| D20 | P3_SIN[1] |
| C22 | P3_SIP[0] |
| C20 | P3_SIP[1] |
| B21 | P3_SON[0] |
| B19 | P3_SON[1] |
| A21 | P3_SOP[0] |
| A19 | P3_SOP[1] |
| E19 | P3_VDDR09 |
| F18 | P3_VHV |
| K22 | RCLK0 |
| J22 | RCLK1 |
| G22 | RESETn |
| F20 | SHSDACN |
| F19 | SHSDACP |
| E21 | SIREF |
| K20 | SPI_CLK |
| J20 | SPI_MISO |
| G20 | SPI_MOSI |
| G21 | SPI_SS _n |
| F22 | STSTPT |
| R21 | TCK |
| T21 | TDI |

| Pin Number | Pin Name |
|------------|-------------------|
| U21 | TDO |
| D12 | TEST |
| T22 | TEST_CLKN |
| U22 | TEST_CLKP |
| V21 | TMS |
| R22 | TRST _n |
| V1 | TSTCN |
| W1 | TSTCP |
| H5 | VDDOL |
| K5 | VDDOL |
| E11 | VDDOM |
| G19 | VDDOR |
| J19 | VDDOR |
| K19 | VDDOT |
| L5 | VSEL_L |
| E12 | VSEL_M |
| H19 | VSEL_R |
| L19 | VSEL_T |
| B10 | VSS |
| B13 | VSS |
| F6 | VSS |
| F8 | VSS |
| F10 | VSS |
| F14 | VSS |
| F16 | VSS |
| G3 | VSS |
| G6 | VSS |
| G8 | VSS |



| Pin Number | Pin Name |
|------------|----------|
| G10 | VSS |
| G12 | VSS |
| G14 | VSS |
| G16 | VSS |
| G18 | VSS |
| H6 | VSS |
| H8 | VSS |
| H10 | VSS |
| H12 | VSS |
| H14 | VSS |
| H16 | VSS |
| H18 | VSS |
| H21 | VSS |
| J2 | VSS |
| J6 | VSS |
| J8 | VSS |
| J10 | VSS |
| J12 | VSS |
| J14 | VSS |
| J16 | VSS |
| J18 | VSS |
| K6 | VSS |
| K8 | VSS |
| K10 | VSS |
| K12 | VSS |
| K14 | VSS |
| K16 | VSS |
| K18 | VSS |

| Pin Number | Pin Name |
|------------|----------|
| L3 | VSS |
| L6 | VSS |
| L8 | VSS |
| L10 | VSS |
| L12 | VSS |
| L14 | VSS |
| L16 | VSS |
| L18 | VSS |
| L21 | VSS |
| P21 | VSS |
| T1 | XTAL1 |
| R1 | XTAL2 |

3

Functional Description

This section describes the chip-level functionality.

3.1

Data Path

The data path of the device flows through the copper interface (T Unit), and the host interface (H Unit). These interfaces are discussed in detail in [Section 4](#), and [Section 5](#), respectively.

Figure 5: Device Data Path (88E2040L)

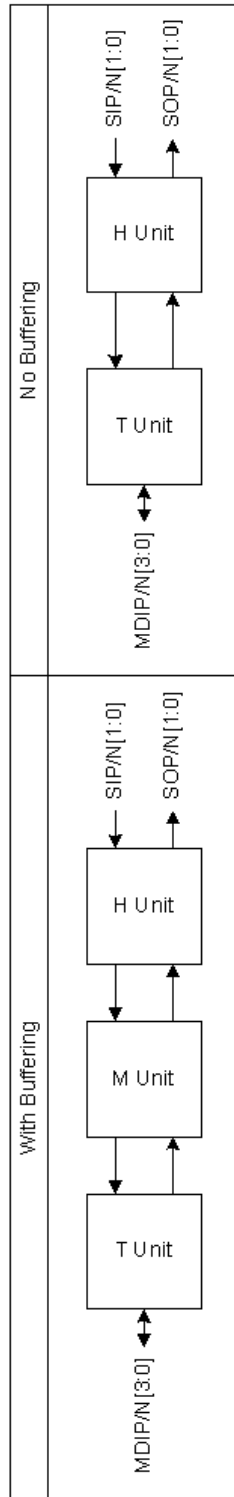
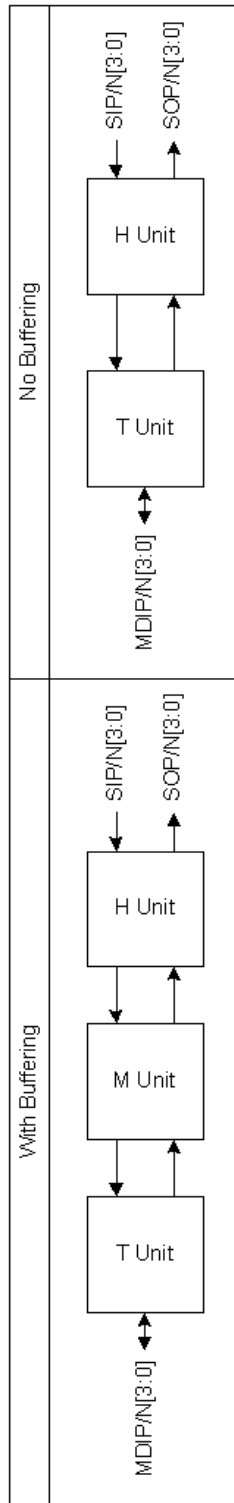


Figure 6: Device Data Path (88E2010)



3.2 Buffering

Packets may flow through some buffering as shown in [Figure 5](#) in [Section 3.1](#). Buffering will occur for a variety of all the reasons described in this section.

3.2.1 EEE Buffering

EEE PHY functionality to operate correctly, an EEE-compliant MAC is required to control the PHY as when to enter and exit the low power idle (LPI) state and buffer packets to allow the PHY adequate time to exit the low power idle state. The PHY should be set to transparent (slave) EEE mode when operating with an EEE-compliant MAC (register 1.C033.0 = 0).

The device is able to support non-EEE compliant MACs by enabling the internal EEE buffering by setting register 1.C033.0 to 1. EEE buffering is automatically disabled when the device or its link partner is not capable of EEE operation.

When the EEE buffer is empty for the amount of time specified by registers 1.C033.15:8, 31.F004.7:0, 31.F004.15:8 for 10 Gbps, 1000 Mbps, and 100 Mbps speeds, respectively (in units of 1 microsecond), the buffer will indicate to the PHY that it wishes to enter the LPI state.

When the EEE buffer is not empty it will indicate to the PHY that it must exit the LPI state. The EEE buffer ensures that no packets are lost by the PHY during the transition from LPI state to normal mode of operation. When the media interface exits the LPI state, the data in the buffer is then released and transmitted to the line. The amount of time the packet is held in the buffer prior to release can be programmed via registers 31.F005.15:8, 31.F006.7:0, and 31.F006.15:8 for 10 Gbps, 1000 Mbps, and 100 Mbps speeds, respectively. The unit is in microseconds. The minimum IPG between packets as set in 31.F005.7:0 will be used to separate packets until the EEE buffer is fully drained.

3.3 Link Interrupt

When the MACs are not bypassed, all local and remote faults received on the line or host will be terminated by the MAC. For example, if a local fault is received on the line, then the MAC terminates the local fault and never passes it upstream to the host. The MAC will transmit a remote fault back to the line.

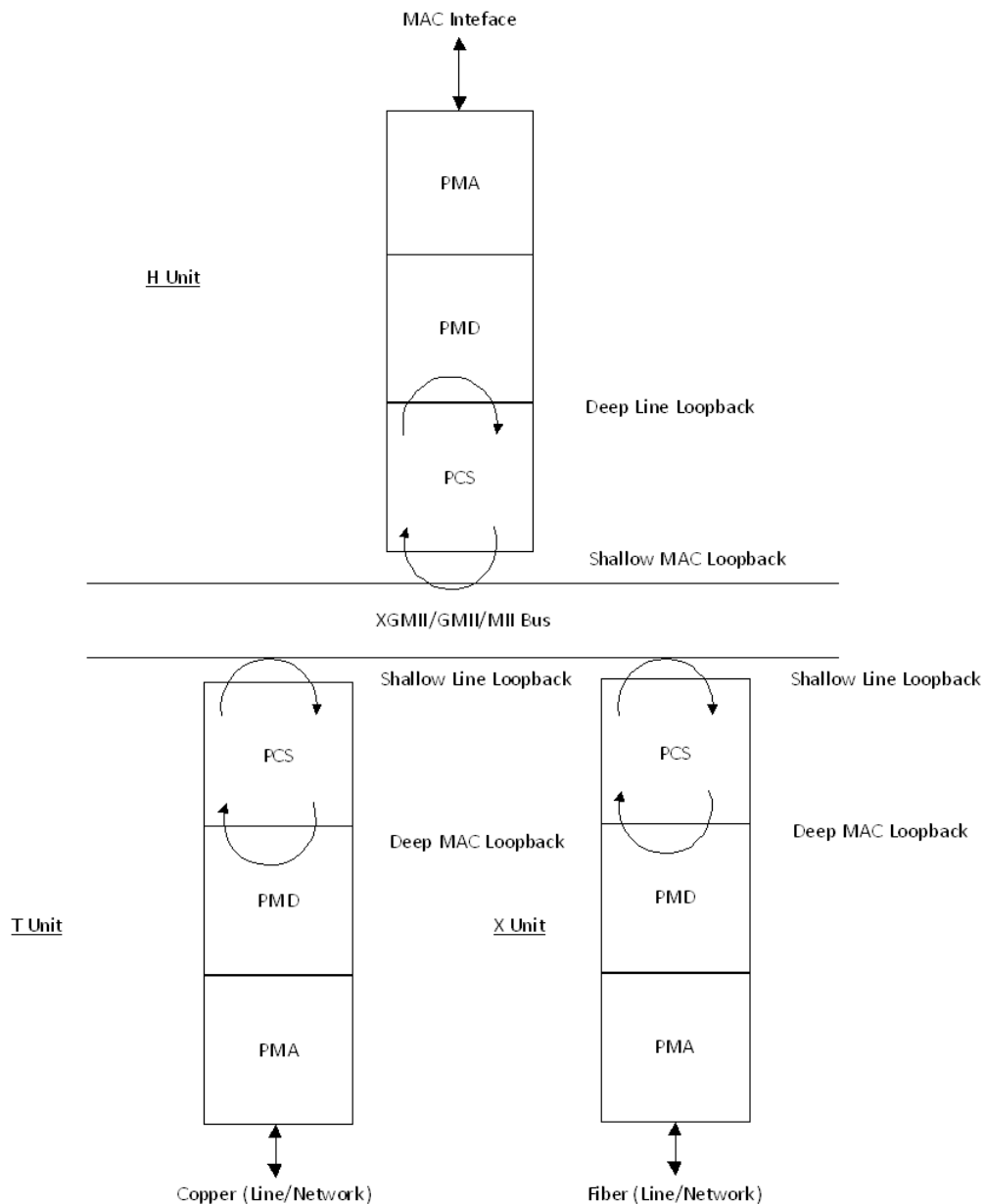
3.4 Loopback

The T, X, and H Units has the ability to perform MAC loopback and line loopback as shown in Figure 7. Each unit can only be in MAC loopback or line loopback at any given time. If MAC loopback is engaged, then loopback speed depends upon the media link speed. If the media link is down, then the MAC interface speed is dependent upon the setting in 31.F000.7:6, Default MAC Interface Speed. A deep line loopback must not be enabled at the same time as a MAC loopback or a closed internal bus loop will be created.

Table 15: Loopback Control

| Loopback Point | Register | Function | Setting |
|----------------|-------------------------------------|---|---|
| A | 3.0000.14 | T Unit Deep MAC Loopback | 1 = Loopback 0 = Normal operation |
| B | 3.1000.14 3.2000.14 | X Unit Deep MAC Loopback | 1 = Loopback 0 = Normal operation |
| C | 4.0000.14 4.1000.14 4.2000.14 | H Unit Deep Line Loopback | 1 = Loopback 0 = Normal operation |
| D | 3.8002.5 | T Unit Shallow Line Loopback for 1000/100/10 mode | 1 = Enable Line Loopback 0 = Normal operation |
| E | 1.C000.11 | T Unit Shallow Line Loopback for 5G/2.5G mode | 1 = Enable Line Loopback 0 = Normal operation |
| F | 3.F003.12 | X Unit Shallow Line Loopback | 1 = Enable Line Loopback 0 = Normal operation |
| G | 4.F003.12 | H Unit Shallow MAC Loopback | 1 = Enable Line Loopback 0 = Normal operation |
| – | 31.F000.7:6 | Default MAC Interface Speed | This is the MAC Interface Speed during Link down. 00 = 10 Mbps 01 = 100 Mbps 10 = 1000 Mbps 11 = 10 Gbps |
| – | 31.F0A8.1:0 | Device Max Speed Limit Control | This controls the link down max speed. 00 = 10 Gbps 10 = 5 Gbps 11 = 2.5 Gbps Port soft reset should be followed. |

Figure 7: Loopback Paths



3.4.1 MAC Loopback

MAC loopback is defined as taking data from the MAC interface and transmitting that data back towards the MAC interface. For the loopback to occur, the unit must have control of the XGMII bus that it is outputting on, that is, that unit must have control of the data path.

If the link is down, then the loopback speed will be determined by register 31.F000.7:6 and 31.F0A8.1:0. Only host shallow MAC loopback is supported when the media link is down.

3.4.2 Line Loopback

Line loopback is defined to be looping the data that is received on the network interface and transmitting that data back onto the network interface.

The speed of the loopback is determined by the active link speed.

3.5 Configuration and Resets

The device can be configured in the following ways:

- Hardware configuration strap options
- MDC/MDIO register access

All hardware configuration options can be overwritten via the other methods except PHYADR and MDIO.

This section will discuss the hardware configuration.

3.5.1 Hardware and Software Resets

RESETn is the hardware reset pin for the entire chip. To ensure that the stopping of the hardware configuration is correct, it is required that upon system power-up, a reset signal be applied to RESETn or the RESETn pin be held low until all the power rails are settled down.

In addition to the hardware reset pin (RESETn), there are several software reset bits that reset various parts of the chip.

- A hardware reset will reset the entire chip and initialize all the registers to their hardware reset default.
- A software reset has a similar effect on the affected units as a hardware reset except all Retain-type of will hold their value, and the Update-type registers will have the previously written values take effect.

Register 31.F001.14 is a software bit that emulates the hardware reset. Setting the bit to 1 will reset the entire chip (all ports) as if the RESETn pin is asserted. All ports have register 31.F001.14; however, special care should be taken when selecting the specific port number to achieve entire chip reset. The applicable register in Port 3 (88E2040L) and Port 0 (88E2010) should be programmed. When triggered, registers are not accessible through the MDIO until the chip reset completes.

Setting register 31.F001.15 to 1 software resets the entire port except for the T Unit. The T Unit will briefly power down and Auto-Negotiation will restart.

Setting registers 31.F001.13, 1.0000.15, 3.0000.15, or 7.0000.15 to 1 software resets the T Unit only.

Setting registers 4.0000.15, 4.1000.15, or 4.2000.15 to 1 software resets the H Unit only.

3.5.2 Hardware Configuration

After the deassertion of RESETn the device will be hardware configured through the CONFIG[7:0] pins. Each pin is used to configure 3 bits. The 3-bit value is set depending on which LED pin or static level is connected to the CONFIG pins at the deassertion of hardware reset.

The three configuration bits per pin mapping for the 88E2010 device is shown in [Table 16](#).

The three bit mapping for the 88E2010 device during hardware configuration is shown in [Table 17](#).

Table 16: 88E2010 Device Configuration Mapping

| Pin Test | Bit 2 | Bit 1 | Bit 2 |
|-----------|-------------|-------------|-------------|
| CONFIG[0] | PHYAD[4] | PHYAD[3] | PHYAD[2] |
| CONFIG[1] | ANEG_MS | PHYAD[1] | PDSTATE |
| CONFIG[2] | ANEG_SPD[2] | ANEG_SPD[1] | ANEG_SPD[0] |
| CONFIG[3] | MACTYPE[2] | MACTYPE[1] | MACTYPE[0] |

Table 16: 88E2010 Device Configuration Mapping (Continued)

| Pin Test | Bit 2 | Bit 1 | Bit 2 |
|-----------|--------------|--------------|--------------|
| CONFIG[4] | MEDIATYPE[2] | MEDIATYPE[1] | MEDIATYPE[0] |
| CONFIG[5] | SPI_CONFIG | RESERVED | RESERVED |
| CONFIG[7] | FACTORY_TEST | RESERVED | RESERVED |

Table 17: 88E2010 Three Bit Mapping

| Pin | Bit 2 |
|----------|-------|
| VSS | 000 |
| LED[0] | 001 |
| LED[1] | 010 |
| LED[2] | 011 |
| LED[3] | 100 |
| Reserved | 101 |
| Reserved | 110 |
| VDDO | 111 |

The three configuration bits per pin mapping for the 88E2040L device is shown in [Table 18](#).

The three bit mapping for the 88E2040L device during hardware configuration is shown in [Table 19](#).

Table 18: 88E2040L Device Configuration Mapping

| Pin | Bit 2 | Bit 1 | Bit 0 |
|-----------|--------------|--------------|--------------|
| CONFIG[0] | PHYAD[4] | PHYAD[3] | PHYAD[2] |
| CONFIG[1] | ANEG_MS | RESERVED | PDSTATE |
| CONFIG[2] | ANEG_SPD[2] | ANEG_SPD[1] | ANEG_SPD[0] |
| CONFIG[3] | MACTYPE[2] | MACTYPE[1] | MACTYPE[0] |
| CONFIG[4] | MEDIATYPE[2] | MEDIATYPE[1] | MEDIATYPE[0] |
| CONFIG[5] | SPI_CONFIG | RESERVED | RESERVED |
| CONFIG[7] | FACTORY_TEST | MDIO[1] | MDIO[0] |

Table 19: 88E2040L Device Three Bit Mapping

| Pin | Bit 2:0 |
|-----------|---------|
| VSS | 000 |
| P3_LED[0] | 001 |
| P3_LED[1] | 010 |
| P2_LED[0] | 011 |
| P2_LED[1] | 100 |
| P1_LED[0] | 101 |
| P1_LED[1] | 110 |

Table 19: 88E2040L Device Three Bit Mapping (Continued)

| Pin | Bit 2:0 |
|------|---------|
| VDDO | 111 |

The configuration bit definition is shown in [Table 20](#).

Table 20: Configuration Bit Definition

| Bits | Definition | Description |
|----------------------------|---|--|
| PHYAD[4:0] | PHY Address | 88E2040L PHYAD[1:0] is hardcoded as a function of REV_PHYAD. |
| REV_PHYAD | 88E2040L - Reverse PHYAD[1:0] order 88E2010 - N/A | 88E2040L PHYAD[1:0] corresponds to the following: 0 = 00 - Port 0 01 - Port 1 10 - Port 2 11 - Port 3 1 = 00 - Port 3 01 - Port 2 10 - Port 1 11 - Port 0 |
| MDIO[1:0] (88E2040L) | This determines whether the four ports are accessed from a 1 MDIO, 2 ports per MDIO, or 1 MDIO per port. 00 = MDC[2]/MDIO[2] Access on all four ports 01 = MDC[1]/MDIO[1] Accesses Port 0 and Port 1 MDC[2]/MDIO[2] Accesses Port 2 and Port 3 10 = MDC[0]/MDIO[0] Accesses Port 0 MDC[1]/MDIO[1] Accesses Port 1 MDC[2]/MDIO[2] Accesses Port 2 MDC[3]/MDIO[3] Accesses Port 3 11 = Reserved | None |
| MACTYPE[2:0] (88E2040L) | 000 = Reserved 001 = Reserved 010 = Reserved 011 = Reserved 100 = 5GBASE-R/2500BASE-X/SGMII Auto-Negotiation On 101 = 5GBASE-R/2500BASE-X/SGMII Auto-Negotiation Off 110 = Reserved 111 = Reserved | C Unit Host interface mode for 88E2040L |

Table 20: Configuration Bit Definition (Continued)

| Bits | Definition | Description |
|---------------------------|--|---|
| MACTYPE[2:0] (88E2010) | 000 = Reserved 001 = Reserved 010 = Reserved 011 = 5GBASE-R/2500BASE-X/SGMII Auto-Negotiation On 100 = 5GBASE-R/2500BASE-X/SGMII Auto-Negotiation On 101 = 5GBASE-R/2500BASE-X/SGMII SGMII Auto-Negotiation Off 110 = Reserved 111 = Reserved | C Unit Host interface mode for 88E2010 |
| MEDIATYPE[2:0] | 000 = Copper Only 001-111 = RESERVED | C Unit Line-side interface |
| PDSTATE | 0 = Start In Power Up State 1 = Start In Power Down State | T Unit Copper power down state |
| ANEG_MS | 0 = Prefer Slave 1 = Prefer Master | T Unit Master and slave configuration |
| FACTORY_TEST | Factory Test Mode 0 = Normal mode (default) 1 = Test Mode (reserved for Marvell) | None |
| ANEG_SPD[2:0] | This sets the default for speed advertisement during Auto-Negotiation. 000 = Reserved 001 = 5G, 2.5G, 1000 Mbps Full 010 = 5G, 2.5G, 1000 Mbps Full, 100 Mbps Full 011 = 5G, 2.5G, 1000 Mbps Full, 100 Mbps Full, 10 Mbps Full 100 = 5G, 2.5G, 1000 Mbps Full, 100 Mbps Full/Half 101 = 5G, 2.5G, 1000 Mbps Full, 100 Mbps Full/Half, 10 Mbps Full/Half 110 = 5G, 2.5G, 1000 Mbps Full/Half, 100 Mbps Full/Half 111 = 5G, 2.5G, 1000 Mbps Full/Half, 100 Mbps Full/Half, 10 Mbps Full/Half | – |
| SPI_CONFIG | – | C Unit 31.F008.5 <= SPI_CONFIG This determines whether the embedded processor loads the firmware image from flash or waits for the image to be downloaded via MDIO. 0 = Download code via SPI. 1 = Wait for download via MDIO. To override this configuration, change 31.F008.5 and then perform a T Unit hardware reset using 31.F001.12. |

3.5.3 Reference Clock Selection

CLK_SEL[1:0] selects which the type and speed of the reference clock input as shown in [Table 21](#). CLK_SEL must be stable and the selected clock toggling prior to de-assertion of RESETn. CLK_SEL must not change value for the duration of device operation.

Table 21: CLK_SEL[1:0] Selection

| CLK_SEL[1:0] | XTAL1/XTAL2 | CLKP/CLKN |
|--------------|-------------|------------|
| 00 | 50 MHz | Floating |
| 01 | GND | 50 MHz |
| 10 | GND | 156.25 MHz |
| 11 | Reserved | Reserved |



Note

50 MHz crystal operation is only supported for commercial-grade devices.

3.6 MDC/MDIO Register Access

The management interface provides access to the internal registers via the MDC and MDIO pins and is compliant with IEEE 802.3 Clause 45. MDC is the management data clock input and it can run from DC to a maximum continuous rate of 12.5 MHz. At high MDIO fanouts, the maximum rate may be decreased depending on the output loading. MDIO is the management data input/output and is a bi-directional signal that runs synchronously to MDC.

The MDIO does not require a pull-up resistor. If another open-drain device driving MDIO requires a pull-up resistor, then it should drive or be pulled up to the same voltage value as the VDDOM rail.

The PHY address is configured during the hardware reset sequence. Refer to [Section 3.5, Configuration and Resets](#), on page 60 for information on how to configure PHY addresses.

Typical read and write operations on the management interface are shown in [Figure 8](#) and [Figure 9](#). The MDIO interface supports preamble suppression operation by default. Between subsequent MDIO access sequences, there must be at least 1 IDLE MDC cycle (MDIO driven high). So the minimum MDC clock cycle for a MDIO operation will 33 cycles. The start of a MDIO operation is marked by the insertion of two MDC cycle with MDIO driven to zero as this will mark the start of frame (ST) pattern as defined in IEEE 802.3 standard. All the required serial management registers are implemented as well as several optional registers. A description of the registers can be found in the register description.

Figure 8: Typical MDC/MDIO Read Operation

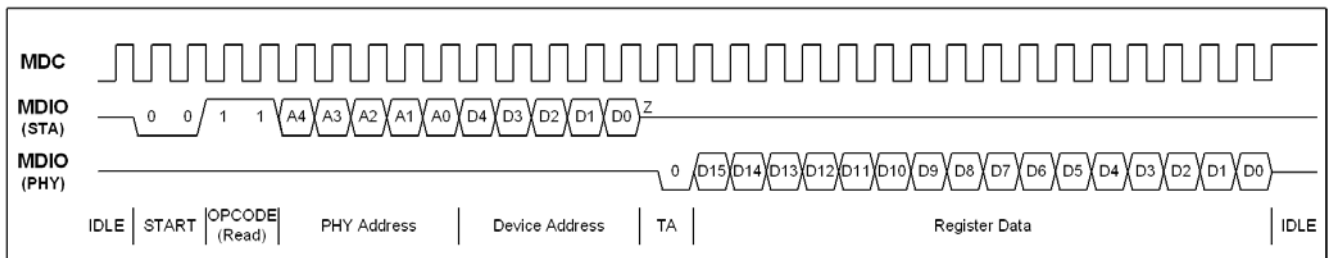
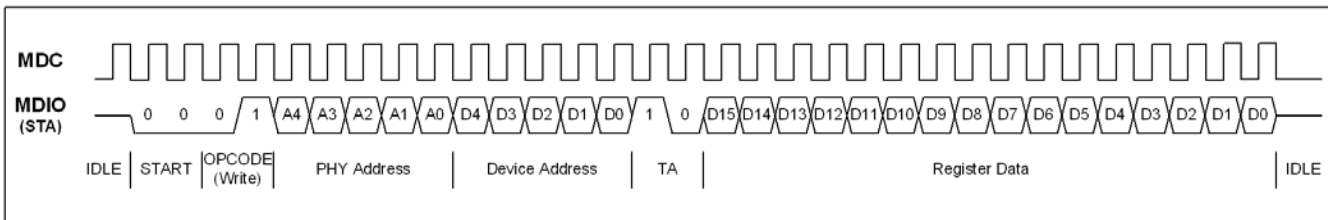


Figure 9: Typical MDC/MDIO Write Operation



3.6.1 Clause 45 MDIO Framing

The extensions for Clause 45 MDIO indirect register accesses are specified in [Table 22](#).

Table 22: Extensions for Management Frame Format for Indirect Access

| Frame | PRE | ST | OP | PHYAD | DEVADR | TA | ADDRESS/DATA | Idle |
|----------------|-------|----|----|-------|--------|----|------------------|------|
| Address | 1...1 | 00 | 00 | PPPPP | DDDDD | 10 | AAAAAAAAAAAAAAAA | Z |
| Write | 1...1 | 00 | 01 | PPPPP | DDDDD | 10 | DDDDDDDDDDDDDDDD | Z |
| Read | 1...1 | 00 | 11 | PPPPP | DDDDD | Z0 | DDDDDDDDDDDDDDDD | Z |
| Read Increment | 1...1 | 00 | 10 | PPPPP | DDDDD | Z0 | DDDDDDDDDDDDDDDD | Z |

The MDIO implements a 16-bit address register that stores the address of the register to be accessed. For an address cycle, it contains the address of the register to be accessed on the next cycle. For read, write, post-read-increment-address cycles, the field contains the data for the register. At power up and reset, the contents of the register are undefined.

Write, read, and post-read-increment-address frames access the address register, though write and read frames do not modify the contents of the address register.

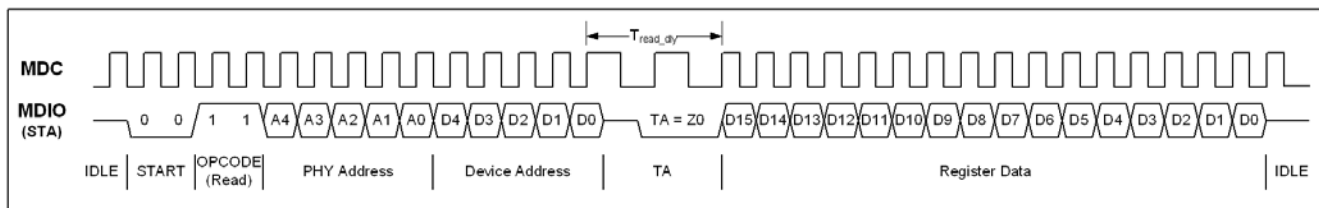
3.6.2 30 MHz High-Speed MDC/MDIO Management Interface Protocol

In addition to supporting the typical MDC/MDIO protocol, the device has the capability to run MDC down to a clock period of 35 ns. The write operation can operate normally at this speed; however, for the read operation, the MDC clock cycle must be slowed down for the TA period as shown in the [Figure 10](#).

During read operations, the MDC clock must slow down so that the PHY has sufficient time to retrieve the data.

See [Section 6.4.4, MDC/MDIO Management Interface Timing, on page 118](#) for timing details.

Figure 10: 30 MHz MDC/MDIO Read Operation



3.6.3 Independent MDC/MDIO Support

The 88E2040L device can be configured to operate with 1, 2, or 4 MDC/MDIO interfaces by setting the MDIO[1:0] configuration bits during hardware reset. The behavior is shown in [Table 23](#).

Table 23: 88E2040L Device MDC/MDIO Interface Mapping

| MDIO[1:0] Configuration Bit | 00 | 01 | 10 |
|-----------------------------|-------------------------|-------------------------|-----------------|
| MDC[0]/MDIO[0] | Pull-low/Do not connect | Pull-low/Do not connect | Port 0 MDC/MDIO |
| MDC[1]/MDIO[1] | Pull-low/Do not connect | Port 0, 1 MDC/MDIO | Port 1 MDC/MDIO |

Table 23: 88E2040L Device MDC/MDIO Interface Mapping (Continued)

| MDIO[1:0] Configuration Bit | 00 | 01 | 10 |
|--------------------------------|--------------------------|-------------------------|-----------------|
| MDC[2]/MDIO[2] | Port 0, 1, 2, 3 MDC/MDIO | Port 2, 3 MDC/MDIO | Port 2 MDC/MDIO |
| MDC[3]/MDIO[3] | Pull-low/Do not connect | Pull-low/Do not connect | Port 3 MDC/MDIO |



Note

Ensure that unused MDC is pulled low and MDIO be left unconnected.

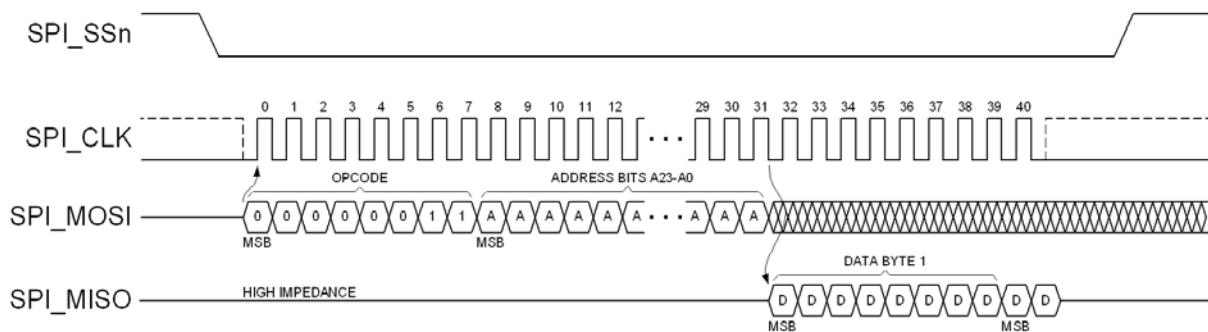
3.7 Firmware Loading

3.7.1 Flash Memory Interface

The device can download code from an external flash memory via the Serial Peripheral Interface bus (SPI) into the processor memory. The SPI bus is a 4-wire serial communications interface used by many microprocessor peripheral chips. When the hardware configuration SPI_CONFIG strap bit is set to 0, the device will download code after the de-assertion of RESETn.

The SPI controller will issue a read array command starting from address 0x000000 as shown in Figure 11. The number of bytes read will be determined by the values contained in the flash image header.

Figure 11: SPI Read Array



The device is always the master and the flash is the slave. Chip select (output SPI_SSn) is driven low by the device during every flash access.

3.7.2 Firmware Download to RAM

As an alternative to using a flash device for storing the firmware image, the image may be downloaded directly to the microcontroller RAM by the host using the Serial Management Interface (MDC/MDIO). In this case, the SPI_CONFIG strap bit must be set to 1 and the device will wait for the firmware to be downloaded to RAM. Refer to the 88E2010/88E2040L Software API package for instructions on downloading firmware to RAM via Serial Management Interface.

3.8 Power Management

This section discusses the general power down for the device. See the unit level sections for details on advanced power management of each unit.

3.8.1 Manual Power Down

The device will automatically power down unused circuits without the need for the user to intervene. The following registers can be set to force the units to power down.

Setting register 31.F001.11 to 1 powers down the entire port. Care should be used when setting this bit. When this bit is set to 1, there is no way to clear this bit via processor instructions. Clear this bit through a hardware reset or via an MDC/MDIO write.

Setting registers 1.0000.11 or 3.0000.11 to 1 powers down the T Unit only.

Setting registers 4.0000.11, 4.1000.11, or 4.2000.11 to 1 powers down the H Unit only.

3.8.2 MAC Interface Power Down

Register 31.F000.3 controls whether the H Unit is powered down while the link is down.

0 = Power down when the link is down.

1 = Always keep the H Unit powered up.

3.8.3 Controlling and Sensing

Register 31.F013 controls whether LED[3:0] pins are inputs or outputs. Each pin can be individually controlled.

Register 31.F012 allows the pins to be controlled and sensed. When configured as input, a read to register 31.F012 will return the real-time sampled state of the pin at the time of the read. A write will write the output register, but it have no immediate effect on the pin since the pin is configured to be an input. The input is sampled once every 38.4 ns.

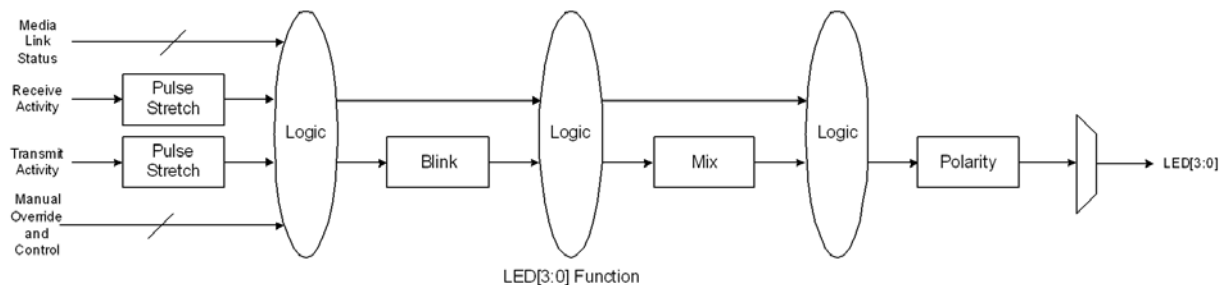
When configured as output, a read to register 31.F012 will return the value in the output register. A write will write the output register which will in turn drive the state of the pin.

3.9 LED

The LED[3:0] pins can be used to drive LED pins. Registers 31.F020 through 31.F027 control the operation of the LED pins. LED[3:0] are used to configure the PHY per [Section 3.5.2](#).

[Figure 12](#) shows the general chaining of function for the LEDs. The various functions are described in the following sections.

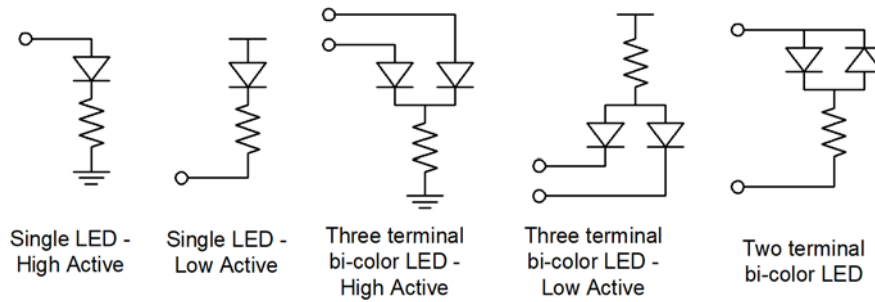
Figure 12: LED Chain



3.9.1 LED Polarity

There are a variety of ways to hook up the LEDs. Some examples are shown in [Figure 13](#). Registers 31.F023.1:0, 31.F022.1:0, 31.F021.1:0, and 31.F020.1:0 specify the output polarity for the LED[3:0] function to accommodate a variety of installation options. The lower bit of each pair specifies the on (active) state of the LED, either high or low. The upper bit of each pair specifies whether the off state of the LED should be driven to the opposite level of the on state or Hi-Z. The Hi-Z state is useful in cases such as the LOS and INIT function where the inactive state is Hi-Z.

Figure 13: Various LED Hookup Configurations



3.9.2 Pulse Stretching and Blinking

Register 31.F027.14:12 specifies the pulse stretching duration of a particular activity. Only the transmit activity, receive activity, collision activity, and (transmit or receive) activity are stretched. All other statuses are not stretched since they are static in nature and no stretching is required.

Some status will require blinking state instead of a solid on state. Registers 31.F027.10:8 and 31.F027.6:4 specify the two blink rates. The pulse stretching is applied first and the blinking will reflect the duration of the stretched pulse.

Registers 31.F020.2, 31.F021.2, 31.F022.2, and 31.F023.2 select which of the two blink rates to use for LED[0] to LED[3], respectively.

- 0 = Select Blink Rate 1.
- 1 = Select Blink Rate 2.

The stretched or blinked output will be mixed if needed (see [Section 3.9.3](#)) and then inverted/Hi-Z according to the polarity described in [Section 3.9.1](#).

3.9.3 Bi-Color LED Mixing

In the dual LED modes, the mixing function allows the 2 colors of the LED to be mixed to form a third color. This is useful since the PHY supports 10/100 Mbps, 1G, and 5G/2.5G operation speeds.

Register 31.F026.7:4 controls the amount to mix in the LED[3], and LED[1] pins. Register 31.F026.3:0 controls the amount to mix in the LED[2] and LED[0] pins. Mixing is determined by the percentage of time the LED is on during the active state. The percentage is selectable in 12.5% increments.

There are two classes of bi-color LEDs: three-terminal type and two-terminal type. For example, the third and fourth LED block from the left in [Figure 13](#) illustrates three-terminal types and the block on the far right is the two-terminal type. In the three-terminal type, both of the LEDs can be turned on at the same time. So the sum of the percentage specified by 31.F026.7:4 and 31.F026.3:0 can exceed 100%. However, in the two-terminal type, the sum should never exceed 100% since only one LED can be turned on at any given time.

Mixing only applies when register 31.F020.12:8 or 31.F022.12:8 are set to 11xxx. There is no mixing in single LED modes.

The behavior for the various dual LED modes are described in [Table 24](#).

Table 24: Dual LED Mode Behavior

| Dual Mode Description | Blink Mix | | Solid Mix | | Speed Type 1 | | Speed Type1 | | Speed Type 2 | | Speed Type 2 | |
|-----------------------------------|--------------|--------------|--------------|--------------|--------------|--------------|--------------|--------------|--------------|--------------|--------------|--------------|
| 31.F020, 31.F022, bits 12:8 | 11010 | | 11011 | | 11100 | | 11101 | | 11110 | | 11111 | |
| Current State | LED3 LED1 | LED2 LED0 | LED3 LED1 | LED2 LED0 | LED3 LED1 | LED2 LED0 | LED3 LED1 | LED2 LED0 | LED3 LED1 | LED2 LED0 | LED3 LED1 | LED2 LED0 |
| 5/2.5 Gbps | Blink Mix | Blink Mix | Solid Mix | Solid Mix | Solid | Off | Solid | Off | Solid | Off | Solid | Off |
| 1 Gbps | Blink Mix | Blink Mix | Solid Mix | Solid Mix | Solid Mix | Solid Mix | Solid Mix | Solid Mix | Off | Solid | Off | Solid |
| 100 Mbps Link | Blink Mix | Blink Mix | Solid Mix | Solid Mix | Off | Solid | Off | Solid | Solid Mix | Solid Mix | Solid Mix | Solid Mix |
| 10 Mbps Link | Blink Mix | Blink Mix | Solid Mix | Solid Mix | Off | Off | Off | Off | Off | Off | Off | Off |
| Link Down | Blink Mix | Blink Mix | Solid Mix | Solid Mix | Off | Off | Off | Off | Off | Off | Off | Off |

3.9.4 Modes of Operation

The LED pins relay various statuses of the PHY so that they can be displayed by the LEDs.

The basic statuses are shown in [Table 25](#). The compound statuses are formed with the basic status plus the speed information as shown in [Table 26](#). The status information is generated by the copper (T Unit) interfaces.

Table 25: Basic LED Status

| Status | Copper |
|-------------|-----------------|
| Transmit | Copper Transmit |
| Receive | Copper Receive |
| Link | Copper Link |
| Full Duplex | Copper Duplex |
| Master | Master/Slave |

Table 26: Compound LED Status

| Compound Status | Copper |
|----------------------------------|---|
| Transmit or Receive | Copper Transmit or Copper Receive |
| Collision (Transmit and Receive) | Copper Transmit and Copper Receive and Copper Half Duplex |
| 10 Mbps Link | Copper Speed = 10 Mbps and Copper Link |

Table 26: Compound LED Status (Continued)

| Compound Status | Copper |
|--|---|
| 100 Mbps Link | Copper Speed = 100 Mbps and Copper Link |
| 1 Gbps Link | Copper Speed = 1 Gbps and Copper Link |
| 5/2.5 Gbps Link | Copper Speed = 5/2.5 Gbps and Copper Link |
| Link | Copper Link |
| Half Duplex | Not Copper Full Duplex |
| Slave | Not Master |
| 10 Mbps Link or 100 Mbps Link | Copper 10 Mbps Link or Copper 100 Mbps Link |
| 10 Mbps Link or 100 Mbps Link or 1 Gbps Link | Copper 10 Mbps Link or Copper 100 Mbps Link or Copper 1 Gbps Link |
| 100 Mbps Link or 5/2.5 Gbps Link | Copper 100 Mbps or Copper 5/2.5 Gbps Link |
| 1 Gbps or 5/2.5 Gbps Link | Copper 1 Gbps or Copper 5/2.5 Gbps Link |

The status that the LED displays is defined by registers 31.F020 to 31.F023 as shown in [Table 25](#) and [Table 26](#). For each LED if the condition selected by bits 12:8 is true the LED will blink. If the condition selected by bits 7:3 is true, then the LED will be solid on. If both selected conditions are true, then the blink will take precedence.

3.9.5 Speed Blink

When 31.F020.7:3 is set to 11111, the LED[0] pin assumes the following behavior:

- LED[0] outputs the sequence shown in [Table 27](#) depending on the status of the link. The sequence consists of 10 segments.
- For a 10 Gbps link, 4 pulses are output.
- For a 1000 Mbps link, 3 pulses are output.
- For a 100 Mbps link, 2 pulses are output.
- For a 10 Mbps link, 1 pulse is output.
- No link outputs 0 pulses.
- The sequence repeats indefinitely.
- The odd-numbered segment pulse duration is specified in 31.F027.1:0. The even-numbered segment pulse duration is specified in 31.F027.3:2.

Table 27: Speed Blinking Sequence

| Segment | 10 Mbps | 100 Mbps | 1 Gbps | 10 Gbps | No Link | Duration |
|---------|---------|----------|--------|---------|---------|-------------|
| 1 | On | On | On | On | Off | 31.F027.3:2 |
| 2 | Off | Off | Off | Off | Off | 31.F027.1:0 |
| 3 | Off | On | On | On | Off | 31.F027.3:2 |
| 4 | Off | Off | Off | Off | Off | 31.F027.1:0 |
| 5 | Off | Off | On | On | Off | 31.F027.3:2 |
| 6 | Off | Off | Off | Off | Off | 31.F027.1:0 |

Table 27: Speed Blinking Sequence (Continued)

| Segment | 10 Mbps | 100 Mbps | 1 Gbps | 10 Gbps | No Link | Duration |
|---------|---------|----------|--------|---------|---------|-------------|
| 7 | Off | Off | Off | On | Off | 31.F027.3:2 |
| 8 | Off | Off | Off | Off | Off | 31.F027.1:0 |
| 9 | Off | Off | Off | Off | Off | 31.F027.3:2 |
| 10 | Off | Off | Off | Off | Off | 31.F027.1:0 |

3.9.6 Combo LED Modes

Combo LED mode is activated when register 31.F024.15 is set to 1.

3.9.6.1 Combo LED Mode Select

There are five Combo LED modes which are set by 31.F024.14:12 as described in [Table 28](#).

Table 28: Combo LED Modes

| Combo LED Mode | Function | | | | | |
|---|--|--------------------------------|------------------|---|-----------|---|
| Combo LED Mode 1 (31.F02414:12 = 000) | Link Down | Link up and no activity | | Link up and activity | | Faulty link (including crc error, alignment, runt and jabber errors) |
| LED0 | Off | Solid green | | Flashing green (rate determined by number of packets) | | When TIMER_A is high, LED0 is on and green LED1 is off; when TIMER_A is low, LED0 is off, LED1 is on and amber. |
| LED1 | Off | Off | | Off | | Default = TIMER_A on for 0.5s off for 0.5s |
| Combo LED Mode 2 (31.F02414:12 = 001) | CRC Error | Alignment | | Runt | | Jabber |
| LED0 | LED0 is green when TIMER_B is high, default = LED0 high for 168 ms, LED1 low for 168 ms. | | | | | |
| LED1 | LED1 amber is on when TIMER_B is low. | | | | | |
| Combo LED Mode 3 (31.F02414:12 = 010) | STP¹ blocked/disabled | | | | | |
| LED0 | Off | | | | | |
| LED1 | On (solid amber) | | | | | |
| Combo LED Mode 4 (31.F02414:12 = 011) | STP is blocked, but is it still receiving/sending data. | | | | | |
| LED0 | Off | | | | | |
| LED1 | On/Off as per TIMER_D (flashing amber), default = 41 ms on and 41 ms off | | | | | |
| Combo LED Mode 5 (31.F02414:12 = 100) | 10 Mbps | 100 Mbps | 1000 Mbps | 2.5G | 5G | |

Table 28: Combo LED Modes (Continued)

| Combo LED Mode | Function | | | | | |
|----------------|----------|-----|---|--|--|--|
| LED0 | Off | On | On 5% (105 ms) Off 95% (1895 ms) Rate = TIMER_1G | On 10% (210 ms) Off 90% (1790 ms) Rate = TIMER_2.5G | On 20% (420 ms) Off 80% (1580 ms) Rate = TIMER_5G | |
| LED1 | Off | Off | Off | Off | Off | |

- Spanning Tree Protocol

Table 29: Combo Mode Timer Control

| Mode | Rate | Setting |
|------|---|--|
| 1 | When the link is up, the flashing rate is based on the number of frames received within 2 ms. | Refer to Table 30 for flashing rate setup. |
| 1 | Faulty Link | TIMER_A = 31.F024.7:0 |
| 2 | CRC, alignment, Runt, and Jabber Errors | TIMER_B = 31.F029.15:8 |
| 4 | STP is blocked, but it still receiving/sending data. | TIMER_D = 31.F039.7:0 |
| 5 | 1G | TIMER_1G = 31.F028.7:0 |
| | 2.5G | TIMER_2.5G = 31.F028.15:8 |
| | 5G | TIMER_5G = 31.F029.7:0 |

3.9.6.2 LED Activity Control

When the Combo LED Mode Selection bits (31.F024.14:12) are set to 000 and the link is up, the flash/blink activity of LED0 indicates the number of frames received within the last 2.1 seconds. Activity flashing of the LED is based on the transmitted and received frames on a link. Register 31.F026.11:10 is used to monitor transmit (31.F026.11:10 = 00) or receive (31.F026.11:10 = 01) or both (31.F026.11:10 = 11) at the same time.

LED0 can flash in two different ways:

- When Combo LED flash bit is set to 0, the more packets received within the previous 2100 ms, the longer LED0 stays on.
- When Combo LED flash bit is set to 1, the more packets received within the previous 2100 ms, the faster LED0 blinks.

The Combo LED flash rate details are listed in [Table 30](#).

Table 30: Combo LED Flash Mode

| Combo LED Flash (31.F024.11) | Flash Rate |
|------------------------------|---|
| 0 | <p><10: on for 31.F030[7:0], the remaining of 2.1s off; <10²: on for 31.F030[15:8], the remaining of 2.1s off; <5*10²: on for 31.F031[7:0], the remaining of 2.1s off; <10³: on for 31.F031[15:8], the remaining of 2.1s off; <5*10³: on for 31.F032[7:0], the remaining of 2.1s off; <10⁴: on for 31.F032[15:8], the remaining of 2.1s off; <5*10⁴: on for 31.F033[7:0], the remaining of 2.1s off; <10⁵: on for 31.F033[15:8], the remaining of 2.1s off; <5*10⁵: on for 31.F034[7:0], the remaining of 2.1s off; <10⁶: on for 31.F034[15:8], the remaining of 2.1s off; <5*10⁶: on for 31.F035[7:0], the remaining of 2.1s off; <10⁷: on for 31.F035[15:8], the remaining of 2.1s off</p> <p>NOTE: For registers 31.F030, 31.F031, 31.F032, 31.F033, 31.F034, and 31.F035, the unit of bit[7:0] and [15:8] is 21 ms. Any value greater than 8'd100 will be ignored.</p> |
| 1 | <p><10: LED on/off every 1/2 of 2.1s; <10²: LED on/off every 1/4 of 2.1s; <5*10²: LED on/off every 1/8 of 2.1s; <10³: LED on/off every 1/16 of 2.1s; <5*10³: LED on/off 1/32 of 2.1s; <10⁴: LED on/off 1/64 of 2.1s; <5*10⁴: LED on/off 1/128 of 2.1s; <10⁵: LED on/off 1/256 of 2.1s; <5*10⁵: LED on/off 1/512 of 2.1s; <10⁶: LED on/off 1/1024 of 2.1s; <5*10⁶: LED on/off 1/2048 of 2.1s; <10⁷: LED on/off 1/4096 of 2.1s</p> |

For example:

When the number of frames received within 2.1 seconds is 4000, in the following 2.1 seconds, the LED will behave as follows:

- If 31.F024.11 = 0, then LED0 will be on for 31.F031[7:0] * 21 ms, and off for (100 - 31.F031[7:0]) * 21 ms.
- If 31.F024.11 = 1, then LED0 will on for 1/32 * 2100 ms and off for 1/32 * 2100 ms repeatedly for 2.1 seconds.

3.10 Interrupt

The T, H, and P Units and the GPIO function can generate interrupts.

The Unit Interrupt Status Register (see 31.F040) shows a summary of which unit is requesting the interrupt.

Each bit of the Unit Interrupt Status Register will be masked with the Unit Interrupt Mask Register (see 31.F043) respectively, and each masked output is ORed to form the aggregated unit interrupt.

The Port Interrupt Status (see 31.F042.0) is the result of logical OR of the aggregated unit interrupt request along with register 31.F041.0 (see Force Interrupt bit) to form the port interrupt. When the bit is 1, the INTn will be driven as an active interrupt exists. The INTn's polarity is controlled by 31.F041.2:0.

In case of multiple port devices such as 88E2040L, INTn is active when one or more ports have the active Port Interrupt. There is no aggregated interrupt register for all ports. So, the Port Interrupt bit (see 31.F042.0) for all ports should be examined to determine which port or how many ports have pending interrupt requests.

The Interrupt Polarity bits (see 31.F041.2:1) for the INTn pin are valid only from Port 0. Other port's Polarity control bit are not valid; however, setting register 31.F041.0 in any port will force the INTn pin as active.

3.11 IEEE 1149.1 and 1149.6 Controller

The IEEE 1149.1 standard defines a test access port and boundary-scan architecture for digital integrated circuits and for the digital portions of mixed analog/digital integrated circuits. The IEEE 1149.6 standard defines a test access port and boundary-scan architecture for AC-coupled signals.

This standard provides a solution for testing assembled printed circuit boards and other products based on highly complex digital integrated circuits and high-density surface-mounting assembly techniques.

The device implements the instructions shown in [Table 31](#). Upon reset, ID_CODE instruction is selected. The PROG_HYST is a proprietary command used to adjust the test receiver hysteresis threshold. The instruction opcodes are shown in [Table 31](#).

[Table 32](#) and [Table 34](#) list the 88E2010 and 88E2040L device boundary scan orders, respectively, where:

TDI → P0_SON/P[0] (AC/DC) → ... → SPI_SSn(Output) → TDO

Table 31: TAP Controller Opcodes

| Instruction | OpCode |
|----------------|----------|
| EXTEST | 00000000 |
| SAMPLE/PRELOAD | 00000001 |
| CLAMP | 00000010 |
| HIGH-Z | 00000011 |
| ID_CODE | 00000100 |
| EXTEST_PULSE | 00000101 |
| EXTEST_TRAIN | 00000110 |
| PROG_HYST | 00001000 |
| BYPASS | 11111111 |

The device reserves five pins called the Test Access Port (TAP) to provide test access:

- Test Mode Select Input (TMS)
- Test Clock Input (TCK)
- Test Data Input (TDI)
- Test Data Output (TDO)
- Test Reset Input (TRSTn)

To ensure race-free operation, all input and output data is synchronous with the test clock (TCK). TAP input signals (TMS and TDI) are clocked into the test logic on the rising edge of TCK, while output signal (TDO) is clocked on the falling edge. For additional details, refer to the IEEE 1149.1 Boundary Scan Architecture document.

3.11.1 BYPASS Instruction

The BYPASS instruction uses the bypass register. This register contains a single shift-register stage and is used to provide a minimum length serial path between the TDI and TDO pins of the device when test operation is not required. This arrangement allows rapid movement of test data to and from other testable devices in the system.

3.11.2 **SAMPLE/PRELOAD Instruction**

The SAMPLE/PRELOAD instruction enables scanning of the boundary-scan register without causing interference to the normal operation of the device. Two functions are performed when this instruction is selected: SAMPLE and PRELOAD.

SAMPLE allows a snapshot to be taken of the data flowing from the system pins to the on-chip test logic or vice versa, without interfering with normal operation. The snapshot is taken on the rising edge of TCK in the Capture-DR controller state, and the data can be viewed by shifting through the component's TDO output.

While sampling and shifting data out through TDO for observation, PRELOAD enables an initial data pattern to be shifted in through TDI and to be placed at the latched parallel output of the boundary-scan register cells that are connected to system output pins. This step ensures that known data is driven through the system output pins upon entering the extest instruction. Without PRELOAD, indeterminate data would be driven until the first scan sequence is complete. The shifting of data for the sample and preload phases can occur simultaneously. While data capture is being shifted out, the preload data can be shifted in.

Table 32: 88X2010 Boundary Scan Chain Order

| Order | Pin | I/O |
|-------|-----------|---------------|
| 1 | SPI_SSn | Output |
| 2 | SPI_SSn | Output Enable |
| 3 | SPI_CLK | Output |
| 4 | SPI_CLK | Output Enable |
| 5 | SPI_MOSI | Output |
| 6 | SPI_MOSI | Output Enable |
| 7 | SPI_MISO | Input |
| 8 | RESETn | Input |
| 9 | RCLK1 | Output |
| 10 | RCLK1 | Output Enable |
| 11 | RCLK0 | Output |
| 12 | RCLK0 | Output Enable |
| 13 | CONFIG[7] | Input |
| 14 | CONFIG[6] | Input |
| 15 | CONFIG[5] | Input |
| 16 | CONFIG[4] | Input |
| 17 | CONFIG[3] | Input |
| 18 | CONFIG[2] | Input |
| 19 | CONFIG[1] | Input |
| 20 | CONFIG[0] | Input |
| 21 | MDIO[0] | Input |
| 22 | MDIO[0] | Output |
| 23 | MDIO[0] | Output Enable |
| 24 | MDC[0] | Input |
| 25 | P0_LED[3] | Input |
| 26 | P0_LED[3] | Output |
| 27 | P0_LED[3] | Output Enable |
| 28 | P0_LED[2] | Input |
| 29 | P0_LED[2] | Output |

Table 32: 88X2010 Boundary Scan Chain Order (Continued)

| Order | Pin | I/O |
|-------|------------|---------------|
| 30 | P0_LED[2] | Output Enable |
| 31 | P0_LED[1] | Input |
| 32 | P0_LED[1] | Output |
| 33 | P0_LED[1] | Output Enable |
| 34 | P0_LED[0] | Input |
| 35 | P0_LED[0] | Output |
| 36 | P0_LED[0] | Output Enable |
| 37 | Reserved | Input |
| 38 | Reserved | Output |
| 39 | Reserved | Output Enable |
| 40 | Reserved | Input |
| 41 | Reserved | Output |
| 42 | Reserved | Output Enable |
| 43 | Reserved | Input |
| 44 | Reserved | Output |
| 45 | Reserved | Output Enable |
| 46 | Reserved | Input |
| 47 | Reserved | Output |
| 48 | Reserved | Output Enable |
| 49 | Reserved | Input |
| 50 | Reserved | Output |
| 51 | Reserved | Output Enable |
| 52 | Reserved | Input |
| 53 | Reserved | Output |
| 54 | Reserved | Output Enable |
| 55 | INTn | Output |
| 56 | INTn | Output Enable |
| 57 | CLK_SEL[1] | Input |

Table 32: 88X2010 Boundary Scan Chain Order (Continued)

| Order | Pin | I/O |
|-------|-------------------------|--------------|
| 58 | CLK_SEL[0] | Input |
| 59 | P0_SIN[3] | Input |
| 60 | P0_SIP[3] | Input |
| 61 | P0_SON[3]/ P0_SOP[3] | Output |
| 62 | P0_SON[3]/ P0_SOP[3] | AC/DC Select |
| 63 | P0_SIN[2] | Input |
| 64 | P0_SIP[2] | Input |
| 65 | P0_SON[2]/ P0_SOP[2] | Output |
| 66 | P0_SON[2]/ P0_SOP[2] | AC/DC Select |
| 67 | P0_SIN[1] | Input |
| 68 | P0_SIP[1] | Input |
| 69 | P0_SON[1]/ P0_SOP[1] | Output |
| 70 | P0_SON[1]/ P0_SOP[1] | AC/DC Select |
| 71 | P0_SIN[0] | Input |
| 72 | P0_SIP[0] | Input |
| 73 | P0_SON[0]/ P0_SOP[0] | Output |
| 74 | P0_SON[0]/ P0_SOP[0] | AC/DC Select |

Table 33: 88E2010 Boundary Scan Exclusion List

| Pin | I/O |
|-----------|--------|
| MDIN[0] | Analog |
| MDIN[1] | Analog |
| MDIN[2] | Analog |
| MDIN[3] | Analog |
| MDIP[0] | Analog |
| MDIP[1] | Analog |
| MDIP[2] | Analog |
| MDIP[3] | Analog |
| TSTCP | Analog |
| TSTCN | Analog |
| TEST_CLKP | Analog |
| TEST_CLKN | Analog |
| CMN | Analog |
| CMP | Analog |
| ATN | Analog |
| ATP | Analog |
| CIREF | Analog |
| SIREF | Analog |
| CLKP | Analog |
| CLKN | Analog |
| XTAL1 | Analog |
| XTAL2 | Analog |
| CHSDACP | Analog |
| CHSDACN | Analog |
| SHSDACP | Analog |
| SHSDACN | Analog |
| CTSTPT | Analog |
| STSTPT | Analog |
| TEST | Analog |

Table 33: 88E2010 Boundary Scan Exclusion List (Continued)

| Pin | I/O |
|---------|--------|
| VDDCTRL | Analog |
| TDI | JTAG |
| TDO | JTAG |
| TMS | JTAG |
| TCK | JTAG |
| TRSTn | JTAG |
| VSEL_L | Power |
| VSEL_M | Power |
| VSEL_R | Power |
| VSEL_T | Power |
| VHV | Power |
| AVDDL | Power |
| AVDDH | Power |
| AVDDT | Power |
| AVSSC | Power |
| AVSS | Power |
| VDDR09 | Power |
| AVDDS | Power |
| AVDDR | Power |
| AVDDC | Power |
| DVDD | Power |
| VDDOL | Power |
| VDDOM | Power |
| VDDOR | Power |
| VDDOT | Power |
| VSS | Power |

Table 34: 88E2040L Boundary Scan Chain Order

| Order | Pin | I/O |
|-------|---------------------|---------------|
| 1 | SPI_SS _n | Output |
| 2 | SPI_SS _n | Output Enable |
| 3 | SPI_CLK | Output |
| 4 | SPI_CLK | Output Enable |
| 5 | SPI_MOSI | Output |
| 6 | SPI_MOSI | Output Enable |
| 7 | SPI_MISO | Input |
| 8 | RESET _n | Input |
| 9 | RCLK1 | Output |
| 10 | RCLK1 | Output Enable |
| 11 | RCLK0 | Output |
| 12 | RCLK0 | Output Enable |
| 13 | CONFIG[7] | Input |
| 14 | CONFIG[6] | Input |
| 15 | CONFIG[5] | Input |
| 16 | CONFIG[4] | Input |
| 17 | CONFIG[3] | Input |
| 18 | CONFIG[2] | Input |
| 19 | CONFIG[1] | Input |
| 20 | CONFIG[0] | Input |
| 21 | MDIO[3] | Input |
| 22 | MDIO[3] | Output |
| 23 | MDIO[3] | Output Enable |
| 24 | MDC[3] | Input |
| 25 | P3_LED[3] | Input |
| 26 | P3_LED[3] | Output |
| 27 | P3_LED[3] | Output Enable |
| 28 | P3_LED[2] | Input |
| 29 | P3_LED[2] | Output |

Table 34: 88E2040L Boundary Scan Chain Order (Continued)

| Order | Pin | I/O |
|-------|-------------------------|---------------|
| 30 | P3_LED[2] | Output Enable |
| 31 | P3_LED[1] | Input |
| 32 | P3_LED[1] | Output |
| 33 | P3_LED[1] | Output Enable |
| 34 | P3_LED[0] | Input |
| 35 | P3_LED[0] | Output |
| 36 | P3_LED[0] | Output Enable |
| 37 | Reserved | Input |
| 38 | Reserved | Output |
| 39 | Reserved | Output Enable |
| 40 | Reserved | Input |
| 41 | Reserved | Output |
| 42 | Reserved | Output Enable |
| 43 | Reserved | Input |
| 44 | Reserved | Output |
| 45 | Reserved | Output Enable |
| 46 | P3_SIN[1] | Input |
| 47 | P3_SIP[1] | Input |
| 48 | P3_SON[1]/ P3_SOP[1] | Output |
| 49 | P3_SON[1]/ P3_SOP[1] | AC/DC Select |
| 50 | P3_SIN[0] | Input |
| 51 | P3_SIP[0] | Input |
| 52 | P3_SON[0]/ P3_SOP[0] | Output |
| 53 | P3_SON[0]/ P3_SOP[0] | AC/DC Select |
| 54 | MDIO[2] | Input |
| 55 | MDIO[2] | Output |
| 56 | MDIO[2] | Output Enable |

Table 34: 88E2040L Boundary Scan Chain Order (Continued)

| Order | Pin | I/O |
|-------|-------------------------|---------------|
| 57 | MDC[2] | Input |
| 58 | P2_LED[3] | Input |
| 59 | P2_LED[3] | Output |
| 60 | P2_LED[3] | Output Enable |
| 61 | P2_LED[2] | Input |
| 62 | P2_LED[2] | Output |
| 63 | P2_LED[2] | Output Enable |
| 64 | P2_LED[1] | Input |
| 65 | P2_LED[1] | Output |
| 66 | P2_LED[1] | Output Enable |
| 67 | P2_LED[0] | Input |
| 68 | P2_LED[0] | Output |
| 69 | P2_LED[0] | Output Enable |
| 70 | Reserved | Input |
| 71 | Reserved | Output |
| 72 | Reserved | Output Enable |
| 73 | Reserved | Input |
| 74 | Reserved | Output |
| 75 | Reserved | Output Enable |
| 76 | Reserved | Input |
| 77 | Reserved | Output |
| 78 | Reserved | Output Enable |
| 79 | P2_SIN[1] | Input |
| 80 | P2_SIP[1] | Input |
| 81 | P2_SON[1]/ P2_SOP[1] | Output |
| 82 | P2_SON[1]/ P2_SOP[1] | AC/DC Select |

Table 34: 88E2040L Boundary Scan Chain Order (Continued)

| Order | Pin | I/O |
|-------|-------------------------|---------------|
| 83 | P2_SIN[0] | Input |
| 84 | P2_SIP[0] | Input |
| 85 | P2_SON[0]/ P2_SOP[0] | Output |
| 86 | P2_SON[0]/ P2_SOP[0] | AC/DC Select |
| 87 | MDIO[1] | Input |
| 88 | MDIO[1] | Output |
| 89 | MDIO[1] | Output Enable |
| 90 | MDC[1] | Input |
| 91 | P1_LED[3] | Input |
| 92 | P1_LED[3] | Output |
| 93 | P1_LED[3] | Output Enable |
| 94 | P1_LED[2] | Input |
| 95 | P1_LED[2] | Output |
| 96 | P1_LED[2] | Output Enable |
| 97 | P1_LED[1] | Input |
| 98 | P1_LED[1] | Output |
| 99 | P1_LED[1] | Output Enable |
| 100 | P1_LED[0] | Input |
| 101 | P1_LED[0] | Output |
| 102 | P1_LED[0] | Output Enable |
| 103 | Reserved | Input |
| 104 | Reserved | Output |
| 105 | Reserved | Output Enable |
| 106 | Reserved | Input |
| 107 | Reserved | Output |
| 108 | Reserved | Output Enable |
| 109 | Reserved | Input |

Table 34: 88E2040L Boundary Scan Chain Order (Continued)

| Order | Pin | I/O |
|-------|-------------------------|---------------|
| 110 | Reserved | Output |
| 111 | Reserved | Output Enable |
| 112 | P1_SIN[1] | Input |
| 113 | P1_SIP[1] | Input |
| 114 | P1_SON[1]/ P1_SOP[1] | Output |
| 115 | P1_SON[1]/ P1_SOP[1] | AC/DC Select |
| 116 | P1_SIN[0] | Input |
| 117 | P1_SIP[0] | Input |
| 118 | P1_SON[0]/ P1_SOP[0] | Output |
| 119 | P1_SON[0]/ P1_SOP[0] | AC/DC Select |
| 120 | MDIO[0] | Input |
| 121 | MDIO[0] | Output |
| 122 | MDIO[0] | Output Enable |
| 123 | MDC[0] | Input |
| 124 | P0_LED[3] | Input |
| 125 | P0_LED[3] | Output |
| 126 | P0_LED[3] | Output Enable |
| 127 | P0_LED[2] | Input |
| 128 | P0_LED[2] | Output |
| 129 | P0_LED[2] | Output Enable |
| 130 | P0_LED[1] | Input |
| 131 | P0_LED[1] | Output |
| 132 | P0_LED[1] | Output Enable |
| 133 | P0_LED[0] | Input |
| 134 | P0_LED[0] | Output |
| 135 | P0_LED[0] | Output Enable |
| 136 | Reserved | Input |

Table 34: 88E2040L Boundary Scan Chain Order (Continued)

| Order | Pin | I/O |
|-------|-------------------------|---------------|
| 137 | Reserved | Output |
| 138 | Reserved | Output Enable |
| 139 | Reserved | Input |
| 140 | Reserved | Output |
| 141 | Reserved | Output Enable |
| 142 | Reserved | Input |
| 143 | Reserved | Output |
| 144 | Reserved | Output Enable |
| 145 | INTn | Output |
| 146 | INTn | Output Enable |
| 147 | CLK_SEL[1] | Input |
| 148 | CLK_SEL[0] | Input |
| 149 | P0_SIN[1] | Input |
| 150 | P0_SIP[1] | Input |
| 151 | P0_SON[1]/ P0_SOP[1] | Output |
| 152 | P0_SON[1]/ P0_SOP[1] | AC/DC Select |
| 153 | P0_SIN[0] | Input |
| 154 | P0_SIP[0] | Input |
| 155 | P0_SON[0]/ P0_SOP[0] | Output |
| 156 | P0_SON[0]/ P0_SOP[0] | AC/DC Select |

Table 35: 88E2040L Boundary Scan Exclusion List

| Pin | I/O |
|------------|--------|
| P0_MDIN[0] | Analog |
| P0_MDIN[1] | Analog |
| P0_MDIN[2] | Analog |
| P0_MDIN[3] | Analog |
| P0_MDIP[0] | Analog |
| P0_MDIP[1] | Analog |
| P0_MDIP[2] | Analog |
| P0_MDIP[3] | Analog |
| P1_MDIN[0] | Analog |
| P1_MDIN[1] | Analog |
| P1_MDIN[2] | Analog |
| P1_MDIN[3] | Analog |
| P1_MDIP[0] | Analog |
| P1_MDIP[1] | Analog |
| P1_MDIP[2] | Analog |
| P1_MDIP[3] | Analog |
| P2_MDIN[0] | Analog |
| P2_MDIN[1] | Analog |
| P2_MDIN[2] | Analog |
| P2_MDIN[3] | Analog |
| P2_MDIP[0] | Analog |
| P2_MDIP[1] | Analog |
| P2_MDIP[2] | Analog |
| P2_MDIP[3] | Analog |
| P3_MDIN[0] | Analog |
| P3_MDIN[1] | Analog |
| P3_MDIN[2] | Analog |
| P3_MDIN[3] | Analog |
| P3_MDIP[0] | Analog |

Table 35: 88E2040L Boundary Scan Exclusion List (Continued)

| Pin | I/O |
|------------|--------|
| P3_MDIP[1] | Analog |
| P3_MDIP[2] | Analog |
| P3_MDIP[3] | Analog |
| TSTCP | Analog |
| TSTCN | Analog |
| TEST_CLKN | Analog |
| TEST_CLKP | Analog |
| P0_CMN | Analog |
| P0_CMP | Analog |
| P1_CMN | Analog |
| P1_CMP | Analog |
| P2_CMN | Analog |
| P2_CMP | Analog |
| P3_CMN | Analog |
| P3_CMP | Analog |
| P0_ATN[1] | Analog |
| P0_ATN[1] | Analog |
| P0_ATN[2] | Analog |
| P0_ATN[3] | Analog |
| P0_ATP[0] | Analog |
| P0_ATP[1] | Analog |
| P0_ATP[2] | Analog |
| P0_ATP[3] | Analog |
| P1_ATN[0] | Analog |
| P1_ATN[1] | Analog |
| P1_ATN[2] | Analog |

Table 35: 88E2040L Boundary Scan Exclusion List (Continued)

| Pin | I/O |
|-----------|--------|
| P1_ATN[3] | Analog |
| P1_ATP[0] | Analog |
| P1_ATP[1] | Analog |
| P1_ATP[2] | Analog |
| P1_ATP[3] | Analog |
| P2_ATN[0] | Analog |
| P2_ATN[1] | Analog |
| P2_ATN[2] | Analog |
| P2_ATN[3] | Analog |
| P2_ATP[0] | Analog |
| P2_ATP[1] | Analog |
| P2_ATP[2] | Analog |
| P2_ATP[3] | Analog |
| P3_ATN[0] | Analog |
| P3_ATN[1] | Analog |
| P3_ATN[2] | Analog |
| P3_ATN[3] | Analog |
| P3_ATP[0] | Analog |
| P3_ATP[1] | Analog |
| P3_ATP[2] | Analog |
| P3_ATP[3] | Analog |
| CIREF | Analog |
| SIREF | Analog |
| CLKP | Analog |
| CLKN | Analog |
| XTAL1 | Analog |
| XTAL2 | Analog |

Table 35: 88E2040L Boundary Scan Exclusion List (Continued)

| Pin | I/O |
|----------|--------|
| CHSDACP | Analog |
| CHSDACN | Analog |
| SHSDACP | Analog |
| SHSDACN | Analog |
| CTSTPT | Analog |
| STSTPT | Analog |
| TEST | Analog |
| TDI | JTAG |
| TDO | JTAG |
| TMS | JTAG |
| TCK | JTAG |
| TRSTn | JTAG |
| VSEL_L | Power |
| VSEL_M | Power |
| VSEL_R | Power |
| VSEL_T | Power |
| P0_VHV | Power |
| P1_VHV | Power |
| P2_VHV | Power |
| P3_VHV | Power |
| P0_AVDDL | Power |
| P1_AVDDL | Power |
| P2_AVDDL | Power |
| P3_AVDDL | Power |
| P0_AVDDH | Power |
| P1_AVDDH | Power |
| P2_AVDDH | Power |
| P3_AVDDH | Power |

Table 35: 88E2040L Boundary Scan Exclusion List (Continued)

| Pin | I/O |
|-----------|-------|
| P0_AVDDT | Power |
| P1_AVDDT | Power |
| P2_AVDDT | Power |
| P3_AVDDT | Power |
| AVSSC | Power |
| AVSS | Power |
| P0_VDDR09 | Power |
| P1_VDDR09 | Power |
| P2_VDDR09 | Power |
| P3_VDDR09 | Power |
| P0_AVDDS | Power |
| P1_AVDDS | Power |
| P2_AVDDS | Power |
| P3_AVDDS | Power |
| P0_AVDDR | Power |
| P1_AVDDR | Power |
| P2_AVDDR | Power |
| P3_AVDDR | Power |
| AVDDC | Power |
| DVDD | Power |
| VDDOL | Power |
| VDDOM | Power |
| VDDOR | Power |
| VDDOT | Power |
| VSS | Power |

3.11.3 EXTEST Instruction

The EXTEST instruction enables circuitry external to the device (typically the board interconnections) to be tested. Prior to executing the EXTEST instruction, the first test stimulus to be applied is shifted into the boundary-scan registers using the SAMPLE/PRELOAD instruction. So, when the change to the extest instruction occurs, known data is driven immediately from the device to its external connections. The SOP/N[1:0] pins will be driven to static levels. The positive and negative legs of the SOP/N[1:0] pins are controlled via a single boundary scan cell. The positive leg outputs the level specified by the boundary scan cell while the negative leg outputs the opposite level.

3.11.4 CLAMP Instruction

The CLAMP instruction enables the state of the signals driven from component pins to be determined from the boundary-scan register while the bypass register is selected as the serial path between TDI and TDO. The signals driven from the component pins do not change while the clamp instruction is selected.

3.11.5 HIGH-Z Instruction

The HIGH-Z instruction places all of the digital component system logic outputs in an inactive high-impedance drive state. In this state, an in-circuit test system may drive signals onto the connections normally driven by a component output without incurring the risk of damage to the component.

3.11.6 ID CODE Instruction

The ID CODE instruction contains the manufacturer identity, part and version.

Table 36: ID CODE Instruction

| Device | Version | Part Number | Manufacturer Identity | |
|----------|--------------|------------------|-----------------------|-------|
| | Bit 31 to 28 | Bit 27 to 12 | Bit 11 to 1 | Bit 0 |
| 88E2010 | 0000 | 0000000000011001 | 00111101110 | 1 |
| 88E2040L | 0000 | 0000000000011011 | 00111101110 | 1 |

3.11.7 EXTEST_PULSE Instruction

The AC- or DC-JTAG test modes can be selected for each port individually by scanning in the desired bit value into AC/DC select scan registers shown in the scan chain ([Table 32, 88X2010 Boundary Scan Chain Order, on page 79](#) or [Table 34, 88E2040L Boundary Scan Chain Order, on page 82](#)). When the AC/DC select is set to DC the EXTEST_PULSE instruction has the same behavior as the EXTEST instruction.

When the AC/DC select is set to AC, the EXTEST_PULSE instruction has the same behavior as the EXTEST instruction except for the behavior of the SOP/N[1:0] pins.

As in the EXTEST instruction, the test stimulus must first be shifted into the boundary-scan registers. Upon the execution of the EXTEST_PULSE instruction the SOP[1:0] pins output the level specified by the test stimulus and SON[1:0] pins output the opposite level.

However, if the TAP controller enters into the Run-Test/Idle state, then the SON[1:0] pins output the level specified by the test stimulus and SOP[1:0] pins output the opposite level.

When the TAP controller exits the Run-Test/Idle state, the SOP[1:0] pins again output the level specified by the test stimulus and SON[1:0] pins output the opposite level.

3.11.7.1 EXTEST_TRAIN Instruction

When the AC/DC select is set to DC, the EXTEST_TRAIN instruction has the same behavior as the EXTEST instruction.

When the AC/DC select is set to AC, the EXTEST_TRAIN instruction has the same behavior as the EXTEST instruction except for the behavior of the SOP/N[1:0] pins.

As in the EXTEST instruction, the test stimulus must first be shifted into the boundary-scan registers. Upon the execution of the EXTEST_PULSE instruction the SOP[1:0] pins output the level specified by the test stimulus and SON[1:0] pins output the opposite level.

However, if the TAP controller enters into the Run-Test/Idle state the SOP/N[1:0] will toggle between inverted and non-inverted levels on the falling edge of TCK. This toggling will continue for as long as the TAP controller remains in the Run-Test/Idle state.

When the TAP controller exits the Run-Test/Idle state, the SOP[1:0] pins again output the level specified by the test stimulus and SON[1:0] pins output the opposite level.

3.11.8 PROG_HYST Instruction

The test receivers connected to the XIP/N[3:0] and MIP/N[3:0] pins require the hysteresis level to be set according to the application that the SERDES is used in. The amount of hysteresis required is a function of the expected voltage swing on the input. The proprietary command PROG_HYST will program three registers in the TAP controller which will set the value of the hysteresis.

When the PROG_HYST opcode is in the instruction register, the following actions occur in the TAP controller states:

- Capture-DR state: Load the value in HYST[2:0] into SR_HYST[2:0].
- Shift-DR state: Shift TDI into SR_HYST[0], SR_HYST[1:0] into SR_HYST[2:1], and SR_HYST[2] to TDO. Three bits should be loaded to set the new test receiver hysteresis value.
- Update-DR state: Load the value in SR_HYST[2:0] into HYST[2:0].
- HYST[2:0] is the register that sets the hysteresis in the test receiver.
- SR_HYST[2:0] is the 3-bit shift register used to shift the values in and out.

The hysteresis mapping is shown in [Table 37](#). 70 mV is the default setting. When the TAP controller is in the Test-Logic-Reset state or when TRSTn is forced low, the HYST[2:0] is reset to the default state

Table 37: Test Receiver Hysteresis Setting

| HYST[2:0] | Hysteresis |
|-----------|------------|
| 000 | 12 mV |
| 001 | 25 mV |
| 010 | 50 mV |
| 011 | 70 mV |
| 100 | 90 mV |
| 101 | 105 mV |
| 110 | 135 mV |
| 111 | 150 mV |

3.11.9 AC-JTAG Fault Detection

The fault detection across AC-coupled connections can be detected with a combination of (DC) EXTEST and any one of the AC-JTAG commands. The AC-coupled connection is shown in Figure 14. The fault signature is shown in Table 38. Column 1 lists the fault type.

Columns 2 to 5 lists the behavior when both the transmitter and receiver are running the EXTEST_TRAIN and EXTEST_PULSE commands. Column 2 shows the expected value captured by the boundary scan cell that is connected to the test receiver, which is connected to the positive input when a negative differential pulse is transmitted. Column 3 is the same as column 2 except for the negative input. Columns 4 and 5 are similar to columns 2 and 3 except a positive differential pulse is transmitted.

Columns 6 to 9 is similar to columns 2 to 5 except both the transmitter and receiver are running the (DC) EXTEST command.

While it is not possible to identify precisely which fault is occurring based on the fault signature, the signature to the no fault condition is unique when the (DC) EXTEST command is run with at least one of the EXTEST_TRAIN or EXTEST_PULSE commands. Running only AC-JTAG commands is not sufficient since the no fault condition signature is not distinguishable from the Tx to Rx short (see shaded cells in Table 38).

Figure 14: AC-Coupled Connection

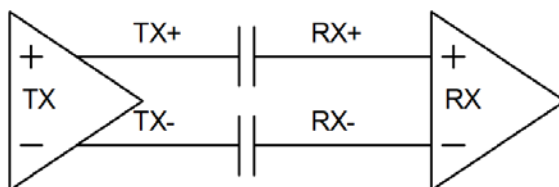


Table 38: AC-Coupled Connection Fault Signature

| DC-Coupled Fault | AC Testing Sample 0 | | AC Testing Sample 1 | | (DC) EXTEST Sample 0 | | (DC) EXTEST Sample 1 | |
|---------------------|---------------------|--------------|---------------------|--------------|----------------------|--------------|----------------------|--------------|
| | Positive Leg | Negative Leg | Positive Leg | Negative Leg | Positive Leg | Negative Leg | Positive Leg | Negative Leg |
| TX+ Open | 0 | X | 0 | X | 1 | X | 1 | X |
| TX- Open | X | 0 | X | 0 | X | 1 | X | 1 |
| RX+ Open | 0 | X | 0 | X | 1 | X | 1 | X |
| RX- Open | X | 0 | X | 0 | X | 1 | X | 1 |
| TX+ short to power | 0/Note 2 | X | 0/Note 2 | X | 1 | X | 1 | X |
| TX- short to power | X | 0/Note 2 | X | 0/Note 2 | X | 1 | X | 1 |
| RX+ short to power | 0/Note 2 | X | 0/Note 2 | X | 1 | X | 1 | X |
| RX- short to power | X | 0/Note 2 | X | 0/Note 2 | X | 1 | X | 1 |
| TX+ short to ground | 0 | X | 0 | X | 1 | X | 1 | X |

Table 38: AC-Coupled Connection Fault Signature (Continued)

| DC-Coupled Fault | AC Testing Sample 0 | | AC Testing Sample 1 | | (DC) EXTEST Sample 0 | | (DC) EXTEST Sample 1 | |
|---------------------|--|--------------|---------------------|--------------|----------------------|--------------|----------------------|--------------|
| | Positive Leg | Negative Leg | Positive Leg | Negative Leg | Positive Leg | Negative Leg | Positive Leg | Negative Leg |
| TX- short to ground | X | 0 | X | 0 | X | 1 | X | 1 |
| RX+ short to ground | 0 | X | 0 | X | 0 | X | 0 | X |
| RX- short to ground | X | 0 | X | 0 | X | 0 | X | 0 |
| TX+ short to TX- | Note 1 | Note 1 | Note 1 | Note 1 | 1 | 1 | 1 | 1 |
| RX+ short to RX- | Note 1 | Note 1 | Note 1 | Note 1 | 1 | 1 | 1 | 1 |
| TX+ short to RX- | X | 0 | X | 1 | X | 0 | X | 1 |
| TX- short to RX+ | 1 | X | 0 | X | 1 | X | 0 | X |
| TX+ short to RX+ | 0 | X | 1 | X | 0 | X | 1 | X |
| TX- short to RX- | X | 1 | X | 0 | X | 1 | X | 0 |
| No Fault | 0 | 1 | 1 | 0 | 1 | 1 | 1 | 1 |
| Note 1 | Short on positive and negative leg can have several behavior on the test receiver. If both drivers cancel each other out, then output on both legs is 0. If one driver dominates the other driver, then both legs are either both 1 or both 0. In any case, the result is that both legs will have the same value. | | | | | | | |
| Note 2 | A solid short to power is assumed. If the short has high inductance, then a pulse may still be sent at the receiver and will be mistaken as a good connection. | | | | | | | |

The fault detection across DC-coupled connections can be detected with any one of the AC-JTAG or (DC) EXTEST commands. The DC-coupled connection is shown in [Figure 15](#). The fault signature is shown in [Table 39](#).

Figure 15: DC-Coupled Connection

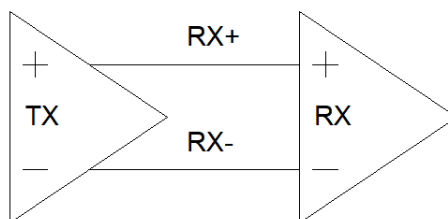




Table 39: DC-Coupled Connection Fault Signature

| DC-Coupled Fault | AC Testing Sample 0 | | AC Testing Sample 1 | | (DC) EXTEST Sample 0 | | (DC) EXTEST Sample 1 | |
|---------------------|---|--------------|---------------------|--------------|----------------------|--------------|----------------------|--------------|
| | Positive Leg | Negative Leg | Positive Leg | Negative Leg | Positive Leg | Negative Leg | Positive Leg | Negative Leg |
| RX+ Open | 0 | X | 0 | X | 1 | X | 1 | X |
| RX- Open | X | 0 | X | 0 | X | 1 | X | 1 |
| RX+ short to power | 0/Note 2 | X | 0/Note 2 | X | 1 | X | 1 | X |
| RX- short to power | X | 0/Note 2 | X | 0/Note 2 | X | 1 | X | 1 |
| RX+ short to ground | 0 | X | 0 | X | 0 | X | 0 | X |
| RX- short to ground | X | 0 | X | 0 | X | 0 | X | 0 |
| RX+ short to RX- | Note 1 | Note 1 | Note 1 | Note 1 | Note 1 | Note 1 | Note 1 | Note 1 |
| No Fault | 0 | 1 | 1 | 0 | 0 | 1 | 1 | 0 |
| Note 1 | Short on positive and negative leg can have several behaviors on the test receiver. If both drivers cancel each other out, then output on both legs is 0. If one driver dominates the other driver, then both legs are either both 1 or both 0. In any case, the result is that both legs will have the same value. | | | | | | | |
| Note 2 | A solid short to power is assumed. If the short has high inductance, then a pulse may still be sent at the receiver and will be mistaken as a good connection. | | | | | | | |

3.12 Reference Clock

The 88E2010/88E2040L device can use a 50 MHz or 156.25 MHz differential clock into CLKP/N or a 50 MHz crystal as the reference clock.

The device can use one of three clocking options as shown in [Table 40](#). CLK_SEL must be stable and the selected clock toggling prior to de-assertion of RESETn. CLK_SEL must not change value for the duration of device operation.

Table 40: Reference Clock Options

| CLK_SEL[1:0] | XTAL1/XTAL2 | CLKP/CLKN |
|--------------|-------------|------------|
| 00 | 50 MHz | Floating |
| 01 | GND | 50 MHz |
| 10 | GND | 156.25 MHz |
| 11 | Reserved | Reserved |



Note

50 MHz crystal operation is only supported for commercial-grade devices.

3.13 Power Supplies

The 88E2010/88E2040L device requires the following power supplies: AVDDT, AVDDL, AVDDH, DVDD, and VDDO.

3.13.1 AVDDL

AVDDL is the copper transmitter and receiver 1.5V analog supply.

3.13.2 AVDDH

AVDDH is the copper transmitter and receiver 1.8V or 2.0V analog supply.

3.13.3 AVDDT

AVDDT is the copper transmitter 2.3V or 2.5V analog supply.

3.13.4 AVDDC

AVDDC is the common analog supply of 1.5V.

3.13.5 AVDDS

AVDDS is the SERDES analog supply of 1.5V.

3.13.6 AVDDR

AVDDR is the regulator supply and should be tied to 1.5V.

3.13.7 DVDD

DVDD is the core logic 0.8V or 0.88V digital supply. (0.88V for I-grade only)

3.13.8 VDDO

There are four separate VDDO segments (VDDOT, VDDOR, VDDOL, and VDDOM). Each segment can be independently set to one for the following voltages: 1.5V, 1.8V, 2.5V, or 3.3V, except VDDOM that can also support 1.2V. Each VDDO segment has a corresponding voltage select configuration pin (VSEL_T, VSEL_R, VSEL_L, and VSEL_M). [Table 41](#) lists the signals under each of the VDDO segments.

If the VDDO* segment is set to 1.2V, 1.5V, or 1.8V, then its corresponding VSEL_* should be tied to VDDO*.

If the VDDO* segment is set to 2.5V, or 3.3V, then its corresponding VSEL_* should be tied to VSS.

The input pins are not high voltage tolerant. For example, if VDDOR is tied to 2.5V, then RESETn should not be driven to 3.3V.

Table 41: Signal Power Segment

| Power Segment | VDDOT | VDDOR | VDDOL | VDDOM |
|----------------|--------|-----------|--------------|-----------|
| Voltage Select | VSEL_T | VSEL_R | VSEL_L | VSEL_M |
| Signals | TCK | GPIO[x:0] | CLK_SEL[1:0] | INTn |
| | TDI | RCLK0 | CONFIG[7:0] | MDC[x:0] |
| | TDO | RCLK1 | LED0[3:0] | MDIO[x:0] |
| | TMS | RESETn | | TEST |
| | TRST | SPI_CLK | | |
| | | SPI_MOS0 | | |
| | | SPI_MOS1 | | |
| | | SPI_SSn | | |

3.13.9 VHV

The VHV pin is a test pin and should be left floating during normal operation.

3.13.10 VDD09

VDD09 is the 0.9V internally generated regulated output and these pins should be tied to an external 0.22 μ F capacitor to VSS.

4 Copper Unit (T Unit)

This section describes the copper unit (T Unit) interface functions.

4.1 Media Interface

The copper interface consists of the MDIP/N[3:0] pins that connect to the physical media for 5GBASE-T, 2.5GBASE-T, 1000BASE-T, 100BASE-TX, and 10BASE-T modes of operation.

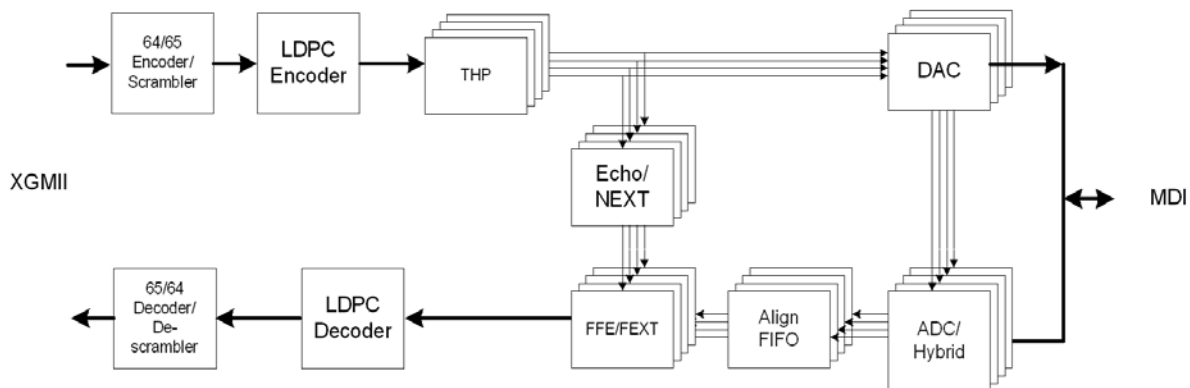
The device integrates MDI interface termination resistors. The IEEE 802.3 specification requires that both sides of a link have termination resistors to prevent reflections. Traditionally, these resistors and additional capacitors are placed on the board between a PHY device and the magnetics. The resistors must be very accurate to meet the strict IEEE return loss requirements. Typically, $\pm 1\%$ accuracy resistors are used on the board. These additional components between the PHY and the magnetics complicate board layout. Integrating the resistors has many advantages including component cost savings, better ICT yield, board reliability improvements, board area savings, improved layout, and signal integrity improvements. See the *Benefits of Integrating Termination Resistors for Ethernet Application Note* for details.

The transmitter can be shut down in all operational speeds by setting register 3.8109.0 to 1 in 10M/100M/1G operation and register 1.0009.0 to 1 for 2.5G/5G operation.

Each channel's transmitter's polarity can be reversed by setting the corresponding bit in register 3.8001.3:0 to 1 in 10M/100M/1G operation. Channel transmitter polarity reversal is not supported for 2.5G/5G operation. The devices support Auto-MDI/MDIX to automatically switch to the proper configuration when a cable is connected.

4.1.1 2.5GBASE-T and 5GBASE-T

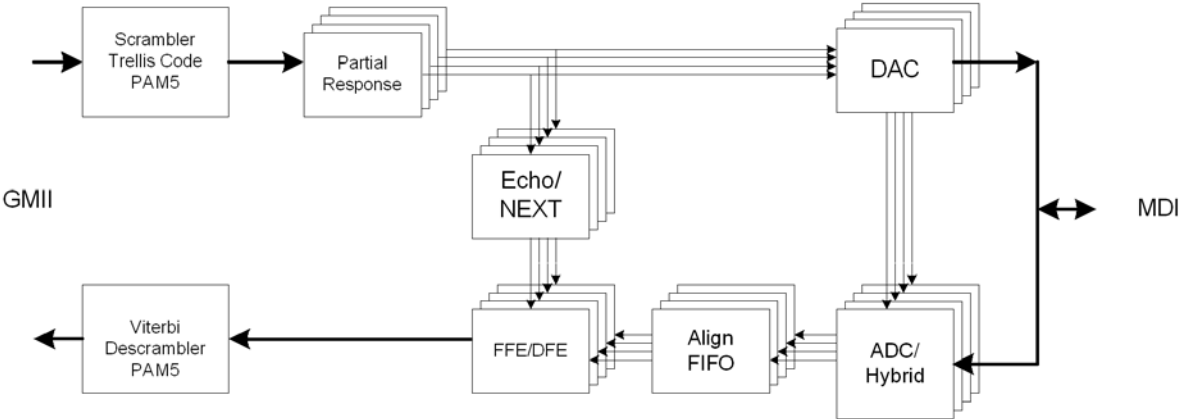
Figure 16: 2.5GBASE-T and 5GBASE-T Data Path



The device performs all the physical layer functions of 2.5GBASE-T and 5GBASE-T over a CAT 5e, 6A, and 7 cable system. The device performs scrambling, LDPC coding, PAM16 mapping, and THP pre-coding on the transmit side with adaptive equalization, full echo cancellation, decoding and de-scrambling on the receive side. It is fully compliant to the IEEE 802.3 standard, including the PMA and PCS sublayers for full physical layer functionality.

4.1.2 1000BASE-T

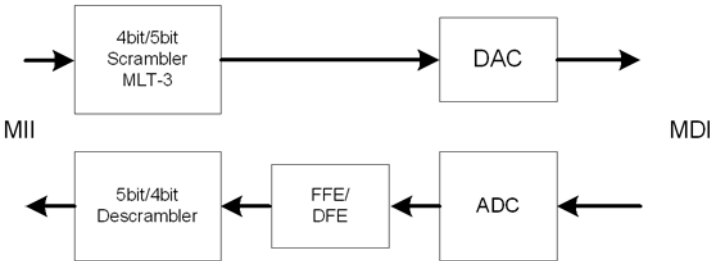
Figure 17: 1000BASE-T Data Path



The device performs all the physical layer functions of 1000BASE-T full or half duplex on twisted pair CAT 5, 6, and 7 cable. It is fully compliant to the IEEE 802.3 standard, including the PMD, PMA, and PCS sublayers. The device, for 1000BASE-T, performs scrambling, Trellis coding, PAM5 mapping functions on the transmit side with adaptive equalization, echo cancellation, viterbi decoding and de-scrambling on the receive side.

4.1.3 100BASE-TX

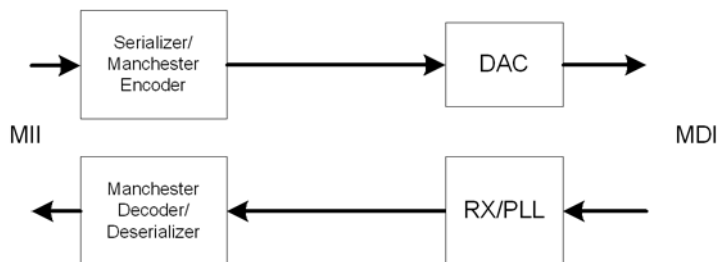
Figure 18: 100BASE-TX Data Path



The device performs all the physical layer functions of 100BASE-TX full or half duplex on twisted pair CAT 5, 6, and 7 cable. It is fully compliant to the IEEE 802.3 standard, including the PMD, PMA, and PCS sublayers. The device supports Auto-MDI/MDIX to automatically switch to the proper configuration once a cable is connected. As mentioned, the device also integrates the PHY termination resistors enabling BOM material and cost savings, ease of board layout, and bettered signal integrity.

4.1.4 10BASE-T

Figure 19: 10BASE-T Data Path



The device additionally performs all the physical layer functions of 10BASE-T full or half duplex on twisted pair cable. It is compliant to the IEEE 802.3 standard, including the PMD, PMA, and PCS sublayers.

4.1.5 Taking Down the Link

4.1.5.1 Taking Down the Link in 5GBASE-T/2.5GBASE-T Modes

When the link is established, the link monitor algorithm will detect conditions where a retrain is required, such as the link partner has dropped the link or the link quality has dropped below acceptable levels.

The PHY supports fast retrain defined for 2.5G/5GBASE-T in IEEE 802.3bz-2016. The PHY also supports a Negotiated Fast Retrain defined for pre-standard devices. If the local device and the link partner have negotiated fast retrain support and the link quality has dropped below operating conditions, then the PHY will enter fast retrain in coordination with the link partner and return to normal operation within the defined fast retrain duration. If the PHY fails to achieve acceptable link quality or the fast retrain process fails, then the PHY will drop the link and return to normal training.

When fast retrain is not negotiated and the link quality has dropped below operating conditions, the PHY will perform a retrain as defined in IEEE Std. 802.3an-2006. Upon a failure to retrain, the PHY will return to Auto-Negotiation.

4.1.5.2 Taking Down the Link in 1000BASE-T Mode

The link is established when both sides so indicate. Each side continues sending idle symbols whenever it has no data to transmit. The link is maintained as long as valid idle, data, or carrier extension symbols are received.

4.1.5.3 Taking Down the Link in 100BASE-TX Mode

For 100BASE-TX links, the PHY devices and its link partner begin transmitting idle symbols after completion of the Auto-Negotiation process. Each side continues sending idle symbols whenever it has no data to transmit. The link is maintained as long as valid idle symbols or data are received.

The PHY devices take down an established link when the required conditions are no longer met. When a link is down, data transmission stops.

For 100BASE-TX and 1000BASE-T links, taking down a link occurs after valid idle codes are no longer received. After the link is down, if Auto-Negotiation is enabled, then the PHY devices reenter the Auto-Negotiation phase and begin transmitting FLPs.

4.2 Loopback

The T Unit implements multiple loopback paths.

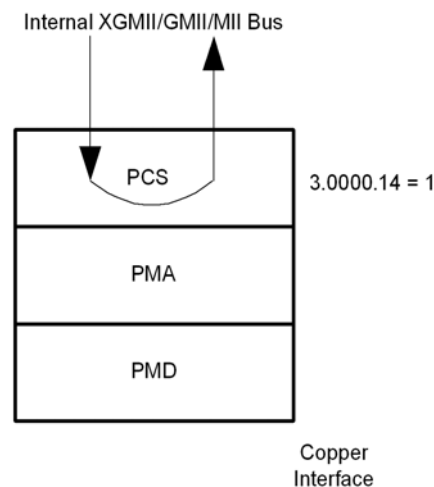
4.2.1 MAC Loopback

The T Unit can loop back data from the internal XGMII/GMII/MII bus by setting register 3.0000.14 to 1 for all modes. In 10/100/1000 loopback mode, the data received from the internal GMII/MII bus is not transmitted on the media interface and the link will be dropped. In 2.5G/5G loopback mode, the link will remain active and data from the internal XGMII bus will be transmitted on to the media interface.

If Auto-Negotiation and loopback are enabled, then FLP Auto-Negotiation codes will be transmitted. If the T Unit is in forced 10BASE-T mode and loopback is enabled, then 10BASE-T idle link pulses will be transmitted on the media interface. If the T Unit is in forced 100BASE-T mode and loopback is enabled, then 100BASE-T idles will be transmitted on the media interface.

When MAC loopback is enabled, the loopback speed will be the active link speed of the T Unit. If the link is down, then the loopback speed will be determined by register 31.F000.7:6.

Figure 20: MAC Interface Loopback Diagram — Copper Media Interface



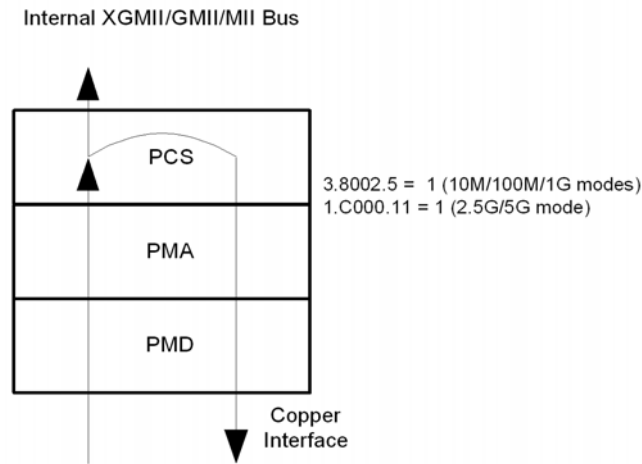
4.2.2 Line Loopback

Line loopback allows a link partner to send frames into the media interface to test the transmit and receive data paths. Frames from a link partner into the PHY bus are looped back and sent out on the line before reaching the internal XGMII/GMII/MII. They are also sent to the internal XGMII/GMII/MII bus. The packets received from the internal XGMII/GMII/MII bus are ignored during line loopback. This allows the link partner to receive its own frames.

Before enabling the line loopback feature, the PHY must first establish link to another PHY link partner. If Auto-Negotiation is enabled, then both link partners should advertise the same speed and full duplex. If Auto-Negotiation is disabled, then both link partners must be forced to the same speed and full duplex. When link is established, the line loopback mode can be enabled setting register 3.8002.5 to 1 for 10M/100M/1G modes and 1.C000.11 to 1 for 2.5G/5G mode.

If MAC loopback 3.0000.14 is set to 1, then the line loopback registers 3.8002.5 and 1.C000.11 are ignored.

Figure 21: Line Loopback Diagram — Copper Media Interface



4.3 Power Management

The T Unit supports several advanced power management modes that conserve power.

4.3.1 Manual Power Down

The T Unit can be manually powered down by setting register 1.0000.11 or 3.0000.11 to 1. In general, this bit should not be set unless there is a need to only power down the T Unit.

When the device is operating in modes that does not require the T Unit to be operational, the T Unit will be powered down automatically regardless of the setting in register 1.0000.11 or 3.0000.11.

4.3.2 Energy Detect

The T Unit can be placed in energy detect power down modes by selecting either of the two Energy Detect modes. Both modes enable the PHY to wake up on its own by detecting activity on the media interface. The status of the Energy Detect is reported in register 3.8008.4 and the Energy Detect changes are reported in register 3.8011.4.

4.3.2.1 Energy Detect (Mode 1)

Energy Detect (Mode 1) is entered by setting register 3.8000.9:8 to 10.

In Mode 1, only the signal detection circuitry and register are active. If the PHY detects energy on the line, then it starts to Auto-Negotiate sending FLPs for 5 seconds. If at the end of 5 seconds the Auto-Negotiation is not completed, then the PHY stops sending FLPs and goes back to monitoring receive energy. If Auto-Negotiation is completed, then the PHY goes into normal operation. If during normal operation the link is lost, the PHY will restart Auto-Negotiation. If no energy is detected after 5 seconds, then the PHY resumes monitoring receive energy.

4.3.2.2 Energy Detect +™ (Mode 2)

Energy Detect (Mode 2) is entered by setting register 3.8000.9:8 to 11.

In Mode 2, the PHY sends out a single 10 Mbps Normal Link Pulse (NLP) every one second. Except for this difference, Mode 2 is identical to Mode 1 operation. If the T Unit is in Mode 1, then it cannot wake up a connected device; so, the connected device must be transmitting NLPs or either device must be woken up through register access. If the T Unit is in Mode 2, then it can wake a connected device.

4.4 Auto-Negotiation

The PHY supports IEEE 802.3 Clauses 28, 40, and 55 Auto-Negotiation. The PHY also supports proprietary extensions to the Auto-Negotiation protocol.

4.4.1 802.3 Clause 28, 40, and 55 Auto-Negotiation

The 10/100/1000/2.5G/5GBASE-T Auto-Negotiation (AN) is based on Clauses 28, 40, 55, and 126 of the IEEE 802.3 specification. It is also based on the NBASE-T Physical Layer Specification. It is used to negotiate speed, duplex, and flow control. When Auto-Negotiation is initiated, the PHY determines whether the remote device has Auto-Negotiation capability: if so, the PHY and the remote device negotiate the speed and duplex with which to operate.

If the remote device does not have Auto-Negotiation capability, then the PHY uses the parallel detect function to determine the speed of the remote device for 100BASE-TX and 10BASE-T modes. If link is established based on the parallel detect function, then it is required to establish link at half-duplex mode only. Refer to IEEE 802.3 Clauses 28, 40, 55, and 126 for a full description of Auto-Negotiation.

The 10/100/1000/2.5G/5GBASE-T Auto-Negotiation can be enabled and disabled via register 7.0000.12. Auto-Negotiation must be enabled if the PHY is intended to operate in 1000BASE-T, 2.5GBASE-T, or 5GBASE-T. Furthermore, the extended next page control bit (7.0000.13) must also be set to 1 if the PHY is intended to operate in 2.5GBASE-T and 5GBASE-T.

Auto MDI/MDIX and Auto-Negotiation may be disabled and enabled independently.

When Auto-Negotiation is disabled, the speed and duplex can be set via registers 1.0000.13, 1.0000.6, and 7.8000.4, respectively. Changes to any of these bits will take effect immediately when Auto-Negotiation is disabled.

When Auto-Negotiation is enabled the abilities that are advertised can be changed via registers 7.0010, 7.0020, and 7.8000.9:8. Changes to these registers do not take effect upon a copper link drop, changes take effect only after one of the following occurs:

- Software reset (1.0000.15, 3.0000.15, or 7.0000.15).
- Restart Auto-Negotiation (7.0000.9).
- Transition from power down to power up (1.0000.11 or 3.0000.11).
- Auto-Negotiation Enable bit toggles (7.0000.12).
- Extended Next Page Enable bit toggles (7.0000.13).
- Speed and Duplex toggles while Auto-Negotiation is disabled (1.0000.13, 1.0000.6, and 7.8000.4).

Registers 7.0010, 7.0020, and 7.8000.9:8 are internally latched once every time the Auto-Negotiation enters the Ability Detect state in the arbitration state machine only following one of the previously listed events. So a write into registers 7.0010, 7.0020, and 7.8000.9:8 has no effect when the PHY begins to transmit Fast Link Pulses (FLPs). This guarantees that sequences of FLPs transmitted are consistent with one another.

If 1000BASE-T, 2.5GBASE-T, or 5GBASE-T modes are advertised, then the PHY automatically sends the appropriate next pages or extended next page to advertise the capability and negotiate master/slave mode of operation. If the user does not select to transmit additional next pages or extended next pages, then the next page bit (7.0010.15) can be set to zero (default) and no further action is required from the user.

If either next pages or extended next pages are required in addition to those selected, or 1000BASE-T, 2.5GBASE-T, or 5GBASE-T, then the user can set register 7.0010.15 to one. Additional next pages can be transmitted and received via registers 7.0016 and 7.0019, respectively. Additional extended next pages can be transmitted and received via registers 7.0016, 7.0017, 7.0018 and 7.0019, 7.001A, and 7.001B, respectively.

1000BASE-T next page exchanges 2.5GBASE-T and 5GBASE-T extended next page exchanges are automatically handled by the PHY without user intervention, regardless of whether additional next pages are sent.

When the PHY completes Auto-Negotiation, it updates the various status in registers 7.0001, 7.0013, 7.8000, and 7.8001. Various Auto-Negotiation statuses such as speed, duplex, page received, and so on are also available in registers 3.8008 and 3.8011.

Clause 45 defines a 16-bit address space and protocol for 10G PHY management registers. The device supports the Clause 45 protocol and address space. Some of the 10M/100M/1G management register bits have an equivalent defined by IEEE 802.3 within the Clause 45 address space. However, there are also 10M/100M/1G management registers that are not defined by IEEE 802.3 within the Clause 45 address space. In the device these management register bits are mapped into 7.8000, 7.8001, and 7.8002.

The changes in Auto-Negotiation settings via MDIO registers will not take into effect (including a link down event) until Auto-Negotiation restart is initiated.

4.4.2 Exchange Complete — No Link Indicator

Sometimes when link does not come up, it is difficult to determine whether the failure is due to the Auto-Negotiation FLP not completing or from the 10/100/1000/2.5G/5GBASE-T link not being able to come up.

Register 3.8011.3 is a latched high bit that gets set to 1 whenever the FLP exchange is completed but the link cannot be established for some reason. When the bit is set, it can be cleared only by reading the register.

This bit will not be set if the FLP exchange is not completed or if link is established.

4.5 Auto Downshift

The auto downshift feature will downshift to the next highest available speed when a link fails to be established after several attempts to link. Failure to link can be caused by cabling issues such as using long CAT 5 cabling for 5GBASE-T or using cable with two twisted pairs instead of four twisted pairs. In either of the case, the Auto-Negotiation will repeatedly negotiate to the higher speed but fail to link.

With the NBASE-T downshift feature enabled, the T Unit is able to Auto-Negotiate with another link partner using cable pairs 1, 2 and 3, 6 to downshift, and link to the next highest advertised speed common between the two PHYs.

By default, the downshift feature is enabled. Setting register 1.C034.4 to 0 will disable the auto downshift feature.

Registers 1.C034 and 1.C035 specify the amount of attempts to link to 5GBASE-T, 2.5GBASE-T, and 1000BASE-T, respectively before down shifting to the next highest available speed. The number of attempts before downshift is (1.C034.[3:0]+1). So the default setting of 2 means NBASE-T downshift occurs after 3 link failures at current resolved speed. During the process of NBASE-T downshift, the number of attempts already performed is shown in the status register 1.C035.[12:9] which gets reset at next link up. Downshift for 100BASE-T and 10BASE-T are not supported.

When the lowest available speed fails to link after the programmed number of attempts, the PHY will restart the algorithm and attempt to link at the highest available speed.

4.6 Auto MDI/MDIX Crossover

The T Unit automatically determines whether it must cross over between pairs as shown in [Table 42](#) so that an external crossover cable is not required. If the T Unit interoperates with a device that cannot automatically correct for crossover, the T Unit makes the necessary adjustment prior to commencing Auto-Negotiation. If the T Unit interoperates with a device that implements MDI/MDIX crossover, then a random algorithm as described in IEEE 802.3 Clause 40.4.4 determines which device performs the crossover.

When the T Unit interoperates with legacy 10BASE-T devices that do not implement Auto-Negotiation, the T Unit follows the same algorithm as previously described since link pulses are present. However, when interoperating with legacy 100BASE-TX devices that do not implement Auto-Negotiation (such as when link pulses are not present), the T Unit uses signal detect to determine whether to crossover.

The auto MDI/MDIX crossover function can be disabled via register 3.8000.6:5.

The pin mapping in MDI and MDIX modes is shown in [Table 42](#).

Table 42: Media Dependent Interface Pin Mapping

| Pin | MDI | | | MDIX | | |
|-----------|------------------------|------------|----------|------------------------|------------|----------|
| | 1000/2.5G/ 5GBASE-T | 100BASE-TX | 10BASE-T | 1000/2.5G/ 5GBASE-T | 100BASE-TX | 10BASE-T |
| MDIP/N[0] | BI_DA± | TX± | TX± | BI_DB± | RX± | RX± |
| MDIP/N[1] | BI_DB± | RX± | RX± | BI_DA± | TX± | TX± |
| MDIP/N[2] | BI_DC± | unused | unused | BI_DD± | unused | unused |
| MDIP/N[3] | BI_DD± | unused | unused | BI_DC± | unused | unused |



Note

[Table 42](#) assumes no crossover on PCB.

The MDI/MDIX status is indicated by register 3.8008.6. This bit indicates whether the signal pairs (3, 6) and (1, 2) are crossed over. In 5GBASE-T, 2.5GBASE-T, and 1000BASE-T operation, the device can also correct for crossover between pairs (4, 5) and (7, 8). However, this is not indicated by register 3.8008.6.

4.7 Auto Polarity Correction

The T Unit automatically corrects polarity errors on the receive pairs in 5GBASE-T, 2.5GBASE-T, 1000BASE-T and 10BASE-T modes. In 100BASE-TX mode, the polarity does not matter.

In 5GBASE-T, 2.5GBASE-T, and 1000BASE-T modes, auto polarity correction is always enabled, receive polarity errors are automatically corrected based on the startup training sequence. When the training is complete the polarity is locked on all pairs. The polarity becomes unlocked only when the receiver loses lock.

If a 1000BASE-T, 2.5GBASE-T, or 5GBASE-T link is established, register 1.0082.11:8 (2.5G/5G) and 3.8182.11:8 (1G) report the polarity on all 4 pairs.

In 10BASE-T mode, auto polarity correction is enabled when register 3.8000.1 is set to 0. If register 3.8000.1 is set to 1, then the polarity will be forced to normal. When enabled, polarity errors are corrected based on the detection of validly spaced link pulses. The detection begins during the MDI crossover detection phase and locks when the 10BASE-T link is up. The polarity becomes unlocked when link is down.

The 10BASE-T polarity correction status is indicated by register 3.8008.1. This bit indicates whether the receive pair (3, 6) is polarity reversed in MDI mode of operation. In the MDIX mode of operation, the receive pair is (1, 2) and register 3.8008.1 indicates whether this pair is polarity reversed. Although all pairs are corrected for receive polarity reversal, register 3.8008.1 only indicates polarity reversal on the pairs described above.

The 10BASE-T receive polarity can be forced to negative by setting register 3.8001.9 to 1. This is useful for debugging and should not be used during normal operation.

5 Host Interface Unit (H Unit)

The host side interface comprises two differential input lanes SIP[1:0]/SIN[1:0] and two differential output lanes SOP[1:0]/SON[1:0]. They are designed to operate over short backplanes to the host device.

These lanes can be arranged to form SGMII, 1000BASE-X, 2500BASE-X, and 5GBASE-R.

5.1 Host Electrical Interface

The input and output buffers of the SERDES interface are internally terminated by 50Ω impedance (100Ω differential). No external terminations are required.

The SERDES transmitter has a three-tap (1 pre-tap and 1 post-tap) FIR filter for channel equalization. The FIR tap can be manually adjusted to optimize the transmit eye over a particular channel.

The receiver performs clock and data recovery and de-serializes the data.

The polarity of the H Unit inputs and outputs can be inverted.

4.F004.15 inverts Lane3 input polarity: 0 = Normal, 1 = Invert

4.F004.14 inverts Lane2 input polarity: 0 = Normal, 1 = Invert

4.F004.13 inverts Lane 1 input polarity: 0 = Normal, 1 = Invert

4.F004.12 inverts Lane 0 input polarity: 0 = Normal, 1 = Invert

4.F004.11 inverts Lane3 output polarity: 0 = Normal, 1 = Invert

4.F004.10 inverts Lane2 output polarity: 0 = Normal, 1 = Invert

4.F004.9 inverts Lane 1 output polarity: 0 = Normal, 1 = Invert

4.F004.8 inverts Lane 0 output polarity: 0 = Normal, 1 = Invert

**Note**

Lane 1 is only applicable when MACTYPE[2:0] = 000, 001, 010, or 011. See [Section 3.5, Configuration and Resets, on page 60](#) for MACTYPE[2:0] configuration details.

5.2 PCS

The Host Interface supports several different PCS. Register 31.F001.2:0 determines the behavior of the host interface as shown in [Table 43](#) and [Table 44](#).

Table 43: 88E2010 Host Interface Configuration

| 31.F001.2:0 | Line Rate | | | | |
|-------------|---------------------|------------|----------------------------|----------|---------|
| | 5 Gbps | 2.5 Gbps | 1 Gbps | 100 Mbps | 10 Mbps |
| 000 | 5GBASE-R | 2500BASE-X | SGMII Auto-Negotiation On | | |
| – | Reserved | | | | |
| – | Reserved | | | | |
| 011 | 5GBASE-R | 2500BASE-X | SGMII Auto-Negotiation On | | |
| 100 | 5GBASE-R | 2500BASE-X | SGMII Auto-Negotiation On | | |
| 101 | 5GBASE-R | 2500BASE-X | SGMII Auto-Negotiation Off | | |
| 110 | 5GBASE-R/2500BASE-X | | | | |
| 111 | Reserved | | | | |

Table 44: 88E2040L Host Interface Configuration

| 31.F001.2:0 | Line Rate | | | | |
|-------------|---------------------|------------|----------------------------|----------|---------|
| | 5 Gbps | 2.5 Gbps | 1 Gbps | 100 Mbps | 10 Mbps |
| 000 | 5GBASE-R | 2500BASE-X | SGMII Auto-Negotiation On | | |
| 001 | 5GBASE-R | 2500BASE-X | SGMII Auto-Negotiation Off | | |
| 010 | Reserved | | | | |
| 011 | Reserved | | | | |
| 100 | 5GBASE-R | 2500BASE-X | SGMII Auto-Negotiation On | | |
| 101 | 5GBASE-R | 2500BASE-X | SGMII Auto-Negotiation Off | | |
| 110 | 5GBASE-R/2500BASE-X | | | | |
| 111 | Reserved | | | | |

5.2.1 5GBASE-R/2500BASE-X

The 5GBASE-R/2500BASE-X PCS is enabled by setting register 31.F001.2:0 = 001 (88E2010 only), 010, 110, or 111.

The 5GBASE-R/2500BASE-X PCS operates according to Clause 49 of the IEEE 802.3ae specification. The PCS uses a 64B/66B coding and scrambling to improve the transmission characteristics of the serial data and ease clock recovery at the receiver. The synchronization headers for 64B/66B code enable the receiver to achieve block alignment on the receive data. For further details, refer to the IEEE 802.3 specification.

5.2.2 5GBASE-R

For the 88E2040L devices, the 5GBASE-R PCS is enabled by setting register 31.F001.2:0 = 000, 001, 100, 101, and the line rate is 5 Gbps.

For the 88E2010 device, the 5GBASE-R PCS is enabled by setting register 31.F001.2:0 = 000, 011, 100, 101, and the line rate is 5 Gbps.

5GBASE-R is identical to 5GBASE-R/2500BASE-X as described in [Section 5.2.1, 5GBASE-R/2500BASE-X](#) except at 50% speed.

5.2.3 2500BASE-X

For the 88E2040L device the 2500BASE-X PCS is enabled by setting register 31.F001.2:0 = 000, 001, 100, 101, and the line rate is 2.5 Gbps.

For the 88E2010 device, the 2500BASE-X PCS is enabled by setting register 31.F001.2:0 = 000, 011, 100, 101, and the line rate is 2.5 Gbps.

2500BASE-X is identical to 1000GBASE-X operation as described in [Section 5.2.4.1, PCS](#) except at 2.5 times the speed. Auto-Negotiation is not supported in 2500BASE-X.

5.2.4 SGMII (Media)

For the 88E2040L device, the SGMII is enabled by setting register 31.F001.2:0 = 000, 001, 100, 101, and the line rate is 10/100/1000 Mbps. SGMII Auto-Negotiation is enabled with the 000 and 100 settings.

For the 88E2010 device, the SGMII is enabled by setting register 31.F001.2:0 = 000, 011, 100, 101, and the line rate is 10/100/1000 Mbps. SGMII Auto-Negotiation is enabled with the 000, 011 and 100 settings.

5.2.4.1 PCS

The 1000BASE-X PCS operates according to Clause 36 of the IEEE 802.3 specification. The PCS uses a 8/10 bit coding for DC line balancing. For further details, refer to the IEEE 802.3 specification.

The SGMII protocol is also supported over 1000BASE-X. The SGMII allows 10 Mbps, 100 Mbps, and 1000 Mbps throughput over 1000BASE-X line coding.

When SGMII Auto-Negotiation is turned off (4.2000.12 = 0), the speed setting is programmed via register 4.2000 bits 13 and 6. Link is established when the underlying 1000BASE-X establishes link.

When SGMII Auto-Negotiation is turned on (4.2000.12 = 1), the SGMII is set to the speed of the line interface. This speed capability is advertised and Auto-Negotiation has to complete prior to link being established.

5.2.4.2 SGMII Auto-Negotiation

SGMII is a de-facto standard designed by Cisco. SGMII uses 1000BASE-X coding to send data as well as Auto-Negotiation information between the PHY and the MAC. However, the contents of the SGMII Auto-Negotiation are different than the 1000BASE-X Auto-Negotiation. See the *Cisco SGMII Specification* and the *MAC Interfaces and Auto-Negotiation Application Note* for further details.

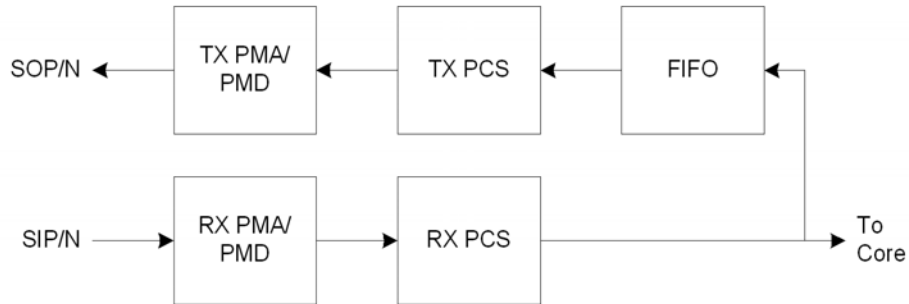
The device supports SGMII interface with and without Auto-Negotiation. Auto-Negotiation can be enabled or disabled by writing to register 4.2000.12. If SGMII Auto-Negotiation is disabled, then the MAC interface link, speed, and duplex status (determined by the media side) cannot be conveyed to the MAC from the PHY. The user must program the MAC with this information in some other way (for example, by reading PHY registers for link, speed, and duplex status).

5.3 Loopback

The host-side SERDES support two loopback paths.

If register 4.F003.12 = 1, then data from the host will loopback to the host as shown in [Figure 22](#).

Figure 22: Shallow Host Loopback



Registers 4.0000.14, 4.1000.14, and 4.2000.14 are physically the same bit. If any of these bits are set to 1, then data from the core will loopback to the core as shown in [Figure 23](#) and [Figure 24](#). If register 4.F003.6, then the ingress path will not be blocked as shown in [Figure 23](#). If register 4.F003.6 = 1, then the ingress path will be blocked as shown in [Figure 24](#).

Figure 23: Deep Line Loopback, No Ingress Blocking

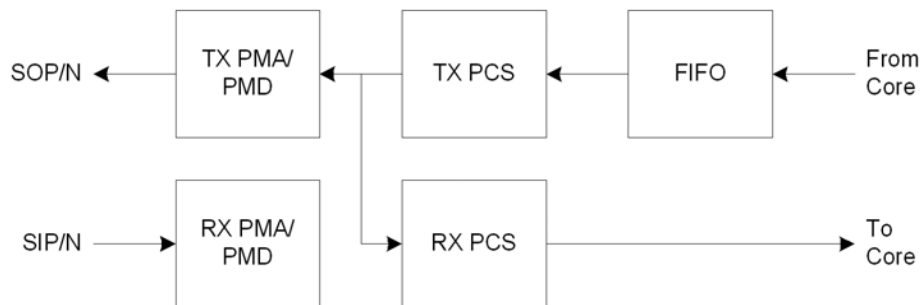
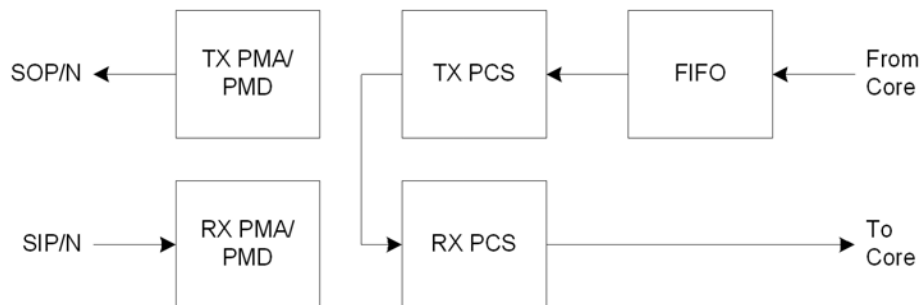


Figure 24: Deep Line Loopback, Ingress Blocking



5.4 Power Management

The device will automatically power down unused circuits. The host side can be forced into a power down state by setting 4.0000.11, 4.1000.11, or 4.2000.11. These power down registers are physically the same bit even though they reside in different locations.

To soft reset the host side only, set registers 4.0000.15, 4.1000.15, or 4.2000.15. These software reset registers are physically the same bit even though they reside in different locations.

6 Electrical Specifications

6.1 Absolute Maximum Ratings

Table 45: Absolute Maximum Rating

Stresses above those listed in Absolute Maximum Ratings may cause permanent device failure. Functionality at or above these limits is not implied. Exposure to absolute maximum ratings for extended periods may affect device reliability.

| Symbol | Parameter | Min | Typ | Max | Units |
|----------------------|--|------|-----|-------------------|-------|
| V _{DDAC} | Power Supply Voltage on AVDDC with respect to VSS | -0.5 | – | 2.5 | V |
| V _{DDAL} | Power Supply Voltage on AVDDL with respect to VSS | -0.5 | – | 2.5 | V |
| V _{DDAH} | Power Supply Voltage on AVDDH with respect to VSS | -0.5 | – | 2.5 | V |
| V _{DDAT} | Power Supply Voltage on AVDDT with respect to VSS | -0.5 | – | 3.0 | V |
| V _{DDAR} | Power Supply Voltage on AVDDR with respect to VSS | -0.5 | – | 2.5 | V |
| V _{DDAS} | Power Supply Voltage on AVDDS with respect to VSS | -0.5 | – | 2.5 | V |
| V _{DD} | Power Supply Voltage on DVDD with respect to VSS | -0.5 | – | 1.2 | V |
| V _{DDO} | Power Supply Voltage on VDDOL, VDDOM, VDDOR, VDDOT with respect to VSS | -0.5 | – | 3.6 | V |
| V _{HV} | Power Supply Voltage on VHV with respect to VSS | -0.5 | – | 1.2 | V |
| V _{PIN} | Voltage Applied to Any Digital Input Pin | -0.5 | – | 3.6 | V |
| T _{STORAGE} | Storage Temperature | -55 | – | +125 ¹ | °C |

1. 125°C is only used as bake temperature for not more than 24 hours. Long-term storage (for example, weeks or longer) should be kept at 85°C or lower.

6.2 Recommended Operating Conditions

Table 46: Recommended Operating Conditions

| Symbol | Parameter | Condition | Min | Typ | Max | Units |
|----------------------------------|---|--|-------|------------------------|------------------|-------|
| V _{DDAC} ^{1,2} | AVDDC Supply | For AVDDC | 1.455 | 1.5 | 1.545 | V |
| V _{DDAL} ^{1,2} | AVDDL Supply | For AVDDL | 1.455 | 1.5 | 1.545 | V |
| V _{DDAH} ^{1,2} | AVDDH Supply | For AVDDH | 1.940 | 2.0 | 2.060 | V |
| | | | 1.746 | 1.8 | 1.854 | V |
| V _{DDAT} ^{1,2} | AVDDT Supply | For AVDDT | 2.425 | 2.5 | 2.575 | V |
| | | | 2.231 | 2.3 | 2.396 | V |
| V _{DDAR} ^{1,2} | AVDDR Supply | For AVDDR | 1.455 | 1.5 | 1.545 | V |
| V _{DDAS} ^{1,2} | AVDDS Supply | For AVDDS | 1.455 | 1.5 | 1.545 | V |
| V _{DD} ^{1,2} | DVDD Supply | For DVDD (C-temp) | 0.776 | 0.8 | 0.824 | V |
| | | For DVDD (I-temp) | 0.854 | 0.88 | 0.906 | V |
| V _{DDO} ^{1,2} | VDDOL, VDDOM, VDDOR, VDDOT Supply | For VDDOM at 1.2V | 1.14 | 1.2 | 1.26 | V |
| | | For VDDO* at 1.5V | 1.425 | 1.5 | 1.575 | V |
| | | For VDDO* at 1.8V | 1.71 | 1.8 | 1.89 | V |
| | | For VDDO* at 2.5V | 2.375 | 2.5 | 2.625 | V |
| | | For VDDO* at 3.3V | 3.135 | 3.3 | 3.465 | V |
| V _{HV} ^{1,2} | VHV Supply | Leave floating | – | – | – | V |
| IREF | Internal Bias Reference CIREF, SIREF | Resistor connected to V _{SS} | – | 4.99K ±1% Tolerance | – | Ω |
| T _A | Commercial Ambient Operating Temperature | Commercial Parts ³ | 0 | – | 70 | °C |
| | | Industrial Parts ⁴ | -40 | – | 85 | °C |
| T _J | Maximum Junction Temperature | | – | – | 105 ⁵ | °C |

1. Maximum noise allowed on supplies is 25 mV peak-peak.
2. The recommended operating conditions assume that the ripple is included. DC operating conditions with the ripple should never exceed the recommended operating levels. For example, on a system: DVDD supply - 12.5 mV (ripple peak) should be less than 0.776V.
3. Commercial operating temperatures are typically below 70°C, for example, 45°C~55°C. The 70°C maximum is the Marvell specification limit.
4. Industrial part numbers have an / following the commercial part numbers. For details, see [Section 8.1, Part Order Numbering, on page 142](#).
5. Refer to the white paper on T_J Thermal Calculations for detailed information.

6.3 Package Thermal Information

6.3.1 Thermal Conditions for 88E2010, 168-pin, HFCBGA Package

Table 47: Thermal Conditions for 88E2010, 168-pin, HFCBGA Package

| Symbol | Parameter | Condition | Min | Typ | Max | Units |
|---------------|--|---|-----|-------|-----|-------|
| θ_{JA} | Thermal Resistance ¹ - Junction to Ambient for the 168-pin, HFCBGA Package $\theta_{JA} = (T_J - T_A)/P$ P = Total Power Dissipation | JEDEC 3 in. x 4.5 in. 4-layer PCB with no air flow | – | 19.56 | – | °C/W |
| | | JEDEC 3 in. x 4.5 in. 4-layer PCB with 1 meter/sec air flow | – | 16.90 | – | °C/W |
| | | JEDEC 3 in. x 4.5 in. 4-layer PCB with 2 meter/sec air flow | – | 15.42 | – | °C/W |
| | | JEDEC 3 in. x 4.5 in. 4-layer PCB with 3 meter/sec air flow | – | 14.35 | – | °C/W |
| ψ_{JT} | Thermal Characteristic Parameter ^a - Junction to the Top Center of the 168-pin, HFCBGA Package $\psi_{JT} = (T_J - T_{top})/P$ P = Total Power Dissipation, T_{top} : Temperature on the Top Center of the Package | JEDEC 3 in. x 4.5 in. 4-layer PCB with no air flow | – | 0.21 | – | °C/W |
| | | JEDEC 3 in. x 4.5 in. 4-layer PCB with 1 meter/sec air flow | – | 0.24 | – | °C/W |
| | | JEDEC 3 in. x 4.5 in. 4-layer PCB with 2 meter/sec air flow | – | 0.26 | – | °C/W |
| | | JEDEC 3 in. x 4.5 in. 4-layer PCB with 3 meter/sec air flow | – | 0.28 | – | °C/W |
| θ_{JC} | Thermal Resistance ^a - Junction to the Case for the 168-pin, HFCBGA Package $\theta_{JC} = (T_J - T_C)/P_{top}$ P_{top} = Power Dissipation from the Top of the Package | JEDEC with no air flow | – | 0.66 | – | °C/W |
| θ_{JB} | Thermal Resistance ^a - Junction to the Board for the 168-pin, HFCBGA Package $\theta_{JB} = (T_J - T_B)/P_{bottom}$ P_{bottom} = Power Dissipation from the Bottom of the Package to the PCB Surface | JEDEC with no air flow | – | 8.18 | – | °C/W |

1. Refer to the white paper on T_J Thermal Calculations for detailed information.

6.3.2 Thermal Conditions for 88E2040L, 484-pin, HFCBGA Package

Table 48: Thermal Conditions for 88E2040L, 484-pin, HFCBGA Package

| Symbol | Parameter | Condition | Min | Typ | Max | Units |
|---------------|--|---|-----|------|-----|-------|
| θ_{JA} | Thermal Resistance ¹ - Junction to Ambient for the 484-pin, HFCBGA Package $\theta_{JA} = (T_J - T_A)/P$ P = Total Power Dissipation | JEDEC 3 in. x 4.5 in. 4-layer PCB with no air flow | – | 9.09 | – | °C/W |
| | | JEDEC 3 in. x 4.5 in. 4-layer PCB with 1 meter/sec air flow | – | 7.85 | – | °C/W |
| | | JEDEC 3 in. x 4.5 in. 4-layer PCB with 2 meter/sec air flow | – | 7.27 | – | °C/W |
| | | JEDEC 3 in. x 4.5 in. 4-layer PCB with 3 meter/sec air flow | – | 6.88 | – | °C/W |
| ψ_{JT} | Thermal Characteristic Parameter ^a - Junction to the Top Center of the 484-pin, HFCBGA Package $\psi_{JT} = (T_J - T_{top})/P$ P = Total Power Dissipation, T_{top} : Temperature on the Top Center of the Package | JEDEC 3 in. x 4.5 in. 4-layer PCB with no air flow | – | 0.16 | – | °C/W |
| | | JEDEC 3 in. x 4.5 in. 4-layer PCB with 1 meter/sec air flow | – | 0.25 | – | °C/W |
| | | JEDEC 3 in. x 4.5 in. 4-layer PCB with 2 meter/sec air flow | – | 0.28 | – | °C/W |
| | | JEDEC 3 in. x 4.5 in. 4-layer PCB with 3 meter/sec air flow | – | 0.30 | – | °C/W |
| θ_{JC} | Thermal Resistance ^a - Junction to the Case for the 484-pin, HFCBGA Package $\theta_{JC} = (T_J - T_C)/P_{top}$ P_{top} = Power Dissipation from the Top of the Package | JEDEC with no air flow | – | 0.30 | – | °C/W |
| θ_{JB} | Thermal Resistance ^a - Junction to the Board for the 484-pin, HFCBGA Package $\theta_{JB} = (T_J - T_B)/P_{bottom}$ P_{bottom} = Power Dissipation from the Bottom of the Package to the PCB Surface | JEDEC with no air flow | – | 2.60 | – | °C/W |

1. Refer to the white paper on T_J Thermal Calculations for information.

6.4 Digital I/O Electrical Specifications

6.4.1 DC Operating Conditions

Table 49: DC Operating Conditions

(Over full range of values listed in the Recommended Operating Conditions unless otherwise specified)

| Symbol | Parameter | Pins | Condition | Min | Typ | Max | Units |
|------------------|---------------------------|--|-------------|-------------|-----|-------------|-------|
| VIH | Input High Voltage | All digital inputs | VDDO = 3.3V | 2.0 | – | VDDO + 0.3V | V |
| | | | VDDO = 2.5V | 1.75 | – | VDDO + 0.3V | V |
| | | | VDDO = 1.8V | 1.26 | – | VDDO + 0.3V | V |
| | | | VDDO = 1.5V | 1.05 | – | VDDO + 0.3V | V |
| | | | VDDO = 1.2V | 0.84 | – | VDDO + 0.3V | V |
| VIL | Input Low Voltage | All digital inputs | VDDO = 3.3V | -0.3 | – | 0.8 | V |
| | | | VDDO = 2.5V | -0.3 | – | 0.75 | V |
| | | | VDDO = 1.8V | -0.3 | – | 0.54 | V |
| | | | VDDO = 1.5V | -0.3 | – | 0.45 | V |
| | | | VDDO = 1.2V | -0.3 | – | 0.36 | V |
| VOH | High-level Output Voltage | All digital outputs | IOH = -4 mA | VDDO - 0.4V | – | – | V |
| VOL | Low-level Output Voltage | All digital outputs | IOL = 4 mA | – | – | 0.4 | V |
| I _{ILK} | Input Leakage Current | With internal pull-up/pull-down resistor | – | 10 | – | 70 | μA |
| | | All others without resistor | – | – | – | 10 | μA |
| I _{LED} | Max Current per LED Pin | All LED pins | – | – | – | 8 | mA |
| CIN | Input Capacitance | All pins | – | – | – | 5 | pF |

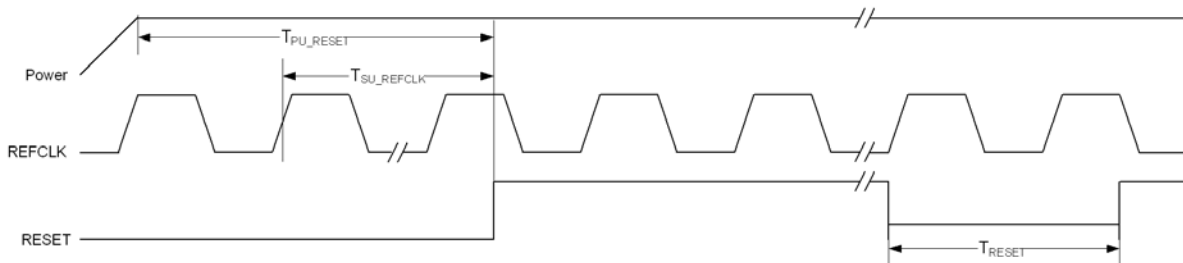
6.4.2 Reset Timing

Table 50: Reset Timing

(Over Full range of values listed in the Recommended Operating Conditions unless otherwise specified)

| Symbol | Parameter | Condition | Min | Typ | Max | Units |
|------------------|--|-----------|-----|-----|-----|-------|
| T_{PU_RESET} | Valid Power to RESET De-asserted | – | 10 | – | – | ms |
| T_{SU_REFCLK} | Number of Valid REFCLK Cycles Prior to RESET De-asserted | – | 10 | – | – | clks |
| T_{RESET} | Minimum Reset Pulse Width During Normal Operation | – | 10 | – | – | ms |

Figure 25: Reset Timing

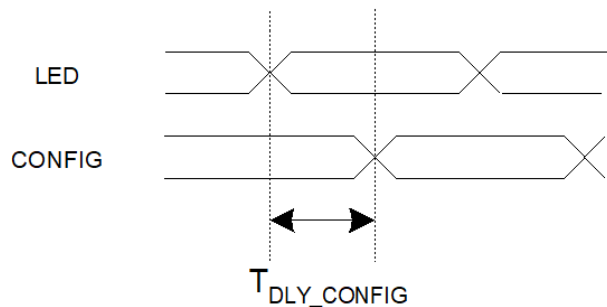


6.4.3 LED to CONFIG Timing

Table 51: LED to CONFIG Timing

| Symbol | Parameter | Condition | Min | Typ | Max | Units |
|-------------------|---------------------|-----------|-----|-----|-----|-------|
| T_{DLY_CONFIG} | LED to CONFIG Delay | – | 0 | – | 25 | ns |

Figure 26: LED to CONFIG Timing



6.4.4 MDC/MDIO Management Interface Timing

Table 52: MDC/MDIO Management Interface Timing

(Over full range of values listed in the Recommended Operating Conditions unless otherwise specified)

| Symbol | Parameter | Min | Typ | Max | Units |
|-----------------|---------------------------------|-----|-----|-----|-------|
| T_{DLY_MDIO} | MDC-to-MDIO (Output) Delay Time | 2 | – | 16 | ns |
| T_{SU_MDIO} | MDIO- (Input) to-MDC Setup Time | 3 | – | – | ns |
| T_{HD_MDIO} | MDIO- (Input) to-MDC Hold Time | 3 | – | – | ns |
| T_{P_MDC} | MDC Period | 35 | – | – | ns |
| T_{H_MDC} | MDC High | 17 | – | – | ns |
| T_{L_MDC} | MDC Low | 17 | – | – | ns |
| V_{HYST} | VDDO Input Hysteresis | – | 360 | – | mV |
| T_{P_MDC} | MDC Period | 35 | – | – | ns |
| T_{read_dly} | Read Delay | 160 | – | – | ns |

Figure 27: MDC/MDIO Management Interface Timing

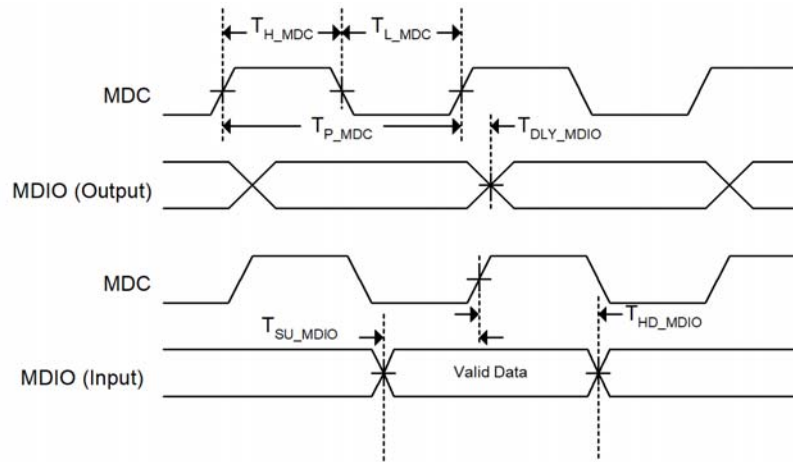


Figure 28: MDC/MDIO Input Hysteresis

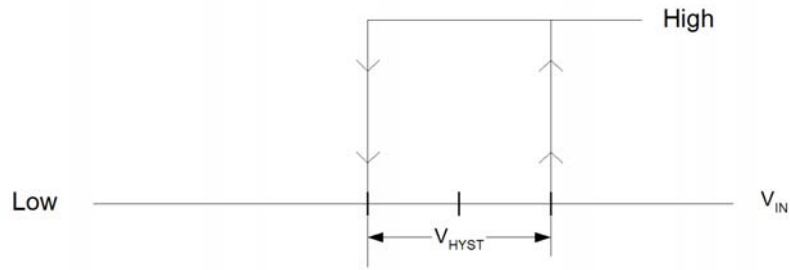
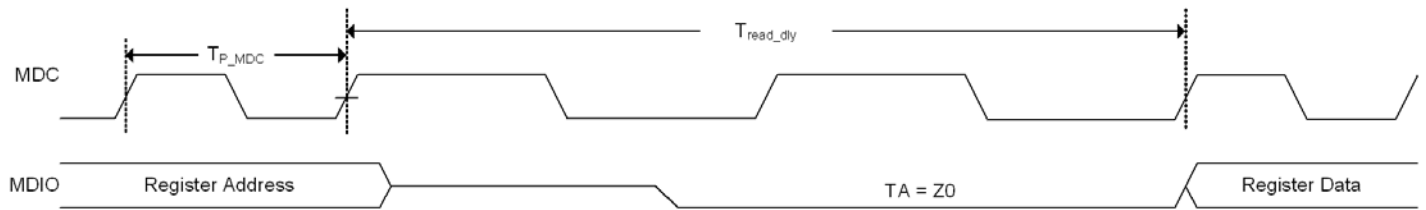


Figure 29: MDC Read Turnaround Delay



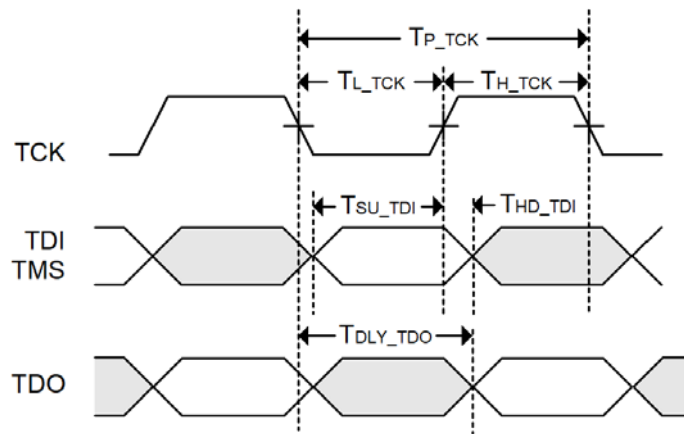
6.4.5 JTAG Timing

Table 53: JTAG Timing

(Over full range of values listed in the Recommended Operating Conditions unless otherwise specified)

| Symbol | Parameter | Condition | Min | Typ | Max | Units |
|----------------|----------------------------|-----------|-----|-----|-----|-------|
| T_{P_TCK} | TCK Period | – | 60 | – | – | ns |
| T_{H_TCK} | TCK High | – | 12 | – | – | ns |
| T_{L_TCK} | TCK Low | – | 12 | – | – | ns |
| T_{SU_TDI} | TDI, TMS-to-TCK Setup Time | – | 10 | – | – | ns |
| T_{HD_TDI} | TDI, TMS-to-TCK Hold Time | – | 10 | – | – | ns |
| T_{DLY_TDO} | TCK-to-TDO Delay | – | 0 | – | 15 | ns |

Figure 30: JTAG Timing



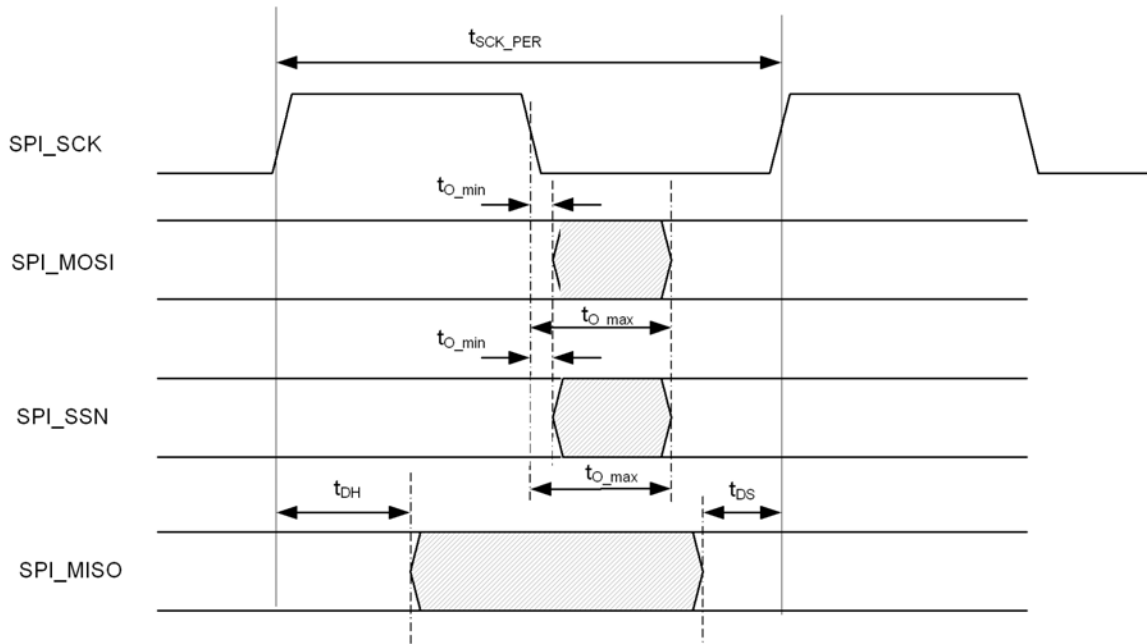
6.4.6 SPI Interface Timing

Table 54: SPI Interface Timing

(Over full range of values listed in the Recommended Operating Conditions unless otherwise specified)

| Symbol | Parameter | Condition | Min | Typ | Max | Units |
|------------------------------|------------------------------|-----------|-----|-------|-----|-------|
| T_{SCK_PER} | SCK Period | – | – | 204.8 | – | ns |
| | SCK Duty Cycle | – | 48 | 50 | 52 | % |
| $T_{O_min\ to\ T_{O_max}}$ | MOSI Valid from SCK Low | – | 0 | – | 20 | ns |
| T_{DH} | MISO Hold Time from SCK High | – | 0 | – | – | ns |
| T_{DS} | MISO Setup Time to SCK High | – | 50 | – | – | ns |

Figure 31: SPI Interface Timing



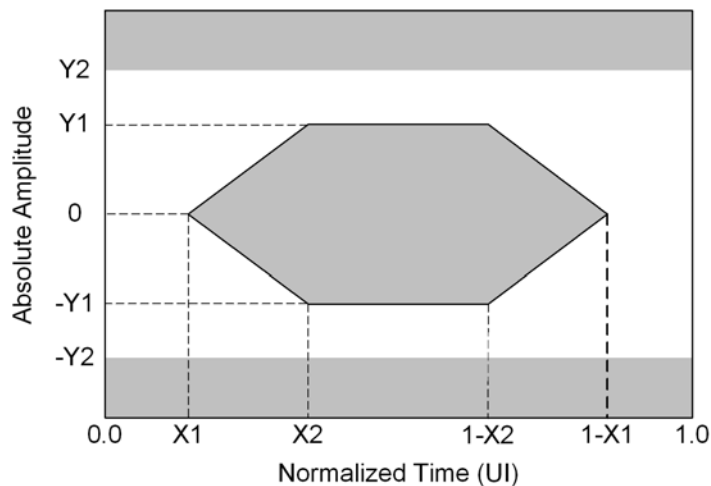
6.5 Analog Electrical Specifications

6.5.1 SGMII Electrical Summary

Table 55: SGMII Electrical Summary

| Test Parameters | Specification | | | Units |
|---|-------------------|------|------|----------|
| | Transmitter Tests | | | |
| | Min | Mean | Max | |
| Output Voltage High | – | – | 1525 | mV |
| Output Voltage Low | 875 | – | – | mV |
| Output Ringing | – | – | 10 | % |
| Output Differential Voltage | 150 | – | 400 | mV |
| Output Offset Voltage | 1.075 | – | – | V |
| Single-ended Output Impedance | 40 | – | – | Ω |
| Output Current On Short to Gnd | – | – | 40 | mA |
| Output Current When P and N are Shorted | – | – | 12 | mA |
| Power Off Leakage Current | – | – | 10 | mA |
| Skew Between P and N | – | – | 20 | ps |
| Total Output Jitter | – | – | 300 | ps |
| Receiver Tests | | | | |
| Sensitivity | – | – | 100 | mVpp |
| Single-ended Termination | – | 50 | – | Ω |
| Jitter Tolerance | 500 | – | – | ps |

Figure 32: Transmitter Eye Mask

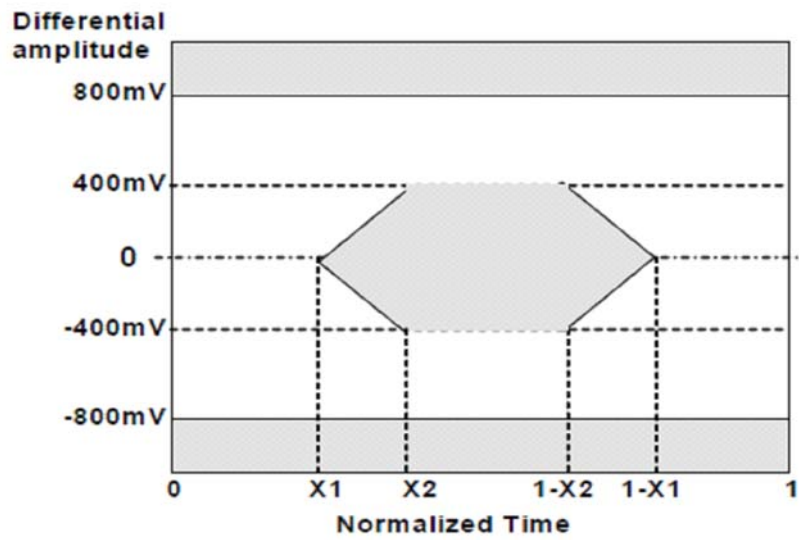


6.5.2 1000BASE-KX/SGMII Electrical Summary

Table 56: 1000BASE-KX/SGMII Electrical Summary

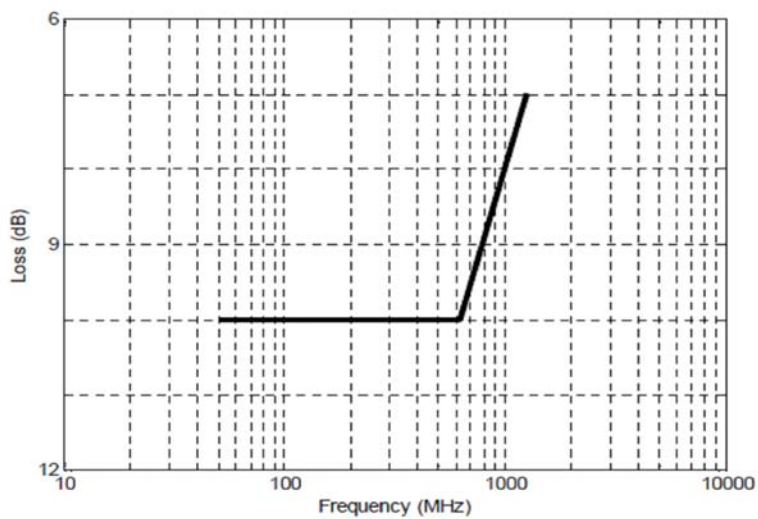
| Test Parameter | Specification | | | Units |
|--|---|---------------------------------|------------|----------|
| | Transmitter Tests at Test Point 1 | | | |
| | Min | Mean | Max | |
| Signaling Speed | 1.249875 | 1.25 | 1.250125 | GBaud |
| Eye Diagram | See Figure 33 . | | | |
| Impedance | – | 100 | – | Ω |
| Differential Peak-to-Peak Output Voltage | 800 | – | 1600 | mV |
| Differential Peak-to-Peak Output Voltage (Max.) with Tx Disabled | – | – | 30 | mV |
| DC Common-Mode Voltage Limits | -0.4 | – | 1.9 | V |
| Common-Mode Voltage Deviation (Max.) During LPI | -150 | – | 150 | mV |
| Differential Output Return Loss (Min.) | RL(f) ≥ 10 for 50 MHz ≤ f < 625 MHz; RL(F) ≥ 10 - 10 x log(f/625) for 625 MHz ≤ f ≤ 1250 MHz | See Figure 34 . | – | dB |
| Transition Timer (20 to 80%) | 60 | – | 320 | ps |
| Deterministic Jitter | – | – | 0.1 | UI |
| Random Jitter | – | – | 0.15 | UI |
| Total Output Jitter @ 10 ⁻¹² | – | – | 0.25 | UI |
| | Transmitter Tests at Test Point 4 | | | |
| Signaling Speed | 1.249875 | 1.25 | 1.250125 | GBaud |
| Impedance | – | 100 | – | Ω |
| Differential Input Peak-to-Peak Amplitude | – | 1600 | – | mV |
| Differential Input Return Loss (Min.) | RL(f) ≥ 10 for 50 MHz ≤ f < 625 MHz; RL(F) ≥ 10 - 10 x log(f/625) for 625 MHz ≤ f ≤ 1250 MHz | See Figure 34 . | – | dB |
| Amplitude of Broadband Noise (Min. RMS) | 8.6 | – | – | mV (RMS) |
| Applied Transition Time (20 to 80%, Min.) | 320 | – | – | ps |
| Applied Sinusoidal Jitter (Min. Peak-to-Peak) | 0.1 | – | – | ps |
| Applied Random Jitter (Min. Peak-to-Peak) @ 10 ⁻¹² | 0.15 | – | – | UI |
| Applied Duty Cycle Distortion (Min. Peak-to-Peak) | 0 | – | – | UI |

Figure 33: Transmitter Eye Mask — 1000BASE-KX/SGMII



| Symbol | Value | Units |
|--------|-------|---------------------|
| X1 | 0.125 | Unit intervals (UI) |
| X2 | 0.325 | Unit intervals (UI) |

Figure 34: 1000BASE-KX/SGMII Return Loss Mask



6.5.3 2500BASE-X Electrical Summary

Table 57: 2500BASE-X Electrical Summary

| Test Parameters | Specification | | | Units |
|---|-------------------|-------|----------|-------|
| | Transmitter Tests | | | |
| | Min | Mean | Max | |
| Signaling Rate | -100 ppm | 3.125 | +100 ppm | GBaud |
| Nominal Unit Interval | – | 320 | – | ps |
| Differential Output | 800 | 1000 | 1200 | mVpp |
| Deterministic Jitter | – | – | 0.17 | UI |
| Random Jitter | – | – | 0.27 | UI |
| Total Output Jitter | – | – | 0.35 | UI |
| Receiver Tests | | | | |
| Signaling Rate | -100 ppm | 3.125 | +100 ppm | GBaud |
| Nominal Unit Interval | – | 320 | – | ps |
| Differential Input Peak-to-Peak Amplitude | – | – | 1600 | mVpp |
| Applied Sinusoidal Jitter (Min. Peak-to-Peak) | 0.17 | – | – | UI |
| Applied Random Jitter (Min. Peak-to-Peak) | 0.18 | – | – | UI |

6.5.4 5GBASE-R Electrical Summary

Table 58: 5GBASE-R Electrical Summary

| Test Parameters | Specification | | | Units |
|---|-------------------|-------|----------|-------|
| | Transmitter Tests | | | |
| | Min | Mean | Max | |
| Signaling Rate | -100 ppm | 3.125 | +100 ppm | GBaud |
| Nominal Unit Interval | – | 193.9 | – | ps |
| Differential Output | – | – | 1200 | mVpp |
| Deterministic Jitter | – | – | 0.12 | UI |
| Random Jitter | – | – | 0.15 | UI |
| Total Output Jitter | – | – | 0.27 | UI |
| Receiver Tests | | | | |
| Signaling Rate | -100 ppm | 3.125 | +100 ppm | GBaud |
| Nominal Unit Interval | – | 193.9 | – | ps |
| Applied Random Jitter (Min. Peak-to-Peak) | 0.15 | – | – | UI |
| | 5 UI @ 0.02 MHz | – | – | N/A |
| | 0.15 UI @ 4 MHz | – | – | |
| Applied Sinusoidal Jitter (Min. Peak-to-Peak) | 0.15 UI @ 20 MHz | – | – | |

6.5.5 10BASE-Te, 100BASE-TX, and 1000BASE-T Electrical Parameters

IEEE tests are typically based on template and cannot simply be specified by a number. For an exact description of the template and the test conditions, refer to the IEEE specifications.

- 10BASE-Te IEEE 802.3 Clause 14
- 100BASE-TX ANSI X3.263-1995
- 1000BASE-T IEEE Clause 40

Table 59: IEEE DC Transceiver Parameters

(Over full range of values listed in the Recommended Operating Conditions unless otherwise specified)

| Symbol | Parameter | Pins | Condition | Min | Typ | Max | Units |
|--------------------|---|-------------|-------------------------|------------------|------------------|-------|--------------|
| V _{ODIFF} | Absolute Peak Differential Output Voltage | MDIP/N[1:0] | 10BASE-Te no cable | 1.54 | – | 1.96 | V |
| | | MDIP/N[1:0] | 10BASE-Te cable model | 585 ¹ | – | – | mV |
| | | MDIP/N[1:0] | 100BASE-TX mode | 0.950 | – | 1.050 | V |
| | | MDIP/N[3:0] | 1000BASE-T ² | 0.67 | – | 0.82 | V |
| | Overshoot ² | MDIP/N[1:0] | 100BASE-TX mode | 0 | – | 5 | % |
| | Amplitude Symmetry (Positive/Negative) | MDIP/N[1:0] | 100BASE-TX mode | 98 | – | 102 | V+/V- |
| V _{IDIFF} | Peak Differential Input Voltage | MDIP/N[1:0] | 10BASE-Te mode | 585 ³ | – | – | mV |
| | Signal Detect Assertion | MDIP/N[1:0] | 100BASE-TX mode | 1000 | 460 ⁴ | – | mV peak-peak |
| | Signal Detect De-assertion | MDIP/N[1:0] | 100BASE-TX mode | 200 | 360 ⁵ | – | mV peak-peak |

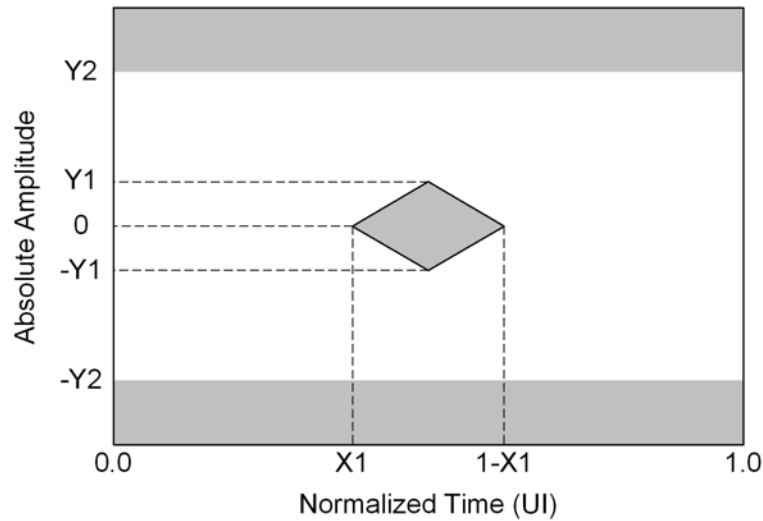
1. IEEE 802.3 Clause 14, Figure 14.9 shows the template for the far-end wave form. This template allows as little as 495 mV peak differential voltage at the far end receiver.
2. IEEE 802.3ab Figure 40 -19 points A&B.
3. The input test is actually a template test; IEEE 802.3 Clause 14, Figure 14.17 shows the template for the receive waveform.
4. The ANSI TP-PMD specification requires that any received signal with peak-to-peak differential amplitude greater than 1000 mV should turn on signal detect (internal signal in 100BASE-TX mode). The device accepts signals typically with 460 mV peak-to-peak differential amplitude.
5. The ANSI-PMD specification requires that any received signal with peak-to-peak differential amplitude less than 200 mV should de-assert signal detect (internal signal in 100BASE-TX mode). The device will reject signals typically with peak-to-peak differential amplitude less than 360 mV.

6.5.6 SERDES Receiver Input

Table 60: SERDES Receiver Input

| Symbol | Parameter | Condition | Min | Typ | Max | Units |
|--------|--|-------------------------------|-------|-----|------------------|------------|
| SDD11 | Input Return Loss | Differential, 100Ω | – | – | – | dB |
| | | f < 2.5 GHz | – | – | -9 | |
| | | 2.5 to 7.5 GHz | – | – | -9+12log(f/2.5G) | |
| Acm | CM Ripple | – | – | – | 20 | mV, pk-pk |
| SCD11 | Input Return Loss | Reference 25Ω | – | – | – | dB |
| | | f < 2.5 GHz | – | – | -6 | |
| | | 2.5 to 7.5 GHz | – | – | -6+12log(f/2.5G) | |
| X1 | Tx Eye Mask | – | – | – | 0.325 | UI |
| Y1 | Tx Eye Mask | – | 0.055 | – | – | V pk, diff |
| Y2 | Tx Eye Mask | – | – | – | 0.5 | V pk, diff |
| Vicm | Input CM | Rx can be DC coupled. | 0.1 | – | 1.4 | V |
| RC2 | Receiver Interference Tolerance at 10 Gbps | As per IEEE 802.3, section 72 | – | – | – | – |

Figure 35: Receiver Eye Mask

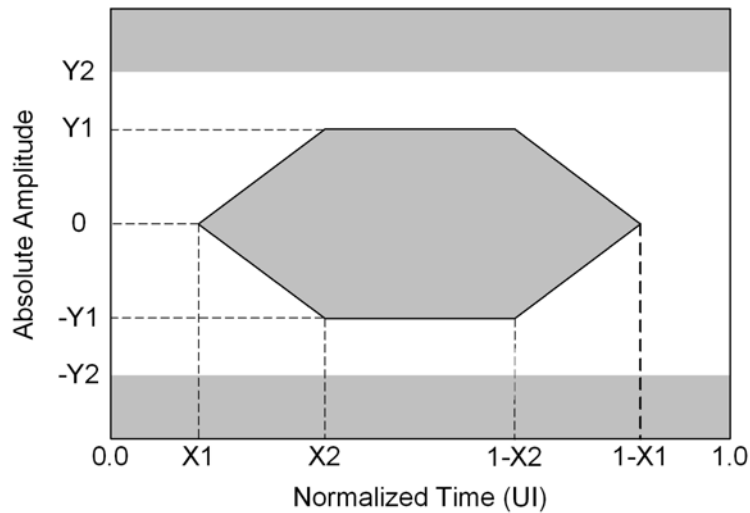


6.5.7 SERDES Transmitter Output

Table 61: SERDES Transmitter Output

| Symbol | Parameter | Condition | Min | Typ | Max | Units |
|--------|-------------------|--------------------|-------|-----|------------------|--------------|
| SDD11 | Input Return Loss | Differential, 100Ω | – | – | – | dB |
| | | f < 2.5 GHz | – | – | -9 | |
| | | 2.5 to 7.5 GHz | – | – | -9+12log(f/2.5G) | |
| tr, tf | Rise, Fall Time | 20 to 80% of swing | 25 | – | 47 | ps |
| Acm | CM Ripple | – | – | – | 20 | mV, pk-pk |
| SCD11 | Input Return Loss | Reference 25Ω | – | – | – | dB |
| | | f < 2.5 GHz | – | – | -6 | |
| | | 2.5 to 7.5 GHz | – | – | -6+12log(f/2.5G) | |
| X1 | Tx Eye Mask | – | – | – | 0.15 | UI |
| X2 | Tx Eye Mask | – | – | – | 0.4 | UI |
| Y1 | Tx Eye Mask | – | 0.185 | – | – | V pk, diff |
| Y2 | Tx Eye Mask | – | – | – | 0.4 | V pk, diff |
| TJ | Total Jitter | – | – | – | 0.3 | UI |

Figure 36: Transmitter Eye Mask



6.5.8 IEEE DC Transceiver Parameters

IEEE tests are typically based on template and cannot simply be specified by a number. For an exact description of the template and the test conditions, refer to the IEEE specifications.

-10BASE-T IEEE 802.3 Clause 14

-100BASE-TX ANSI X3.263-1995

Table 62: IEEE DC Transceiver Parameters

(Over full range of values listed in the Recommended Operating Conditions unless otherwise specified)

| Symbol | Parameter | Pins | Condition | Min | Typ | Max | Units |
|--------------------|---|-------------|-------------------------|------------------|------------------|-------|--------------|
| V _{ODIFF} | Absolute Peak Differential Output Voltage | MDIP/N[1:0] | 10BASE-T no cable | 0.950 | 1.0 | 1.050 | V |
| | | MDIP/N[1:0] | 10BASE-T cable model | 585 ¹ | – | – | mV |
| | | MDIP/N[1:0] | 100BASE-TX mode | 0.950 | 1.0 | 1.050 | V |
| | | MDIP/N[3:0] | 1000BASE-T ² | 0.67 | 0.75 | 0.82 | V |
| | Overshoot ² | MDIP/N[1:0] | 100BASE-TX mode | 0 | – | 5% | V |
| | Amplitude Symmetry (Positive/Negative) | MDIP/N[1:0] | 100BASE-TX mode | 0.98x | – | 1.02x | V+/- |
| V _{IDIFF} | Peak Differential Input Voltage | MDIP/N[1:0] | 10BASE-T mode | 585 ³ | – | – | mV |
| | Signal Detect Assertion | MDIP/N[1:0] | 100BASE-TX mode | 100 | 460 ⁴ | – | mV peak-peak |
| | Signal Detect De-assertion | MDIP/N[1:0] | 100BASE-TX mode | 200 | 360 ⁵ | – | mV peak-peak |

1. IEEE 802.3 Clause 14, Figure 14.9 shows the template for the far-end waveform. This template allows as little as 495 mV peak differential voltage at the far end receiver.

2. IEEE 802.3ab Figure 40 -19 points A&B.

3. The input test is actually a template test; IEEE 802.3 Clause 14, Figure 14.17 shows the template for the receive wave form.

4. The ANSI TP-PMD specification requires that any received signal with peak-to-peak differential amplitude greater than 1000 mV should turn on signal detect (internal signal in 100BASE-TX mode).

5. The ANSI-PMD specification requires that any received signal with peak-to-peak differential amplitude less than 200 mV should de-assert signal detect (internal signal in 100BASE-TX mode). The device will reject signals typically with peak-to-peak differential amplitude less than 360 mV.

6.6 Reference Clock

6.6.1 CLKP/N Timing — 156.25 MHz

Table 63: CLKP/N Timing — 156.25 MHz

| Symbol | Parameter | Condition | Min | Typ | Max | Units |
|--------|-------------------|-----------------------------|---------|--------|--------------|-----------|
| Fclk | Frequency | – | -50 ppm | 156.25 | +50 ppm | MHz |
| tr, tf | Rise, Fall Time | 20 to 80% of swing | 0.3 | 0.5 | 0.8 | ns |
| A | Amplitude | Differential pk | 0.4 | 0.75 | 0.9 | V |
| Tduty | Duty Cycle | – | 0.45 | 0.5 | 0.55 | – |
| Tj | Jitter | Integrated from 1 to 30 MHz | – | – | 0.5 | ps, (RMS) |
| Zin | Input Impedance | Differential | 90 | 100 | 110 | Ω |
| Vicm | Input CM | CLK can be DC coupled. | 0.1 | – | AVDDC - 0.1V | V |
| SDD11 | Input Return Loss | Differential, 100 Ω | – | – | -12 | db |



Note

When the transmitter or the receiver is in LPI transmit mode or switching to and from the LPI mode, a short-term rate of frequency variation will be less than 0.1 ppm/second.

6.6.2 CLKP/N Timing — 50 MHz

Table 64: CLKP/N Timing — 50 MHz

| Symbol | Parameter | Condition | Min | Typ | Max | Units |
|--------|-------------------|-----------------------------|---------|------|--------------|-----------|
| Fclk | Frequency | – | -50 ppm | 50 | +50 ppm | MHz |
| tr, tf | Rise, Fall Time | 20 to 80% of swing | 0.3 | 0.5 | 0.8 | ns |
| A | Amplitude | Differential pk-pk | 0.4 | 0.75 | 0.9 | V |
| Tduty | Duty Cycle | – | 0.45 | 0.5 | 0.55 | – |
| Tj | Jitter | Integrated from 1 to 30 MHz | – | – | 0.5 | ps, (RMS) |
| Zin | Input Impedance | Differential | 90 | 100 | 110 | Ω |
| Vicm | Input CM | CLK can be DC coupled. | 0.1 | – | AVDDC - 0.1V | V |
| SDD11 | Input Return Loss | Differential, 100 Ω | – | – | -12 | db |

6.6.3 XTAL Timing¹ Data

Table 65: XTAL Timing

(Over full range of values listed in the Recommended Operating Conditions unless otherwise specified)

| Symbol | Parameter | Condition | Min | Typ | Max | Units |
|---------------------|--------------------------------|-----------|---------------|-----|---------------|-------|
| T _{P_XTAL} | XTAL Period | – | 20 -50 ppm | 20 | 20 +50 ppm | ns |
| T _{H_XTAL} | XTAL High Time | – | 6.5 | 10 | 13.5 | ns |
| T _{L_XTAL} | XTAL Low Time | – | 6.5 | 10 | 13.5 | ns |
| T _{R_XTAL} | XTAL Rise | 10 to 90% | – | 2.0 | – | ns |
| T _{F_XTAL} | XTAL Fall | 90 to 10% | – | 2.0 | – | ns |
| T _{J_XTAL} | XTAL Total Jitter ² | – | – | – | 200 | ps |

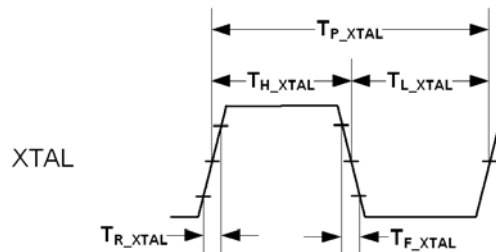
1. If the crystal option is used, then ensure that the frequency is 50 MHz ±50 ppm. Capacitors must be chosen carefully - see the application note supplied by the crystal vendor.
2. PLL-generated clocks are not recommended as input to XTAL since they can have excessive jitter. Zero delay buffers are also not recommended for the same reason.



Note

50 MHz crystal operation is only supported for commercial-grade devices.

Figure 37: XTAL Timing



6.7 Latency

The total latency in the egress direction is $T_{EGRESS} + T_{EGRESS_HL} + T_{CORE}$. The total latency in the ingress direction is $T_{INGRESS} + T_{CORE}$. If the high latency mode is not used, then the T_{CORE} and T_{EGRESS_HL} are 0, respectively.

Table 66: Egress Path Latency^{1 2 3 4} Data

| Symbol | Condition (per Port, Line to Host) | Min | Typ | Max | Unit |
|---------------------|-------------------------------------|--------|--------|--------|------|
| T _{EGRESS} | Reserved to 5GBASE-T | 1,698 | 1,713 | 1,740 | ns |
| | Reserved to 2.5GBASE-T | 2,727 | 2,753 | 2,802 | ns |
| | Reserved to 1000BASE-T | 358 | 385 | 423 | ns |
| | Reserved to 1000BASE-X/SGMII-1000 | 318 | 367 | 428 | ns |
| | Reserved to 100BASE-T | 2,381 | 2,552 | 2,814 | ns |
| | Reserved to 10BASE-T | 19,542 | 21,157 | 23,593 | ns |
| | 5GBASE-R to 5GBASE-T | 1,716 | 1,731 | 1,752 | ns |
| | 2500BASE-X to 2.5GBASE-T | 2,746 | 2,765 | 2,804 | ns |
| | 1000BASE-X/SGMII-1000 to 1000BASE-T | 271 | 302 | 332 | ns |
| | 1000BASE-X/SGMII-1000 to 1000BASE-X | 231 | 284 | 337 | ns |
| | SGMII to 100BASE-TX | 1,143 | 1,174 | 1,298 | ns |
| SGMII to 10BASE-T | 6,192 | 6,290 | 6,428 | ns | |

1. Latency numbers are based on default ppm FIFO depth = 01 in both egress and ingress direction.
2. The packet size used for ingress side RM FIFO simulation is 1512+4 (CRC) bytes per packet.
3. Low latency enabled
4. T_{EGRESS_HL} @5G = 625 ns, T_{EGRESS_HL} @2.5G = 1,875 ns, and others = 0 ns

Table 67: Ingress Path Latency^{1 2 3 4} Data

| Symbol | Condition (per Port, Line to Host) | Min | Typ | Max | Unit |
|----------------------|-------------------------------------|-------|-------|-------|------|
| T _{INGRESS} | 5GBASE-T to Reserved | 1,394 | 1,415 | 1,449 | ns |
| | 2.5GBASE-T to Reserved | 2,625 | 2,664 | 2,726 | ns |
| | 1000BASE-T to Reserved | 521 | 556 | 602 | ns |
| | 1000BASE-X/SGMII-1000 to Reserved | 412 | 461 | 522 | ns |
| | 100BASE-TX to Reserved | 2,990 | 3,241 | 3,583 | ns |
| | 5GBASE-R/2500BASE-X to Reserved | 125 | 135 | 150 | ns |
| | 5GBASE-T to 5GBASE-R | 1,367 | 1,384 | 1,405 | ns |
| | 2500BASE-T to 2.5GBASE-X | 2,541 | 2,587 | 2,626 | ns |
| | 1000BASE-T to 1000BASE-X/SGMII-1000 | 340 | 379 | 417 | ns |
| | 1000BASE-X to 1000BASE-X/SGMII-1000 | 231 | 284 | 337 | ns |

Table 67: Ingress Path Latency^{1 2 3 4} Data (Continued)

| Symbol | Condition (per Port, Line to Host) | Min | Typ | Max | Unit |
|--------|------------------------------------|--------|--------|--------|------|
| | 100BASE-TX to SGMII | 1,242 | 1,352 | 1,391 | ns |
| | 10BASE-T to SGMII | 11,358 | 12,193 | 12,245 | ns |

1. Latency numbers are based on default ppm FIFO depth = 01 in both egress and ingress direction.
2. The packet size used for ingress side RM FIFO simulation is 1512+4 (CRC) bytes per packet.
3. Low latency enabled.
4. T_{EGRESS_HL @5G} = 625 ns, T_{EGRESS_HL @2.5G} = 1,875 ns, and others = 0 ns

7 Mechanical Drawing

7.1 168-pin 10 mm x 12 mm HFCBGA Package Mechanical Drawings

Figure 38: 168-pin 10 mm x 12 mm HFCBGA Top and Side View

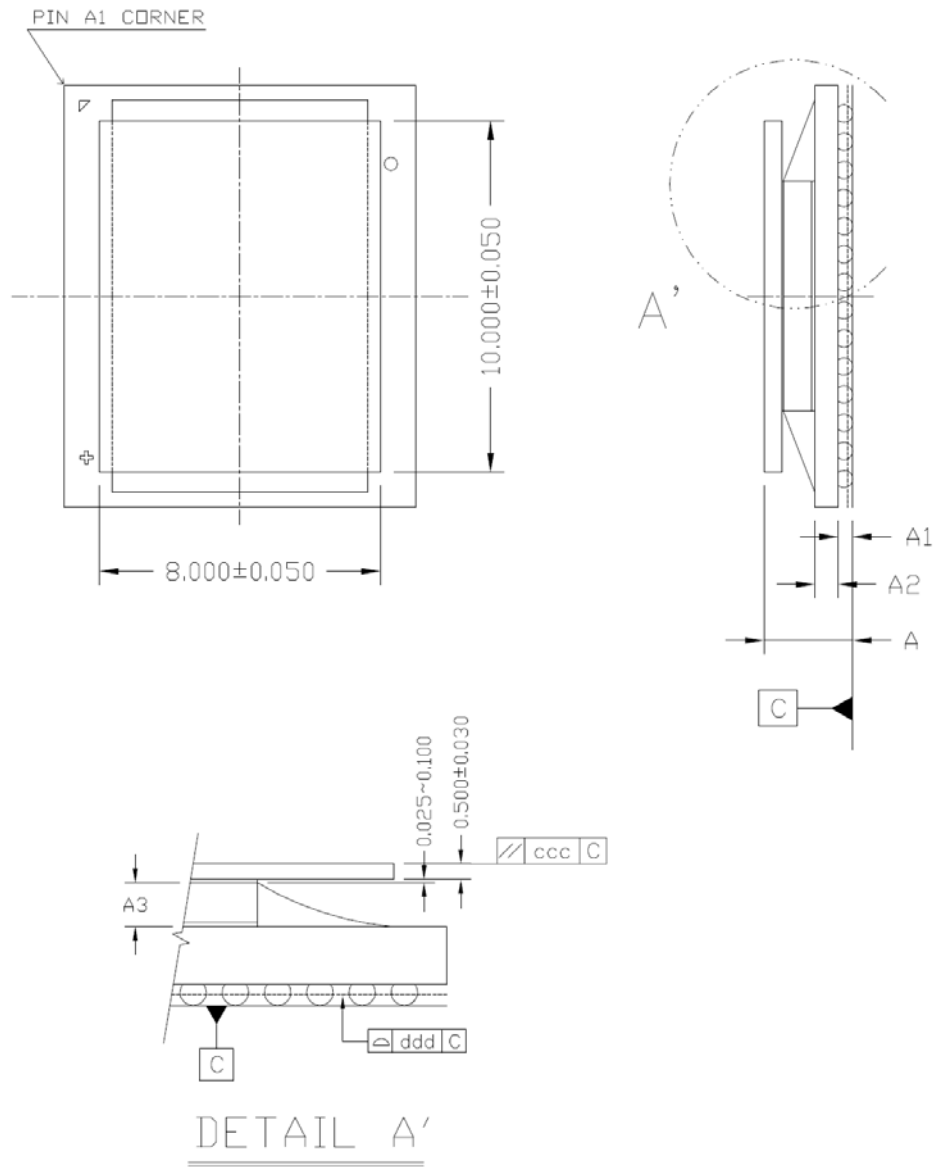
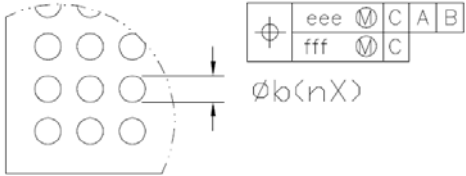
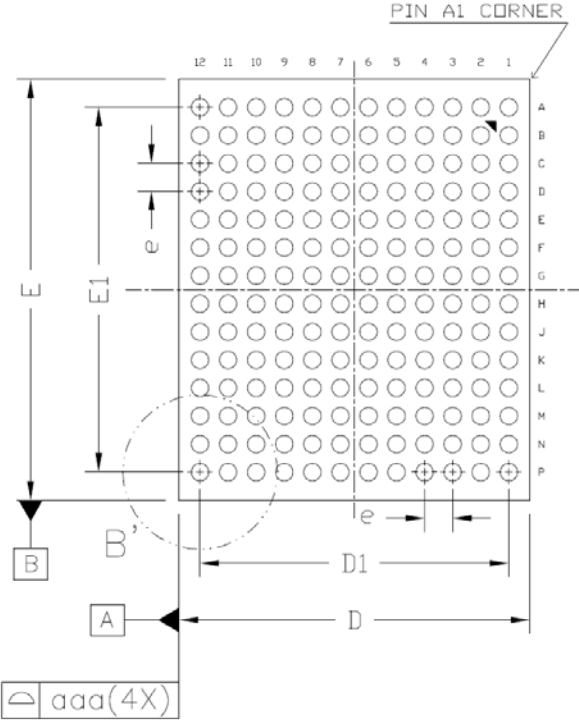


Figure 39: 168-pin 10 mm x 12 mm HFCBGA Bottom View



DETAIL B'

Table 68: 168-pin 10 mm x 12 mm HFCBGA Package Dimensions

| | SYMBOL | COMMON DIMENSIONS | | |
|--|--------|-------------------|-------|-------|
| | | MIN. | NOM. | MAX. |
| TOTAL THICKNESS | A | 2.407 | 2.527 | 2.647 |
| STAND OFF | A1 | 0.360 | -- | 0.460 |
| SUBSTRATE THICKNESS | A2 | 0.670 REF | | |
| THICKNESS FROM SUBSTRATE SURFACE TO DIE BACKSIDE | A3 | 0.887 REF | | |
| BODY SIZE | D | 10.000 BSC | | |
| | E | 12.000 BSC | | |
| BALL DIAMETER | | 0.500 | | |
| BALL WIDTH | b | 0.440 | -- | 0.640 |
| BALL PITCH | e | 0.800 BSC | | |
| BALL COUNT | n | 168 | | |
| EDGE BALL CENTER TO CENTER | D1 | 8.800 BSC | | |
| | E1 | 10.400 BSCC | | |
| EXPOSE DIE SIZE | D2 | -- | | |
| | E2 | -- | | |
| PACKAGE EDGE TOLERANCE | aaa | 0.100 | | |
| SUBSTRATE PARALLELISM | bbb | -- | | |
| TOP PARALLELISM | ccc | 0.200 | | |
| COPLANARITY | ddd | 0.150 | | |
| BALL OFFSET (PACKAGE) | eee | 0.150 | | |
| BALL OFFSET (BALL) | fff | 0.80 | | |

7.2 484-pin 23 mm x 23 mm HFCBGA Package Mechanical Drawings

Figure 40: 484-pin 23 mm x 23 mm HFCBGA Top and Side View

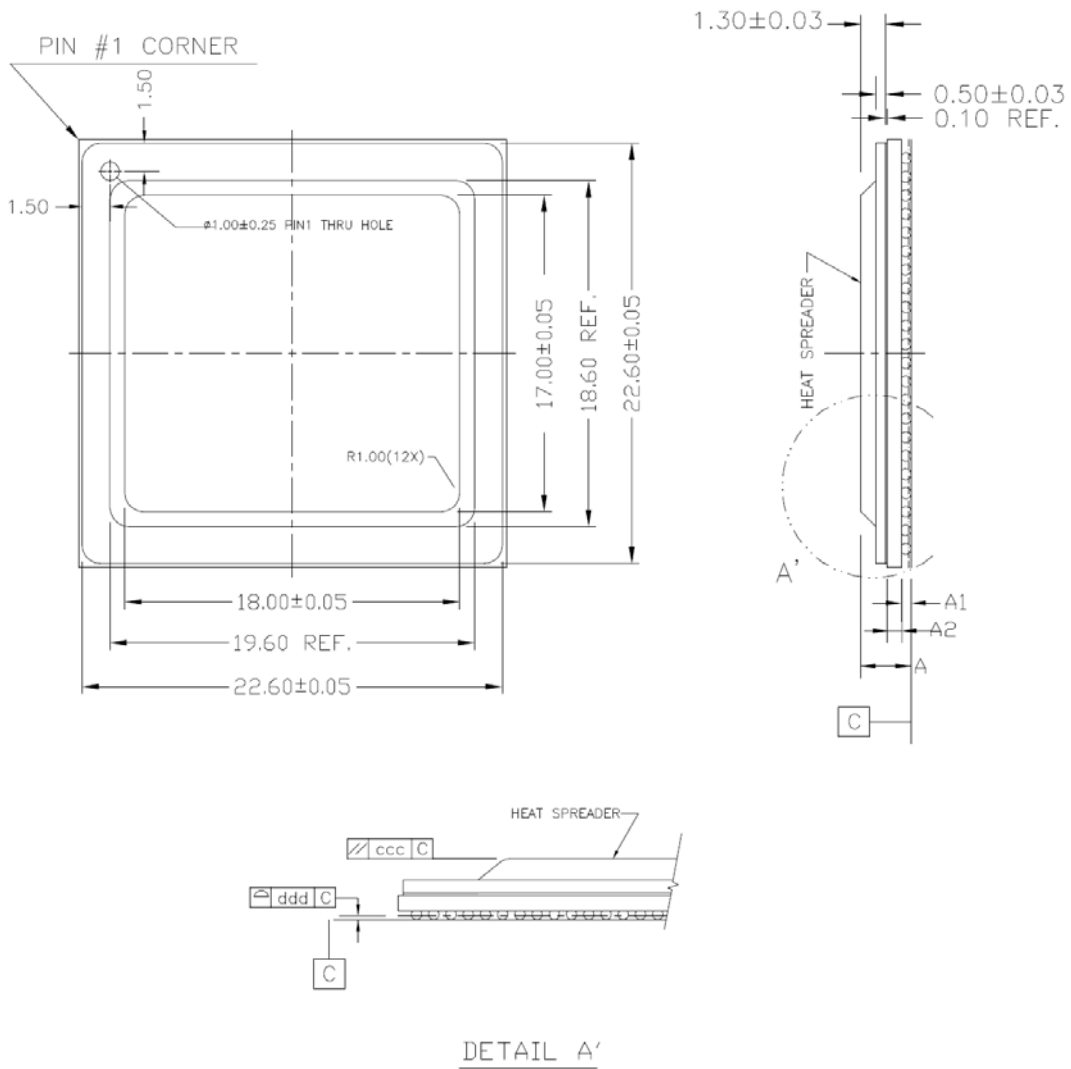


Figure 41: 484-pin 23 mm x 23 mm HFCBGA Bottom View

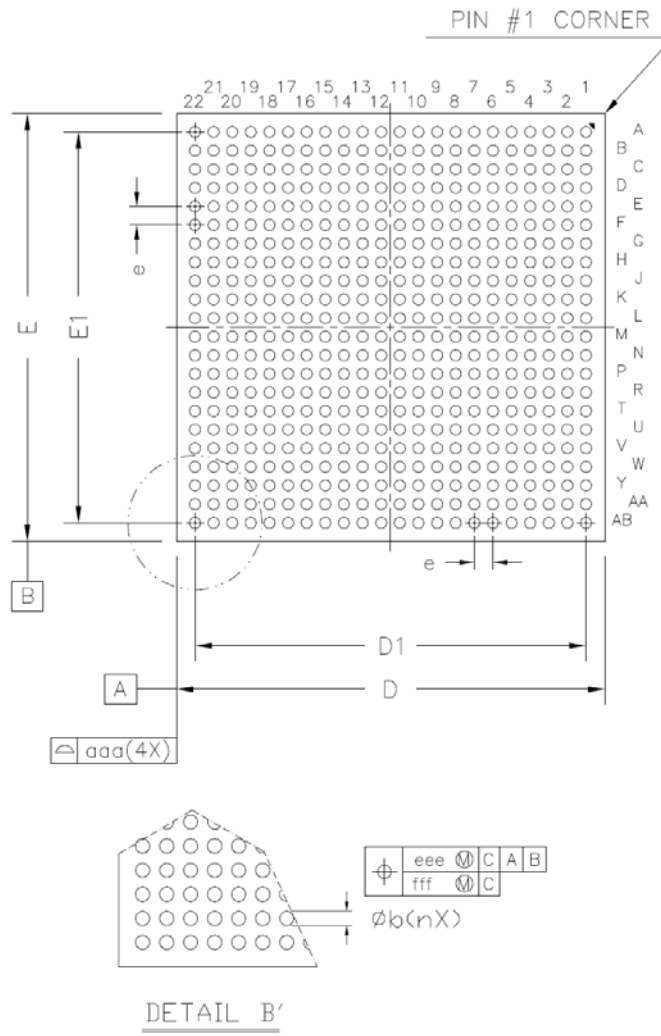


Table 69: 484-pin 23 mm x 23 mm HFCBGA Package Dimensions

| | SYMBOL | COMMON DIMENSIONS | | |
|--|--------|-------------------|-------|-------|
| | | MIN. | NOM. | MAX. |
| TOTAL THICKNESS | A | 2.580 | 2.700 | 2.820 |
| STAND OFF | A1 | 0.400 | -- | 0.600 |
| SUBSTRATE THICKNESS | A2 | 0.800 REF | | |
| THICKNESS FROM SUBSTRATE SURFACE TO DIE BACKSIDE | A3 | -- REF | | |
| BODY SIZE | D | 23.000 BSC | | |
| | E | 23.000 BSC | | |
| BALL DIAMETER | | 0.600 | | |
| BALL WIDTH | b | 0.500 | -- | 0.700 |
| BALL PITCH | e | 1.000 BSC | | |
| BALL COUNT | n | 484 | | |
| EDGE BALL CENTER TO CENTER | D1 | 21.000 BSC | | |
| | E1 | 21.000 BSCC | | |
| EXPOSE DIE SIZE | D2 | -- | | |
| | E2 | -- | | |
| PACKAGE EDGE TOLERANCE | aaa | 0.100 | | |
| SUBSTRATE PARALLELISM | bbb | -- | | |
| TOP PARALLELISM | ccc | 0.200 | | |
| COPLANARITY | ddd | 0.150 | | |
| BALL OFFSET (PACKAGE) | eee | 0.150 | | |
| BALL OFFSET (BALL) | fff | 0.100 | | |

8 Part Order Numbering/Package Marking

This section includes information on the following topics:

- Section 8.1, Part Order Numbering
- Section 8.2, Package Marking

8.1 Part Order Numbering

Figure 42 shows the ordering part numbering scheme for the 88E2010/88E2040L devices. Contact Marvell FAEs or sales representatives for complete ordering information.

Figure 42: Sample Part Number

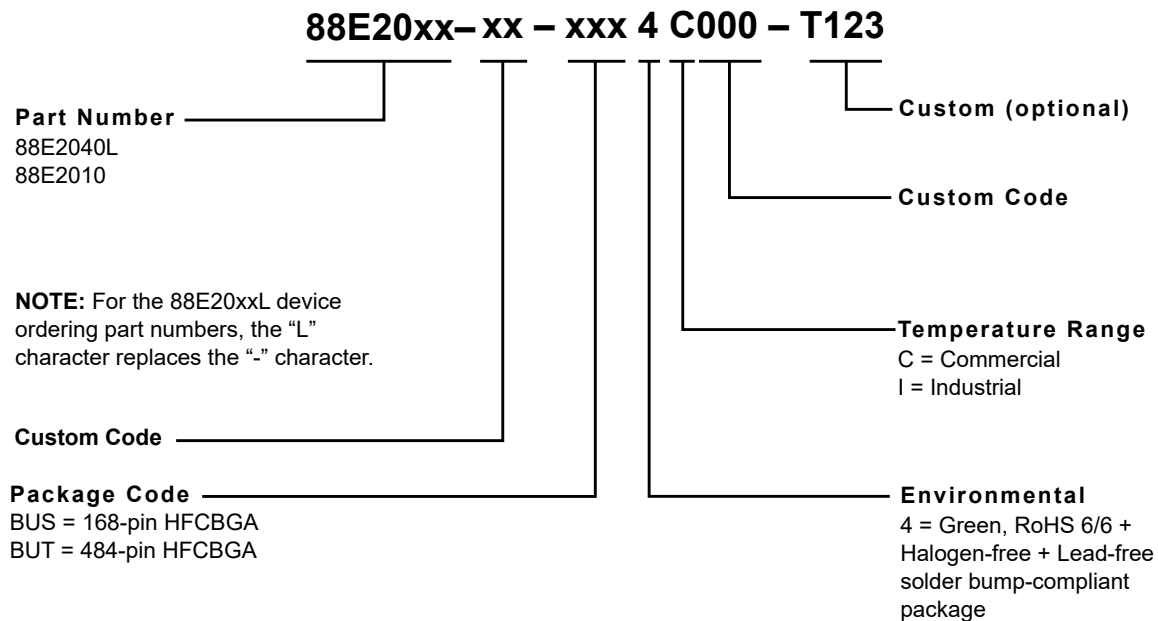


Table 70: 88E2010/88E2040L Commercial Part Order Options

| Part Number | Package Type | Part Order Number |
|-------------|---|---------------------|
| 88E2010 | 168-pin 10 mm x 12 mm HFCBGA- Commercial, Green, RoHS 6/6 + Halogen-free + Lead-free solder bump-compliant | 88E2010-XX-BUS4C000 |
| 88E2040L | 484-pin 23 mm x 23 mm HFCBGA - Commercial, Green, RoHS 6/6 + Halogen-free + Lead-free solder bump-compliant | 88E2040LXX-BUT4C000 |

Table 71: 88E2010/88E2040L Industrial Part Order Options

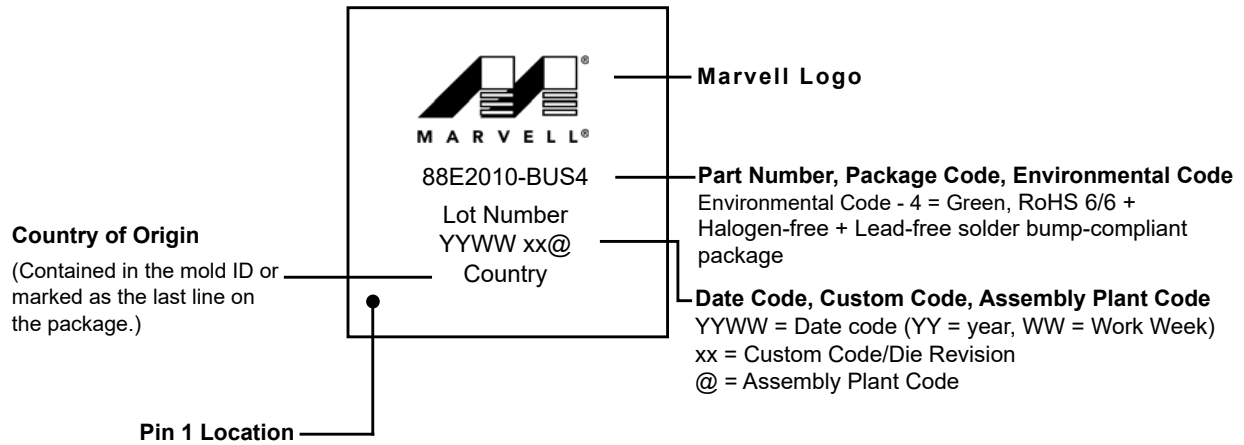
| Part Number | Package Type | Part Order Number |
|-------------|--|---------------------|
| 88E2010 | 168-pin 10 mm x 12 mm HFCBGA- Commercial, Green, RoHS 6/6 + Halogen-free + Lead-free solder bump-compliant | 88E2010-XX-BUS4I000 |
| 88E2040L | 484-pin 23 mm x 23 mm HFCBGA - Commercial, Green, RoHS 6/6 + Halogen-free + Lead-free solder bump-compliant | 88E2040LXX-BUT4I000 |

8.2 Package Marking

8.2.1 Commercial Marking Examples

Figure 43 is an example of the package marking and pin 1 location for the 88E2010 package.

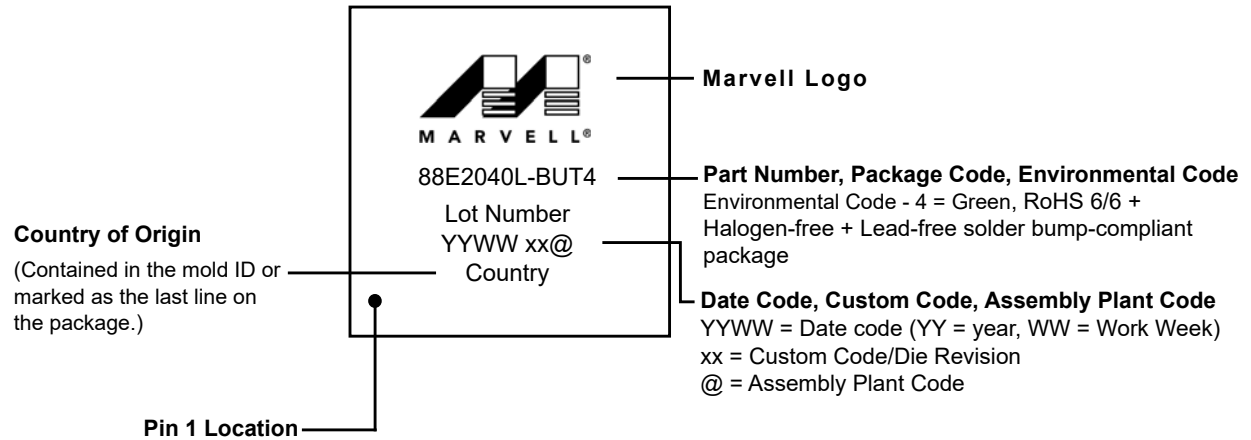
Figure 43: 88E2010 Commercial Package Marking and Pin 1 Location



Note: The above example is not drawn to scale. Location of markings is approximate.

Figure 44 is an example of the package marking and pin 1 location for the 88E2040L package.

Figure 44: 88E2040L Commercial Package Marking and Pin 1 Location

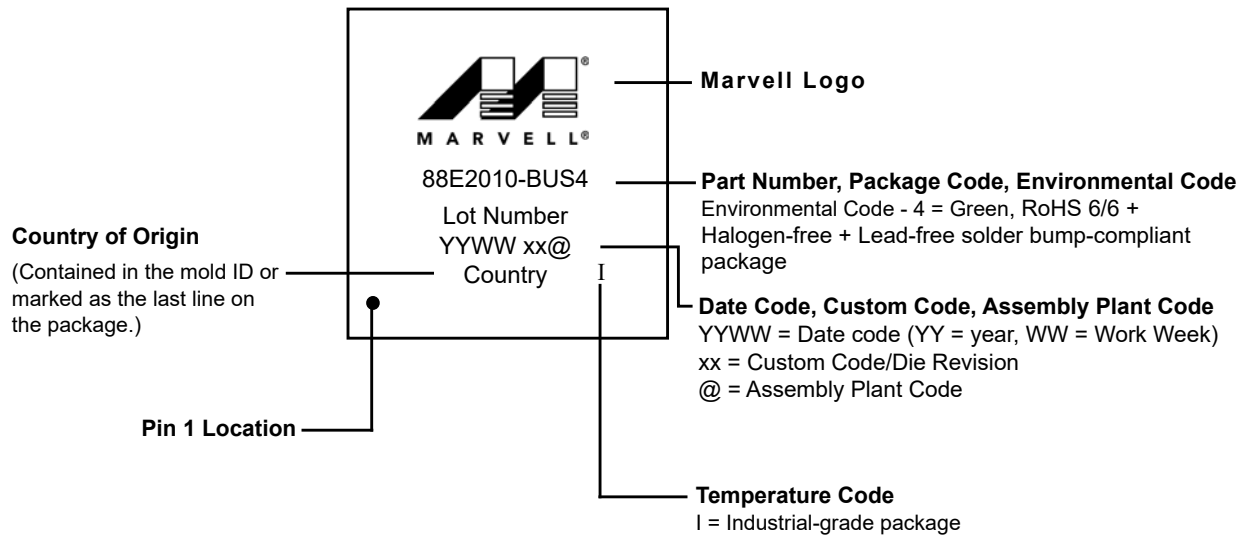


Note: The above example is not drawn to scale. Location of markings is approximate.

8.2.2 Industrial Marking Examples

Figure 45 is an example of the package marking and pin 1 location for the 88E2010 package.

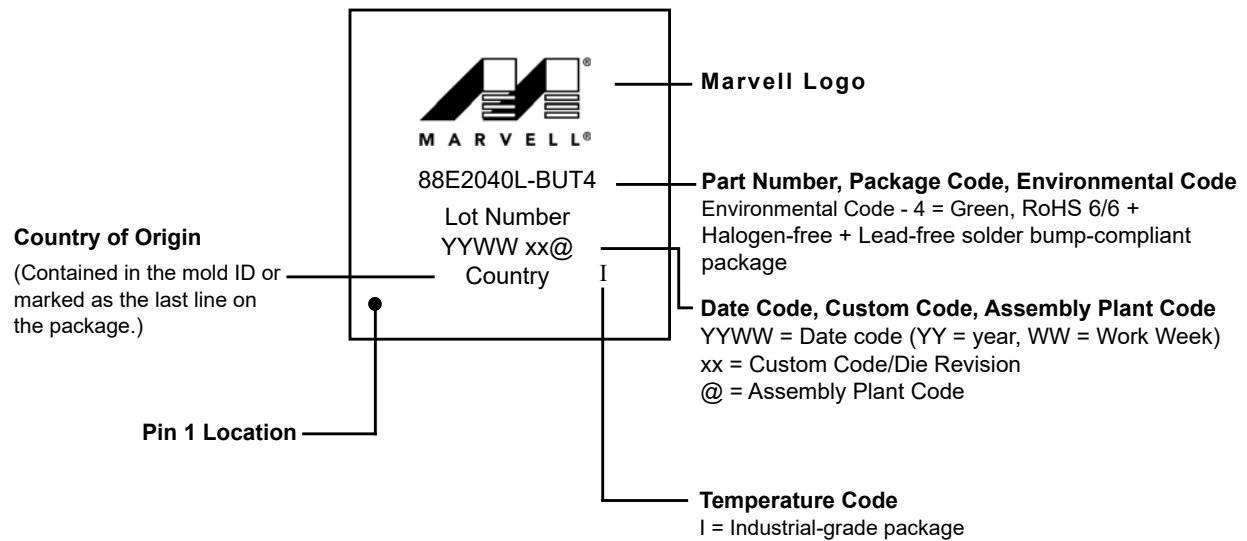
Figure 45: 88E2010 Industrial Package Marking and Pin 1 Location



Note: The above example is not drawn to scale. Location of markings is approximate.

Figure 46 is an example of the package marking and pin 1 location for the 88E2040L package.

Figure 46: 88E2040L Industrial Package Marking and Pin 1 Location



Note: The above example is not drawn to scale. Location of markings is approximate.

A Revision History

Table 72: Document Change History

| Revision | Date | Section | Detail |
|----------------|--------------------|---|---|
| Rev. B | September 10, 2018 | Revision B released. | |
| Rev. B 2.08 | September 10, 2018 | Section 6, Electrical Specifications | • 6.5.1 "SGMII Electrical Summary" on page 122 updated. |
| | | | • 6.5.2 "1000BASE-KX/SGMII Electrical Summary" on page 123 updated. |
| | | | • 6.5.3 "2500BASE-X Electrical Summary" on page 125 updated. |
| | | | • 6.5.4 "5GBASE-R Electrical Summary" on page 126 updated. |
| | | | • 6.5.5 "10BASE-Te, 100BASE-TX, and 1000BASE-T Electrical Parameters" on page 127 updated. |
| Rev. B 2.07 | August 10, 2018 | Entire document | • Styles and format updated. |
| Rev. B 2.06 | August 2, 2018 | Cover/Legal | • Legal disclaimer updated. |
| Rev. B 2.05 | July 31, 2018 | Section 2, Signal Description | • Table 14, 88E2040L Pin List — Alphabetical by Signal Name, on page 44 added. |
| | | Section 3, Functional Description | • Table 20, Configuration Bit Definition, on page 62 updated. |
| | | Section 5, Host Interface Unit (H Unit) | <ul style="list-style-type: none"> • Table 112, NGBASE-T Fast Retrain Status and Control, on page 172 updated. • Table 157, Copper Specific Interrupt Enable Register 1, on page 193 and Table 157, Copper Specific Interrupt Enable Register 1, on page 193 updated. • Table 337, 5GBASE-R/2500BASE-X Interrupt Enable Register, on page 268 and Table 338, 5GBASE-R/2500BASE-X Interrupt Status Register, on page 269 updated. |

Table 72: Document Change History (Continued)

| Revision | Date | Section | Detail |
|--------------------------------------|--|-----------------------------------|---|
| Rev. B 2.04 | May 25, 2018 | Product Overview | <ul style="list-style-type: none"> Features, on page 3 updated. References to EEE, 802.3az, Long Reach, Clause 22, AVS, WOL, and GPIO removed. |
| | | Section 2, Signal Description | <ul style="list-style-type: none"> Table 2, Media Dependent Interface, on page 22 through Table 12, Power and Ground (Continued), on page 34 updated. |
| | | | <ul style="list-style-type: none"> Table 10, Adaptive Voltage Scaling Interface (88E2010/P Device Only), on page 49 removed. |
| | | Section 3, Functional Description | <ul style="list-style-type: none"> Table 25, Basic LED Status, on page 71 updated. 3.8 "Wake On LAN (WOL)" on page 86 removed. 3.9 "Long Reach Mode of Operation" on page 86 removed. 3.13 "GPIO" on page 94, 3.13.1 "Enabling the GPIO Function" on page 94, and 3.13.3 "GPIO Interrupts" on page 94 removed. 3.6.1 "Clause 45 MDIO Framing" on page 66 and 3.10.1.1 "Clause 22 Access to Clause 45 MDIO Manageable Device (MMD)" on page 89 updated. 3.21 "Adaptive Voltage Scaling (AVS)" on page 134 removed. |
| | | Section 4, Copper Unit (T Unit) | <ul style="list-style-type: none"> 4.5 "Energy Efficient Ethernet" on page 140 removed. 4.4.1 "802.3 Clause 28, 40, and 55 Auto-Negotiation" on page 102 removed. |
| Section 6, Electrical Specifications | <ul style="list-style-type: none"> Table 46, Recommended Operating Conditions, on page 113 updated. | | |

Table 72: Document Change History (Continued)

| Revision | Date | Section | Detail |
|--|----------------|-------------------------------------|---|
| Rev. B 2.03 | April 24, 2018 | Cover | <ul style="list-style-type: none"> Updated title. |
| | | Product Overview | <ul style="list-style-type: none"> Features, on page 3, Figure 1, 88E2010 Top-level Block Diagram, on page 4 and Figure 2, 88E2040L Top-level Block Diagram, on page 5 updated. |
| | | Section 1, General Chip Description | <ul style="list-style-type: none"> 1 "General Chip Description" on page 14, Figure 3, 88E2010 Device Functional Block Diagram, on page 15 and Figure 4, 88E2040L Device Functional Block Diagram, on page 16 updated. |
| | | Section 2, Signal Description | <ul style="list-style-type: none"> 2.1.1 "88E2010 Device Pin Map" on page 19 and 2.1.2 "88E2040L Device Pin Map" on page 20 updated. |
| | | | <ul style="list-style-type: none"> Table 2, Media Dependent Interface, on page 22, Table 3, SERDES Interface, on page 24, Table 4, Clock/Reset/Reference, on page 26, Table 5, Management Interface, on page 27, Table 6, SPI Interface, on page 28, and Table 7, LED, on page 29 updated. |
| | | | <ul style="list-style-type: none"> Table 8, Configuration, on page 30, Table 9, JTAG Interface, on page 30, Table 10, Adaptive Voltage Scaling Interface (88E2010/P Device Only), on page 49, Table 10, Test Pins, on page 31, Table 11, Power and Ground, on page 33, and Table 12, Power and Ground (Continued), on page 34, and Table 13, 88E2010 Pin List — Alphabetical by Signal Name, on page 40 updated. |
| | | Section 3, Functional Description | <ul style="list-style-type: none"> Figure 5, Device Data Path (88E2040L), on page 54 and Figure 6, Device Data Path (88E2010), on page 55 updated. |
| <ul style="list-style-type: none"> 3.2 Auto-Speed Adjustment" on page 54, 3.5 "Configuration and Resets" on page 60, 3.5.2 "Hardware Configuration" on page 60, 3.6.3 "Independent MDC/MDIO Support" on page 66, 3.7.2 "Firmware Download to RAM" on page 68, 3.8.1 "Manual Power Down" on page 68, 3.13 "GPIO" on page 94, 3.13.1 "Enabling the GPIO Function" on page 94, and 3.8.3 "Controlling and Sensing" on page 69 updated. | | | |
| | | | <ul style="list-style-type: none"> Table 32, 88X2010 Boundary Scan Chain Order, on page 79 and Table 33, 88E2010 Boundary Scan Exclusion List, on page 81 updated. |

Table 72: Document Change History (Continued)

| Revision | Date | Section | Detail |
|----------------|----------------|---|---|
| Rev. B 2.02 | April 23, 2018 | Section 3, Functional Description | <ul style="list-style-type: none"> Table 34, 88E2040L Boundary Scan Chain Order, on page 82 and Table 35, 88E2040L Boundary Scan Exclusion List, on page 85 updated. 3.11.6 "ID CODE Instruction" on page 88 updated. |
| | | Section 5, Host Interface Unit (H Unit) | <ul style="list-style-type: none"> 5 "Host Interface Unit (H Unit)" on page 106, 5.2 "PCS" on page 107, 5.2.1 "5GBASE-R/2500BASE-X" on page 107, 5.2.2 "5GBASE-R" on page 108, 5.2.3 "2500BASE-X" on page 108, 5.2.4 "SGMII (Media)" on page 108, and 5.8 "Interrupt" on page 124 updated. |
| | | Section 6, Electrical Specifications | <ul style="list-style-type: none"> 6.3.1 "Thermal Conditions for 88E2010, 168-pin, HFCBGA Package" on page 114, 6.3.2 "Thermal Conditions for 88E2040L, 484-pin, HFCBGA Package" on page 115, and 6.7 "Latency" on page 134 updated. |
| | | Section 8, Part Order Numbering/Package Marking | <ul style="list-style-type: none"> Table 70, 88E2010/88E2040L Commercial Part Order Options, on page 142 and Table 71, 88E2010/88E2040L Industrial Part Order Options, on page 143 updated. |
| Rev. B 2.01 | April 20, 2018 | Initial datasheet draft. | |



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ВЧ соединители, коаксиальные кабели, кабельные сборки и микроволновые компоненты:

(Применяются в телекоммуникациях гражданского и специального назначения, в средствах связи, РЛС, а так же военной, авиационной и аэрокосмической отраслях промышленности).



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